



First Quarter FY 2022 Quarterly Update

Infineon Technologies AG
Investor Relations



Infineon at a glance

Addressing long-term high-growth trends

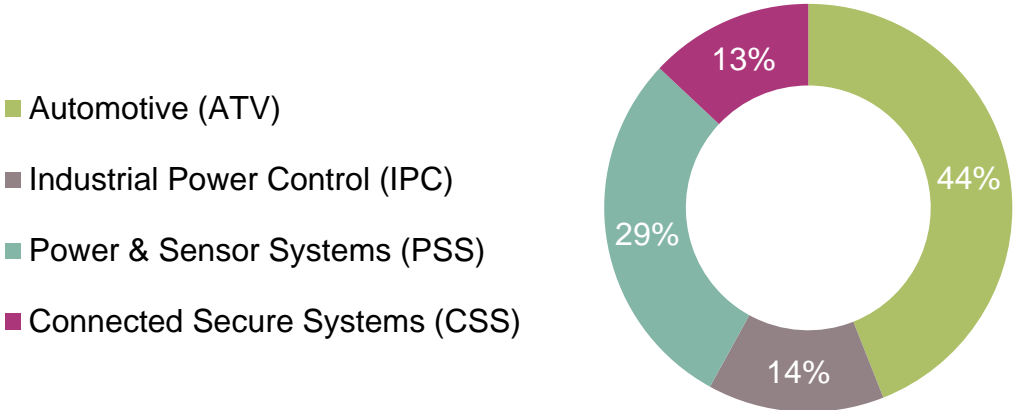
Electrification

- › CO₂ saving
- › Energy efficiency
- › Cost saving

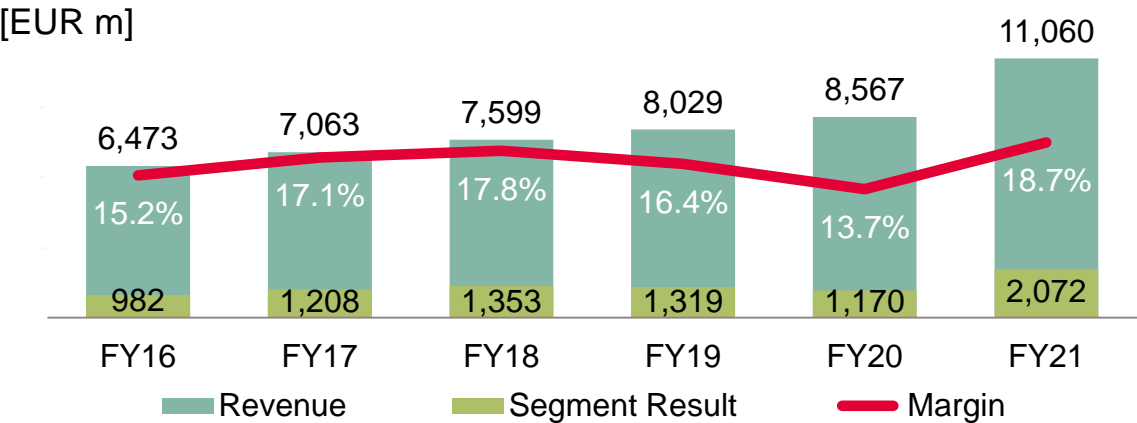
Digitalization

- › Productivity
- › Comfort
- › New use cases

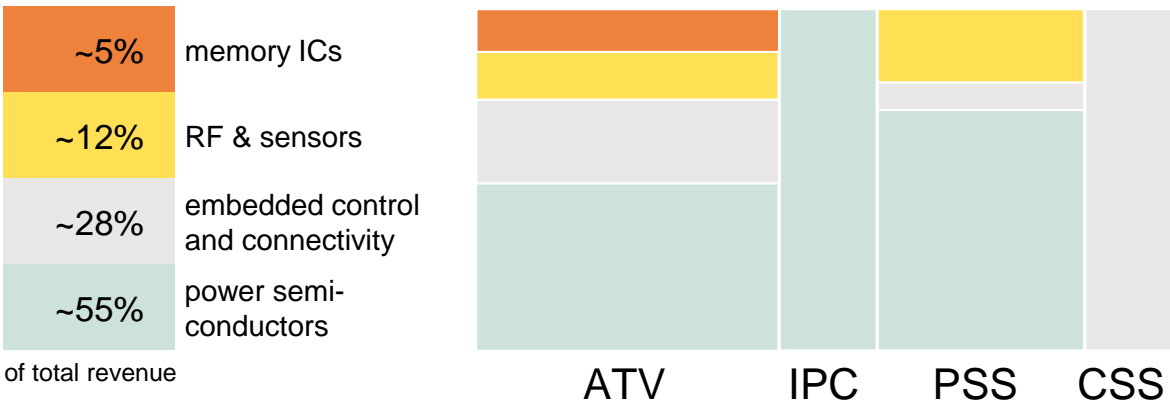
FY21 revenue by segment



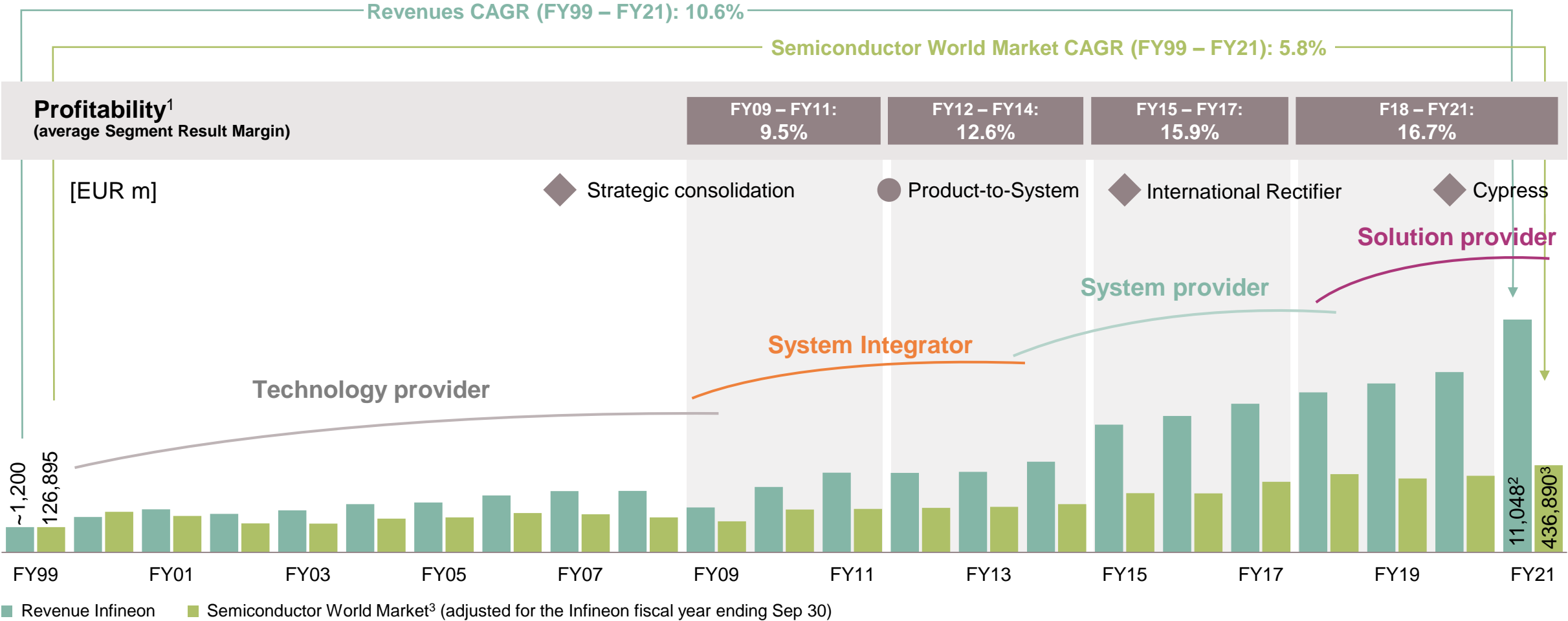
Financials



FY21 revenue by product category



Since 1999, Infineon has grown by more than 10% p.a.,
thereby consistently outperforming the semiconductor market

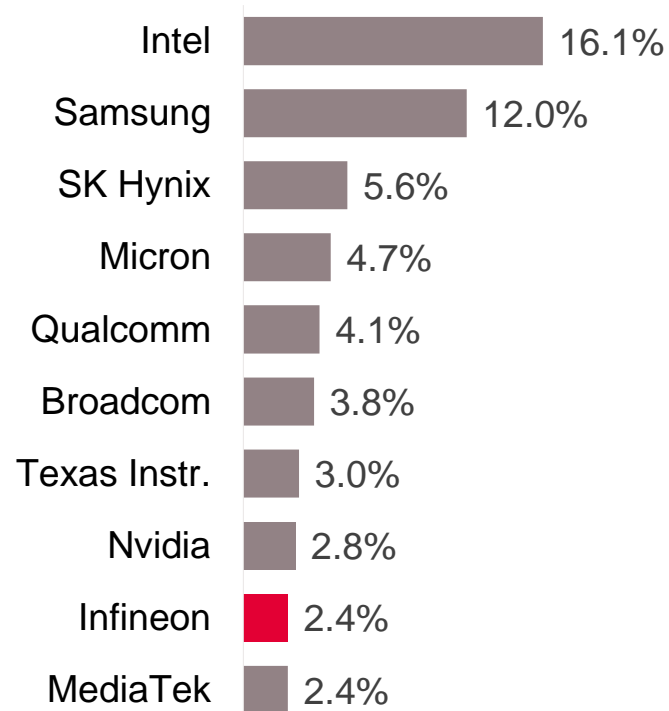


¹ In FY09 Infineon's management changed the measure it uses to assess the operating performance of its operating segments to "Segment Result"
² Based on Infineon's portfolio (excl. Other Operating Segments and Corporate & Eliminations) per end of FY21 | ³ Source: WSTS (World Semiconductor Trade Statistics) in EUR adjusted for fiscal year, September 2021

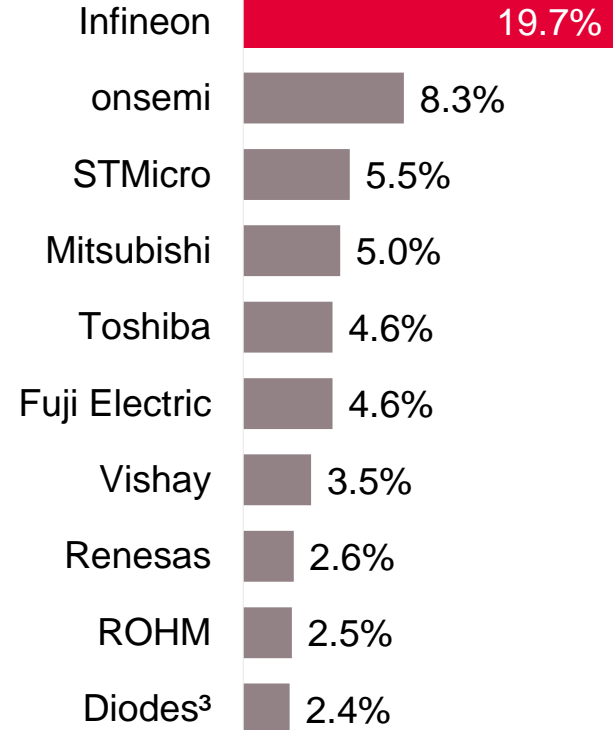
Infineon is a global top-10 player, #1 in power semiconductors, and ranked #3 in the overall microcontroller market



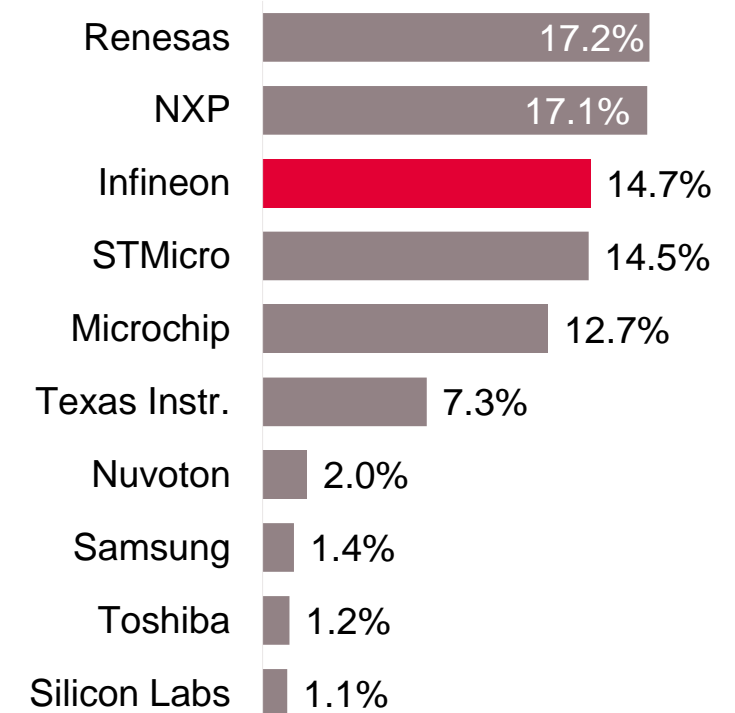
Semiconductor suppliers 2020 total market: \$473bn¹



Power discretes and modules 2020 total market: \$20.9bn²



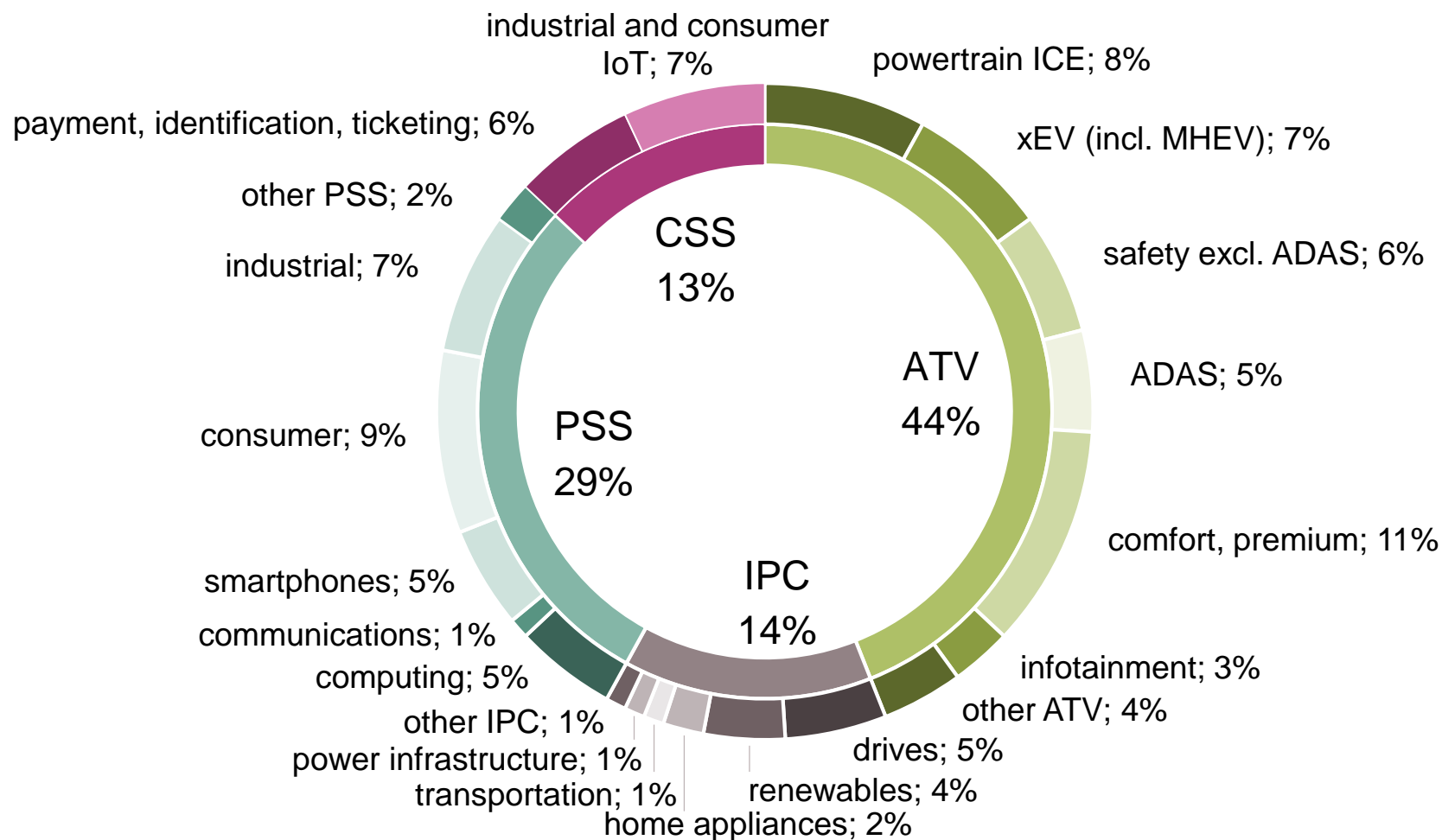
MCU suppliers 2020 total market: \$17.3bn¹



¹ Based on or includes research from Omdia: *Annual 2001-2020 Semiconductor Market Share Competitive Landscaping Tool – Q2 2021*. August 2021. | ² Based on or includes research from Omdia: *Power Semiconductor Market Share Database – 2020*. September 2021. | ³ Diodes acquired Lite-On Semiconductor in November 2020. Both companies are reported combined as Diodes. Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk.

Well-balanced portfolio among key trends Electrification and Digitalization

FY21 revenue of €11,060m by target application



AURIX™ – the “gold standard” of Automotive MCUs continues its success story with the recently announced TC4x



Current AURIX™ TC2x/TC3x microcontroller family

- › AURIX™ is one of the leading Automotive microcontrollers with more than 320m units shipped to date
- › 32-bit real-time capable multi-core architecture based on up to 6 unified RISC/MCU/DSP TriCore™ processor cores, application-specific accelerators and security subsystem
- › Wide array of automotive applications: inverter control, engine and battery management, transmission control, safety control, ADAS, active suspension, LED pixel lighting, sensor fusion, domain control

New AURIX™ TC4x microcontroller family

- › New AURIX™ TC4x family for next generation eMobility, ADAS, automotive E/E architectures and affordable artificial intelligence (AI)
- › Highest standards in real-time execution, security and dependability
- › New zero downtime SOTA (Software Over the Air) features
- › Smart accelerators like for AI-based real-time control and 4D radar signal processing – up to 78x acceleration vs. previous generation
- › Enabling the next generation of intelligent and connected electric cars



AI-based xEV features

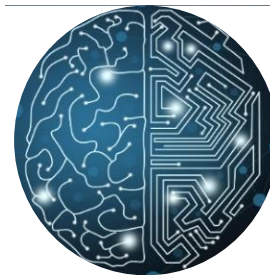
- › Predictive control and virtual sensing
- › Advance State of Health (SoH) and State of Charge (SoC) algorithms



Intelligent safety host

- › Companion chip for safety critical applications next to high-performance MPUs
- › Highest safety standards – ASIL-D, ISO26262

New AI and neural network features



Enhanced safety and control



AI-based ADAS features

- › Object classification
- › Advanced radar signal processing
- › Sensor fusion



Domain/zone control

- › E/E architecture – reduce complexity
- › Model predictive control
- › Intrusion prevention and detection

AIROC™ portfolio expansion to support Matter with multiprotocol solutions including BLE and IEEE 802.15.4 low-power SoC



Infineon joins Connectivity Standards Alliance – shaping the future of IoT

- › Launching the new AIROC™ Bluetooth® Low Energy (BLE) and IEEE 802.15.4 to support Matter with multiprotocol solutions
 - Built on market-proven wireless IP technology for maximum interoperability
 - Superior RF performance enables robust and reliable connectivity
 - Low power consumption supports applications requiring long battery life
 - Software enablement reduces development time for BLE and Matter over Thread applications



A proprietary, license-free home automation connectivity standard that aims to reduce fragmentation between different vendors and achieve interoperability between smart home devices and Internet of Things platforms. Other members include Amazon, Apple, Google, Comcast, the Zigbee Alliance, IKEA, Signify, etc.

AIROC™ CYW30739

Low power system on chip (SoC) with multi-protocol connectivity and integrated MCU



Multi-protocol subsystem features:

- › Bluetooth® v5.3 with LE 2-Mbps support
- › Fully compliant IEEE 802.15.4 MAC and PHY layers
- › Best-in-class Rx sensitivity of -95.5 dBm (BLE) and -103.5 dBm (IEEE 802.15.4)

Examples of target applications



Smart Home



Smart Building



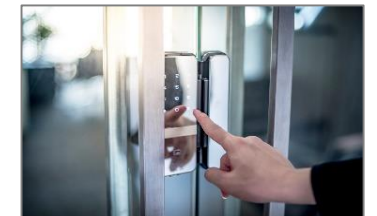
Residential Lighting



Commercial Lighting



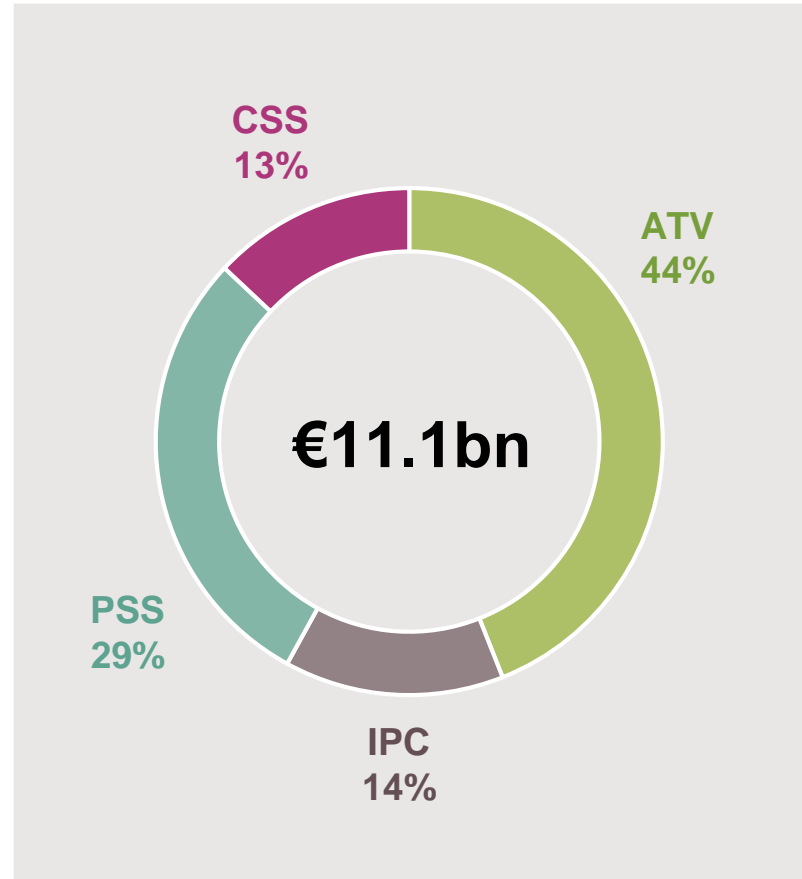
Access Control



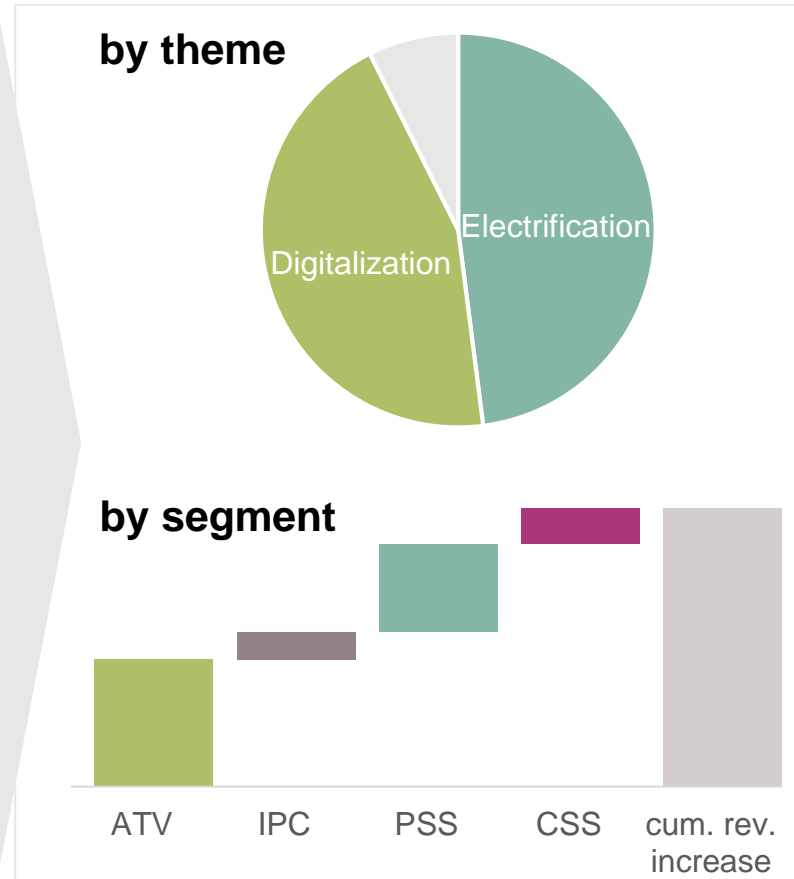
Door Locks

Growing annual revenues by €5bn+ in FY25 – multitude of growth drivers across markets/applications; well-diversified divisional split

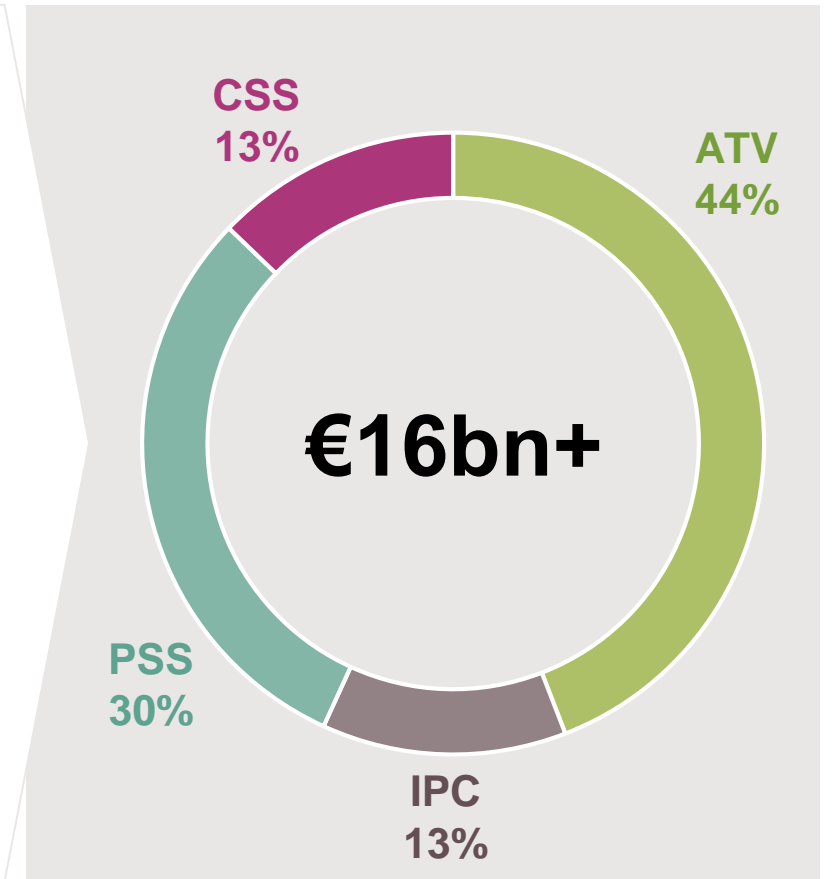
FY21 by division



Cum. rev. growth FY21 to FY25e



FY25e by division (indicative)



Infiniteon's value creation is crystallized in a resilient through-cycle Target Operating Model



Revenue growth	
Segment Result Margin	
Investment-to-sales	

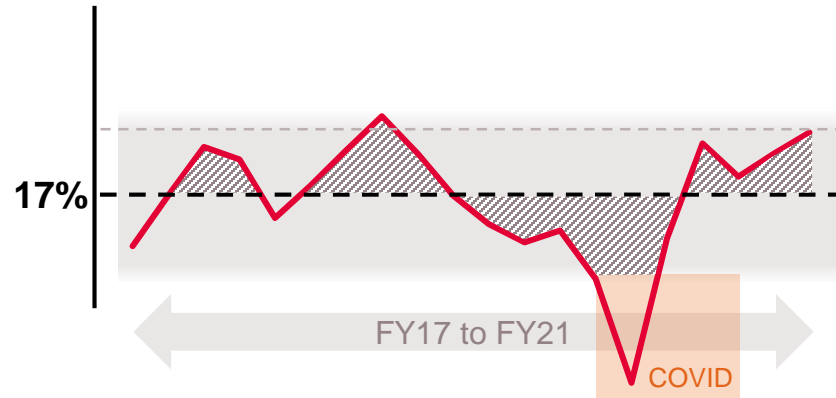
Target Operating Model¹

9%+
19%
13%

¹ Infineon financial performance to approach targets as Cypress integration progresses

Key levers identified to get to the target profitability flight level – 19% Segment Result Margin over the (next) cycle

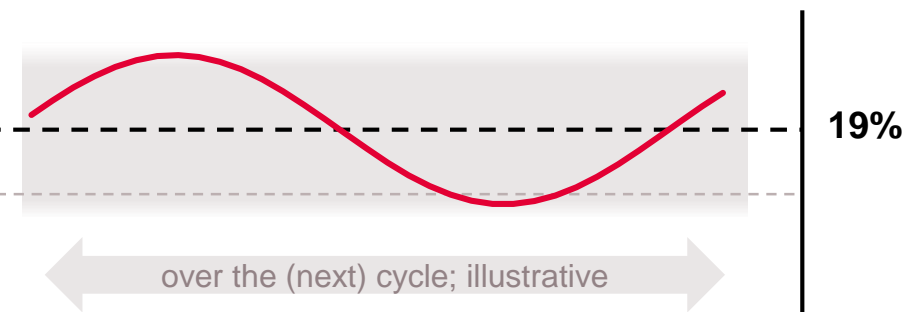
Looking back: former TOM achieved



Assuming no pandemic, 17% Segment Result Margin target would have been achieved over the cycle



Looking ahead: all set up to reach current TOM



Levers for margin expansion

- › Higher value system solutions:
 - › P2S and Cypress revenue synergies
 - › Additional customer value creation
 - › Business mix
- › Manufacturing productivity and cost control:
 - › 300 mm productivity
 - › Cypress cost synergies, SG&A scaling
- › Cypress accretion for entire period

Inhibitors to margin expansion

- › Increased supplier (foundry) and materials costs
- › Pre-funding P2S synergies
- › Pre-funding SiC/GaN roadmap

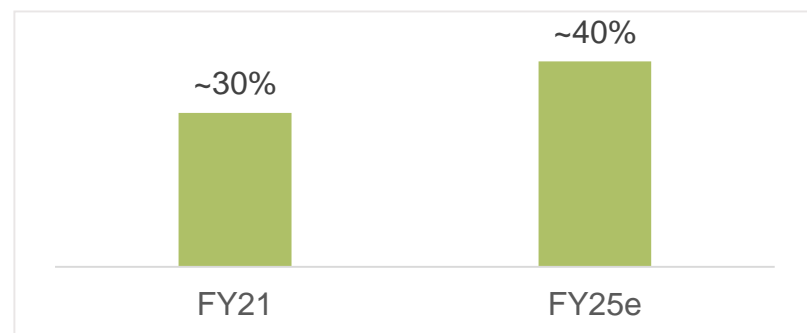
Strategic differentiation through in-house manufacturing



In-house manufacturing

- › We manufacture power and sensor technologies in-house where we can gain a strategic advantage from our leading-edge manufacturing technologies and our outstanding process expertise
- › This results in a differentiation potential in terms of cost and/or performance
- › **The current chip shortage highlights the strategic value of in-house manufacturing**

Infineon's outsourcing share

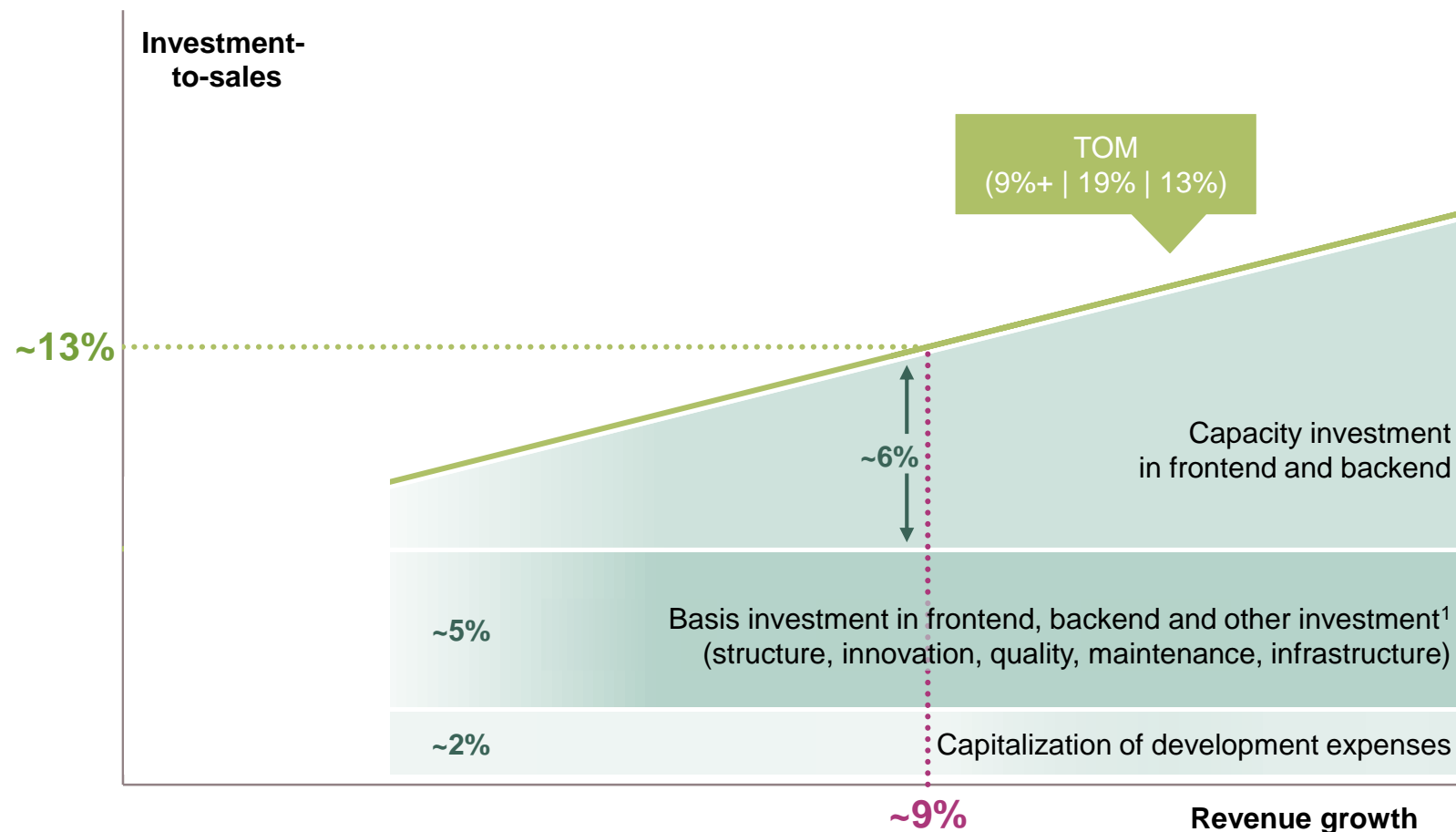


Outsourcing

- › We work with outsourcing partners where we see no or only little differentiation to optimize our capital efficiency (CMOS and derivate technologies and standard packages)
- › We cooperate with subcontractors and foundries in order to ensure adequate capacity growth and flexibility
- › Infineon's outsourcing share is expected to increase from ~30% in FY21 to ~40% in FY25

We focus our investments to those areas with highest differentiation

Split of investment-to-sales by category



Major focus topics

- › Capacity expansion for **SiC and GaN**
- › Further capacity expansion for **300 mm** in **Villach and Dresden**
- › Further capacity expansion for **200 mm** in **Kulim**
- › **Focused insourcing** from silicon foundries
- › **Clean room** for WBG / 300 mm and major office buildings (slightly above €1bn over five years)
- › **~€2.4bn** investments planned in FY22

¹ Frontend clean rooms and major office buildings are not included

Outlook for Q2 FY22 and FY22

	Outlook Q2 FY22 ¹	Outlook FY22 ¹
Revenue	~ €3.2bn	€13.0bn +/- €500m
Segment Result Margin	~ 22%	At the mid-point of the revenue guidance: ~ 22%
Investments in FY22		~ €2.4bn
D&A in FY22		€1.6bn - €1.7bn ²
Free Cash Flow in FY22		~ €1.0bn

¹ Based on an assumed average exchange rate of \$1.15 for €1.00

² Including the amortization of around 400 million Euros from the purchase price allocation for Cypress and, to a lesser extent, International Rectifier



ESG: targets and achievements



We contribute a net CO₂ reduction of more than 70 million tons

CO₂ burden¹

2.2 million tons
of CO₂ equivalents



Ratio ~1:33

CO₂ savings²

72.5 million tons
of CO₂ equivalents



Net ecological benefit: **CO₂ emissions reduction of more than 70 million tons**



Infineon is excellent in resource efficiency

We are committed to CO₂ neutrality by 2030

Our CO₂-saving applications are high-growth, we are part of the solution!

The ~1:33 ratio is expected to further improve in the coming years



¹ | ² For explanatory notes see "ESG footnotes" in the appendix.

Note: Compared to the last fiscal year, the increase in CO₂ burden can be mainly explained by the inclusion of the data from Cypress

Infiniteon is excellent in resource efficiency and committed to CO₂ neutrality – sustainability is in our DNA



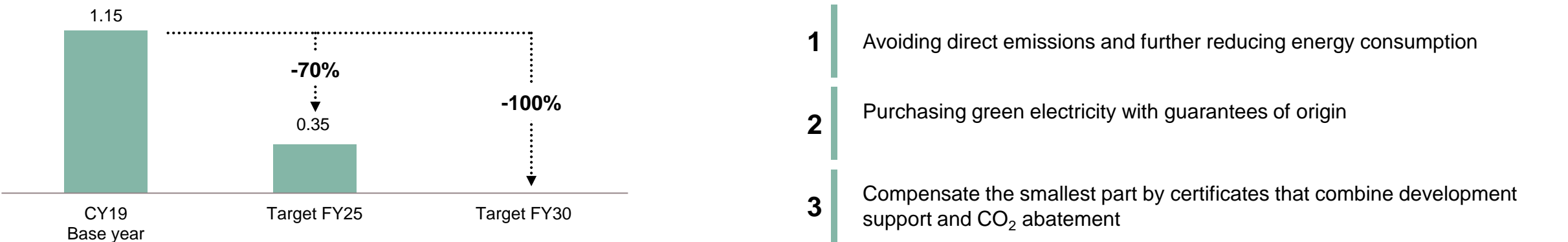
Infiniteon ranks among the 10 percent most sustainable companies in the world¹

In CY20, we used resources in our manufacturing processes much more efficiently than the global average of the semiconductor industry:



Infiniteon’s CO₂ target² by 2025 and 2030

Net CO₂ emissions in million tons of CO₂ equivalents²



¹ Based on the results of *The Sustainability Yearbook 2022* by S&P Global in cooperation with RobecoSam | ² Related to Scope 1 and 2 emissions

High-growth applications offer further additional CO₂ savings potential

In CY20:

Wind energy: Annual installation capacity increased over 80%¹



PV energy: Annual installation capacity increase of ~15%²



Drives: Increasing penetration of more efficient drives³



EVs: Increased sales contributed to an average fleet emission reduction of 14 g/km in Europe⁴












Net ecological benefit increases over time

¹ Wood Mackenzie: *Global Wind Power Market Outlook, Q2 2021*. June 2021 | ² Based on or includes content supplied by IHS Markit Climate and Sustainability Group: *PV Installations Tracker, Q2 2021*. June 2021

³ Based on or includes research from Omdia: *Industrial Motor Control Sourcebook 2020*. December 2020 | ⁴ CO₂ emissions from new passenger cars in Europe: Car manufacturers' performance in 2020 - 08/2021

External recognitions confirm our engagement in contributing to a sustainable society

		Rating/Score	Scale	Date
	MSCI ESG	AA	CCC to AAA	02/2021
	CDP	B climate scoring B water scoring	F to A	12/2021
	Ecovadis	99th percentile "Platinum" award	0 to 100	02/2022
	Dow Jones Sustainability Index	83 Dow Jones Sustainability™ World and Europe Index listing	0 to 100	11/2021
	Ethibel Sustainability Index Excelence Europe"	Index member	-	05/2020
	ISS ESG Corporate Rating	B- Prime Status	D- to A+	01/2021
	FTSE4Good Index	Index member	-	06/2021
	Euronext Vigeo Eurozone 120 Index Euronext Vigeo Europe 120 Index	Indices member	-	05/2021
	Sustainalytics	Top ESG performer	-	01/2022

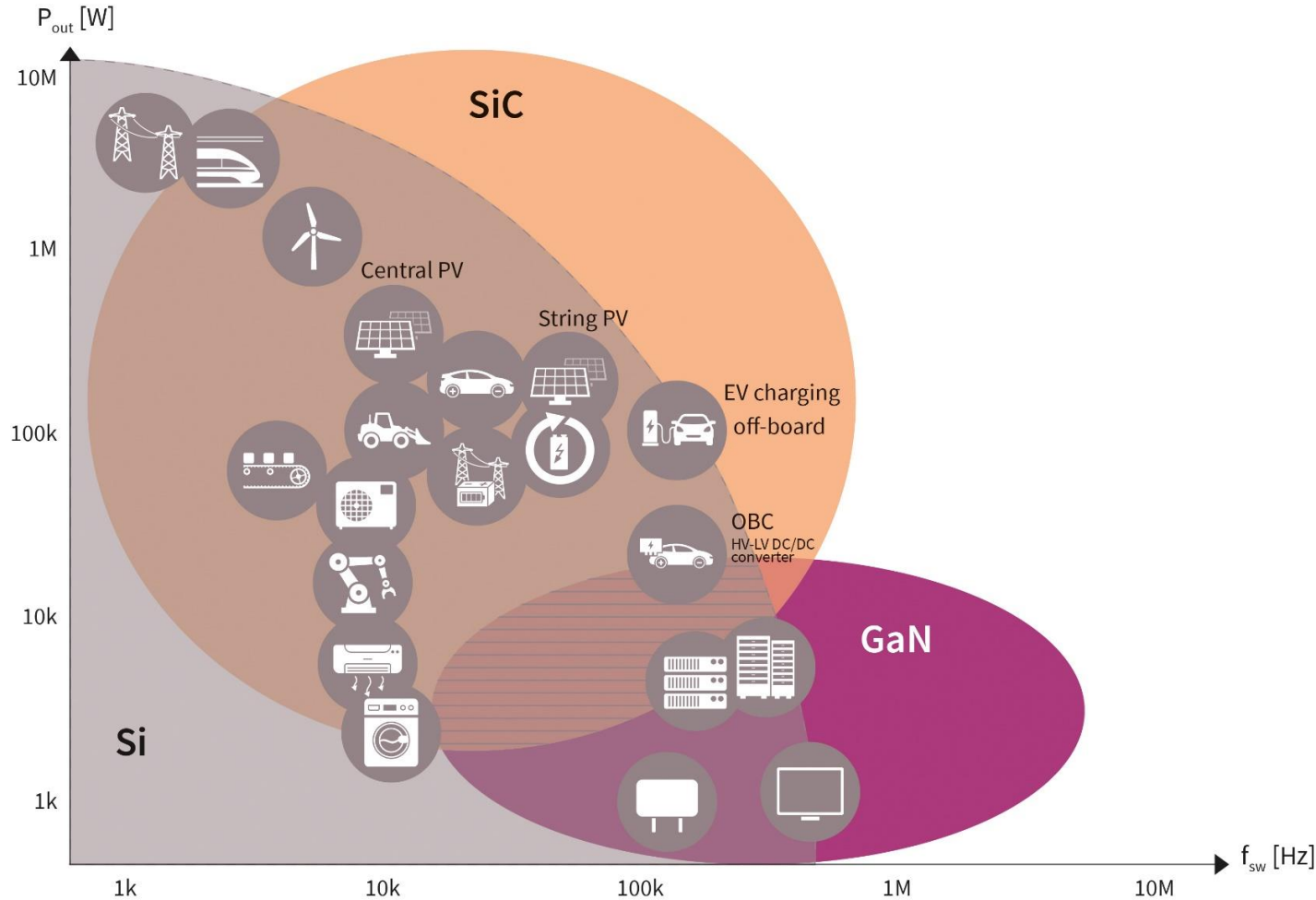


Infineon's Wide Bandgap Strategy



Leveraging full potential based on the power ratings and switching frequency required by the application

Comparison of technologies



Si

- › Si remains the mainstream technology
- › Targeting 25 V - 6.5 kV
- › Suitable from low to high power

SiC

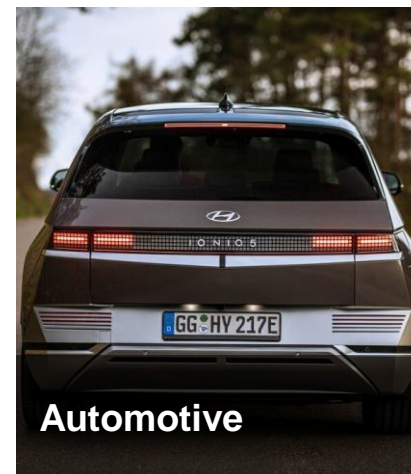
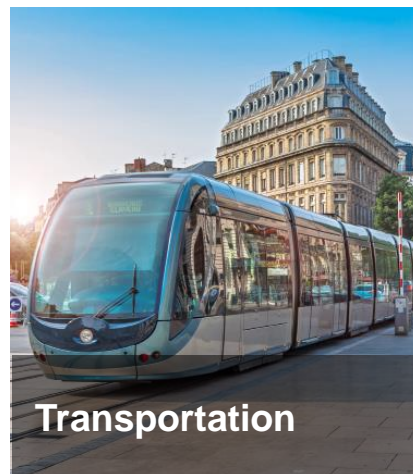
- › SiC complements Si in many applications and enables new solutions
- › Targeting 650 V - 3.3 kV
- › High power – high switching frequency

GaN

- › GaN enables new horizons in power supply applications and audio fidelity
- › Targeting 80 V - 600 V
- › Medium power – highest switching frequency

SiC – Infineon is serving all relevant applications

Focus applications



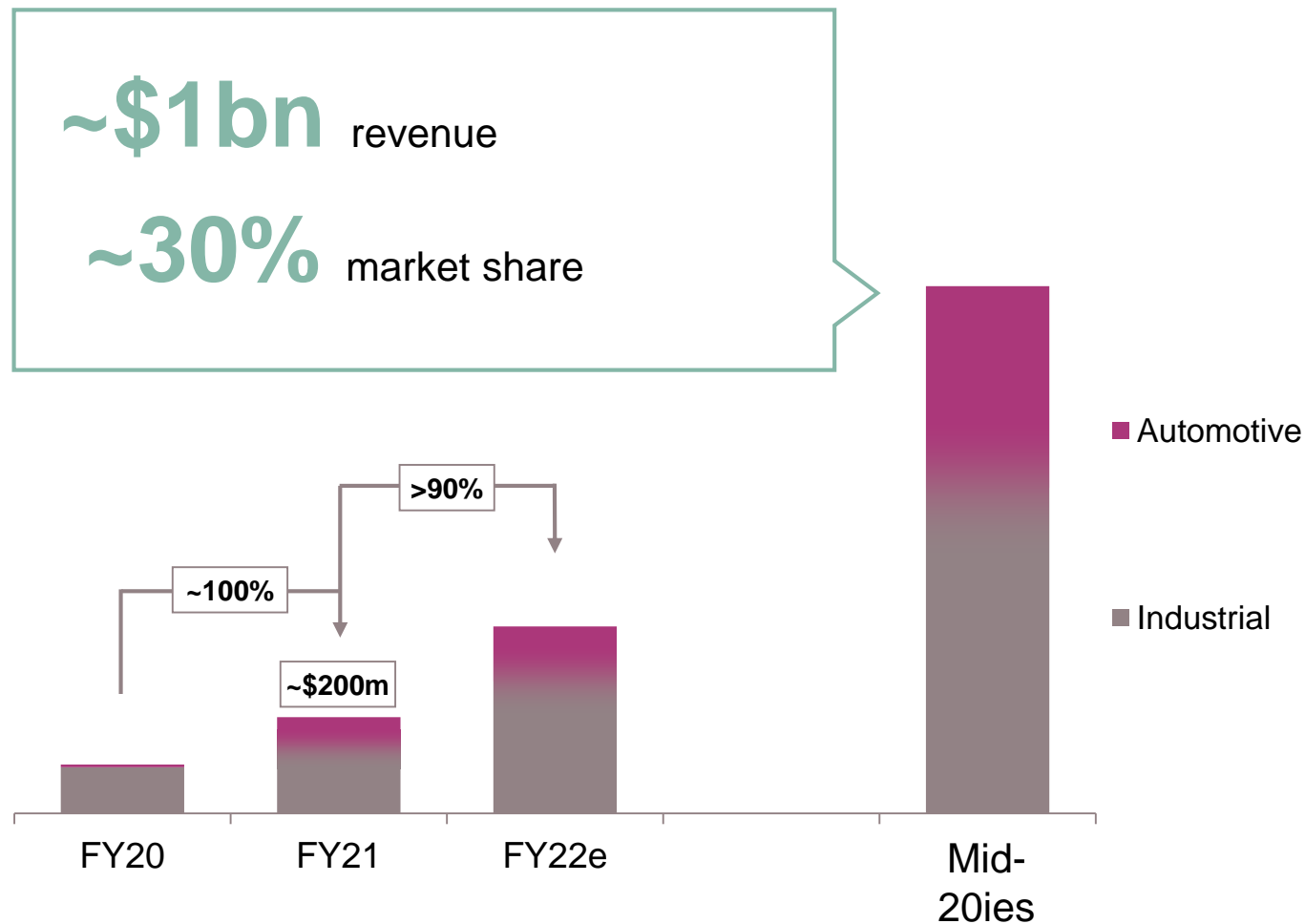
Infineon serves
> 3,000
 customers directly or via
 distribution

Customers



SiC – US\$ 1 billion revenue in sight

SiC revenue development

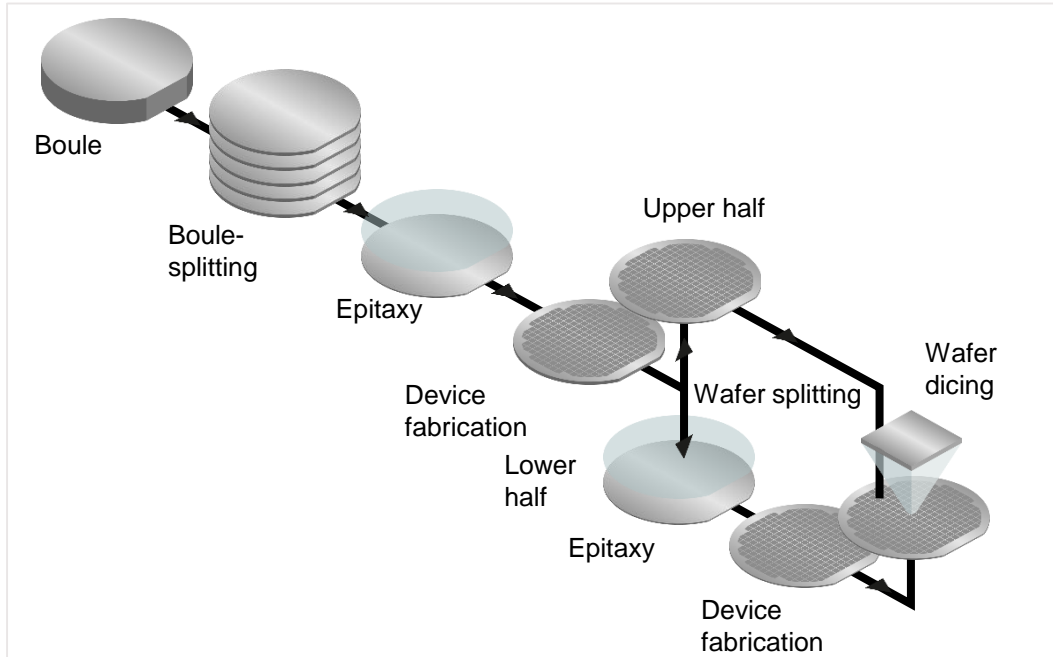


Infineon's success factors

- › Best in class Trench MOSFET on the market
- › 2nd Gen. CoolSiC™ Trench MOSFET will be launched in FY22
- › Broadest portfolio fits customers' individual needs
- › Scalable portfolio allows for easy and seamless upgrade from IGBT to SiC-based inverters
- › Strong module capabilities
- › System expertise and customer access

Our Cold Split technology leads to significant reduction of raw material losses during SiC manufacturing

Cold Split technology




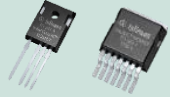
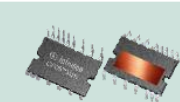







- › First product qualified on Cold Split technology
- › Ramping pilot line and prepare volume production
- › 3 supplier LTAs for boules and wafers in place

Crystal	Technology	# of wafers (indexed)
Today	SiC boule Sawing Grinding	1x
	Traditional wire sawing wastes ~75% of raw material!	
2021	SiC boule Boule Splitting Grinding	Up to 2x
	Boule splitting reduces raw material losses by 50%!	
Next step	SiC wafer Wafer Splitting	2x
	Wafer splitting results in minimal raw material losses!	

Strong CoolSiC™ portfolio expansion: by packages and by voltages

Broadest and best-in-class SiC portfolio

	Industrial						Automotive grade			
package options voltages	CoolSiC™ Diode	CoolSiC™ Hybrid		CoolSiC™ MOSFET			CoolSiC™ Diode	CoolSiC™ Hybrid	CoolSiC™ MOSFET	
	Discrete	Discrete	Module	Discrete	IPM	Module	Discrete	Discrete	Discrete	Module
										
600 V										
650 V										
1200 V										
1700 V										

Continuous expansion of portfolio

SiC and GaN capacity expansion to respond to fast growing demand

Villach, Austria



- › 150/200 mm Si lines will be converted to SiC and GaN manufacturing while reusing non specific equipment
- › → SiC capacity secured in Villach
- › → GaN scaling-up to volume manufacturing

Further expansion in Kulim

Kulim, Malaysia

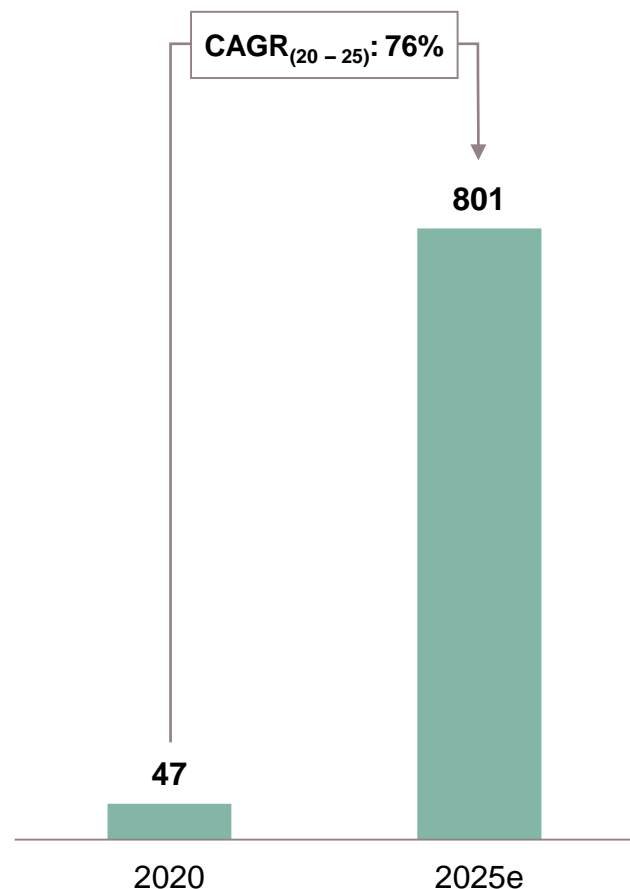


- › Transfers of
 - › 200 mm Si
 - › WBG epitaxy as first step
- › Ground ready for 3rd module

GaN technology – Infineon well positioned to address key markets

GaN market forecast¹

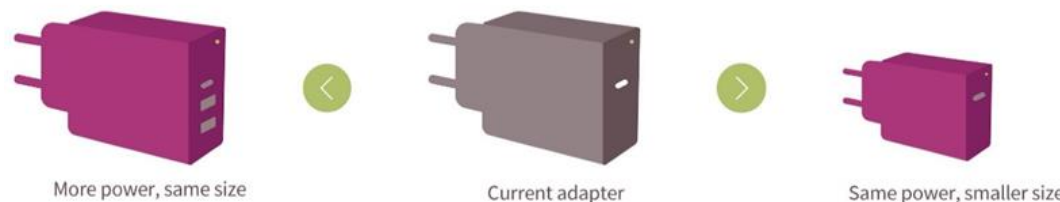
[USD m]



¹ GaN power devices market forecast. Yole Développement (Yole): *Compound Semiconductor Quarterly Market Monitor*. Q3 2021

Key values of GaN vs Si

Higher power density in adapters and chargers



10x
switching
frequency

> 2%
more power
efficiency

20%
lower
System Cost

25%
higher power
density

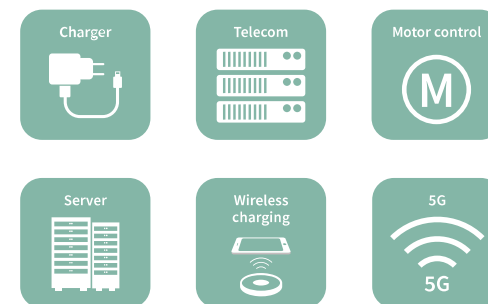
3x
less
weight

We combine leading-edge system and application understanding with additional strengths:

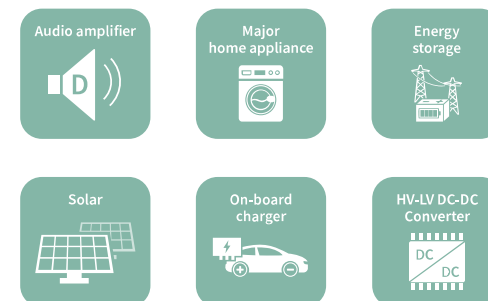
Broad GaN IP portfolio, large R&D force and best-in-class manufacturing landscape

Applications

Focus applications



Emerging applications



Infiniteon's GaN portfolio is seeing increasing demand from a broad range of applications

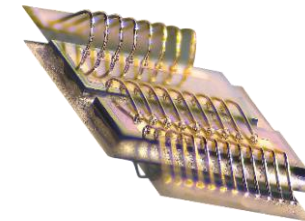
GaN for power applications

- › GaN discretes, GaN drivers, integrated power stages (including the right-fit driver) for 650 V, 600 V, 200 V and 100 V with a broad package portfolio, as well as controllers addressing the consumer and industrial market
- › GaN for power chips are focused on high current-carrying capacity at frequencies below 10 MHz
- › Increasing revenue and design wins, e.g. in charger and adapter, servers for data center, edge computing and telecom, notebook as well as handhelds



GaN for RF applications

- › GaN power amplifier with frequencies of 2.5 to 2.7 GHz and 8 W output power for 5G applications and satellite communications. Power amplifier modules including a RF GaN chip and an integrated bias and control-IC in development
- › GaN for RF chips are focused on high frequencies beyond 1 GHz
- › GaN power amplifiers are already shipped to a leading global infrastructure provider of power antennas for 5G basebands



GaN design wins of more than €1bn achieved

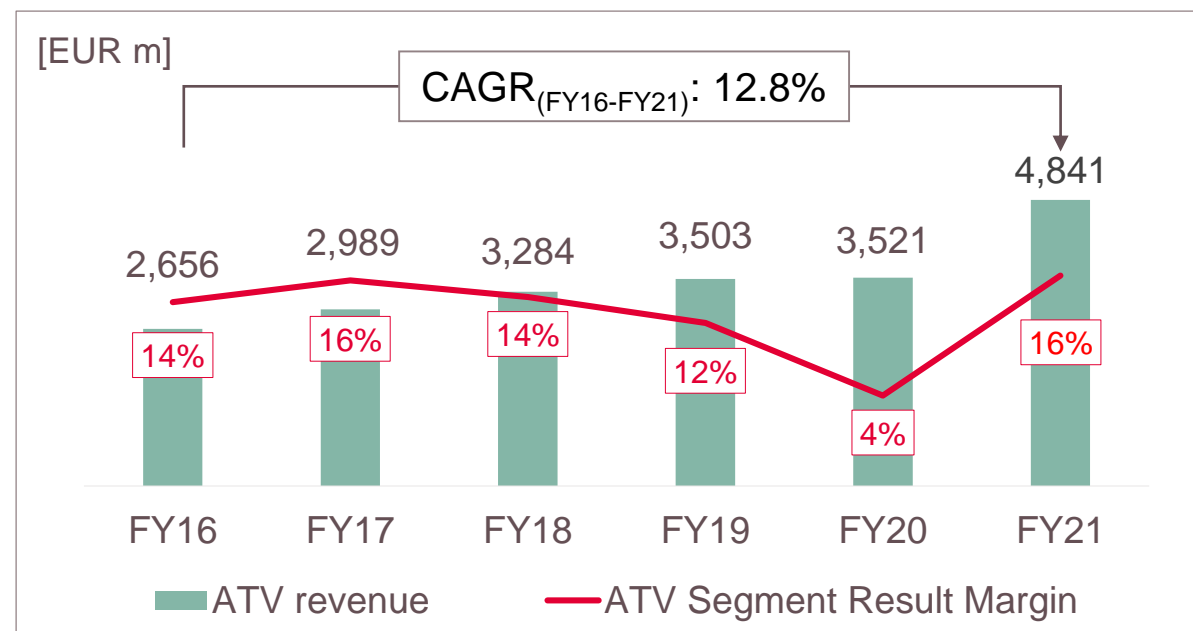


Automotive

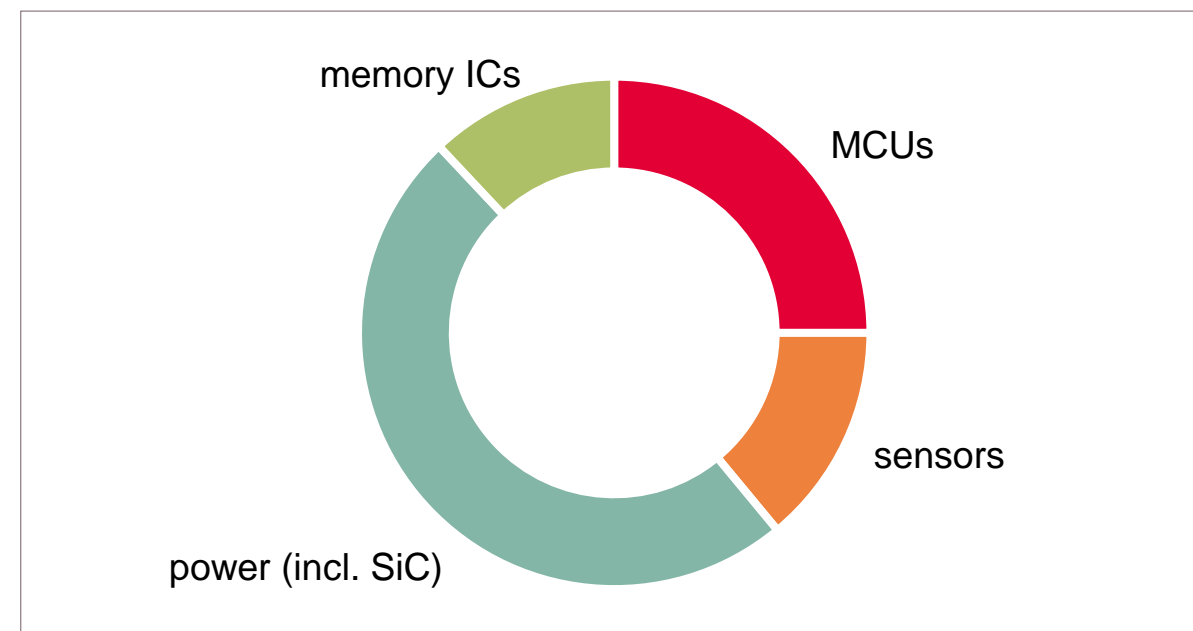


ATV at a glance

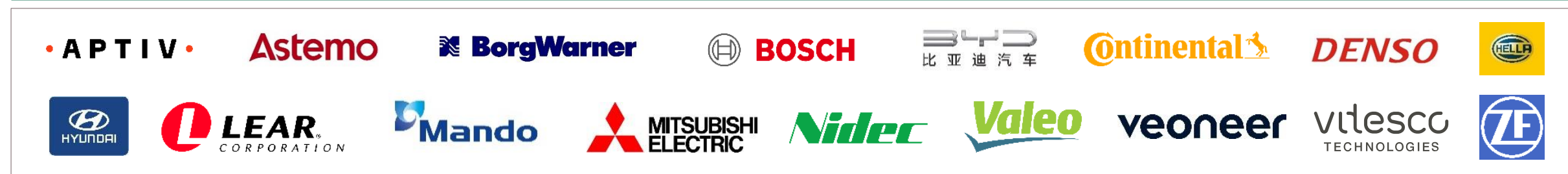
ATV revenue and Segment Result Margin






FY21 revenue split by product group



Key customers



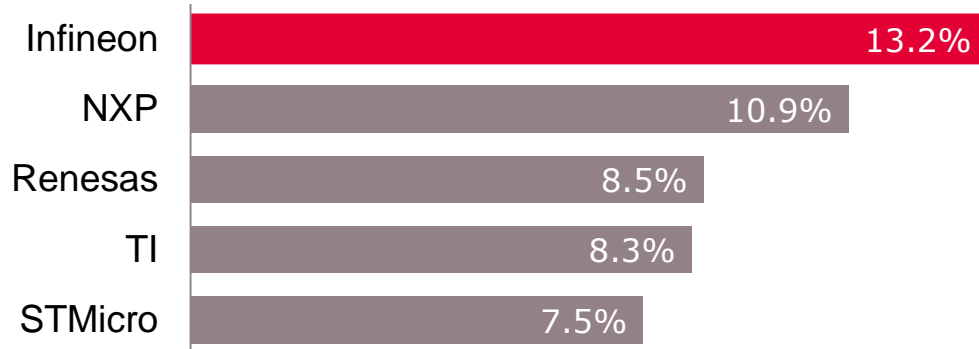
Market outlook for ATV division's target applications

Applications	Market Outlook for CY22
<div data-bbox="208 454 351 596"> <p>Automotive</p>  </div>	<ul style="list-style-type: none"> › Market demand-supply uncertainties to continue into CY22 due to COVID-19 pandemic and component supply limitations › Gradual easing of semiconductor shortages throughout the year expected; risks of further supply chain disruptions remain › Elevated share of higher-end cars expected to persist
<div data-bbox="208 796 351 939"> <p>eMobility</p>  </div>	<ul style="list-style-type: none"> › Electromobility momentum expected to continue › Stricter CO₂ regulations, government incentives as well as consumer demand expected to support the growth momentum › Acceleration of OEMs' xEV roadmaps, build-up of battery capacities are expected to continue into 2022
<div data-bbox="208 1103 351 1246"> <p>Autonomous driving</p>  </div>	<ul style="list-style-type: none"> › L1 and L2 will see strong growth as L0 share declines › L2+ penetration expected to increase; first L3 models with regulatory approval to be launched › Robotaxi pilots and small-scale launches continue

Infiniteon's top market position is built on system competence based on an industry-leading product portfolio

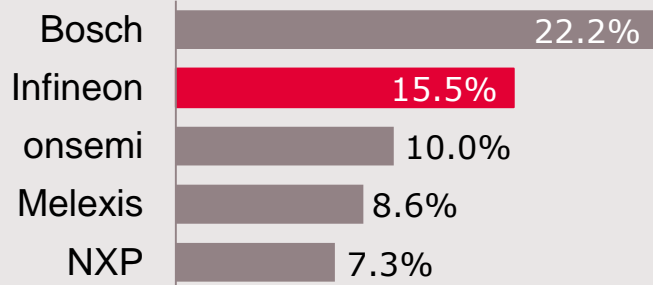


Automotive semiconductors (2020 total market: \$35.0bn)

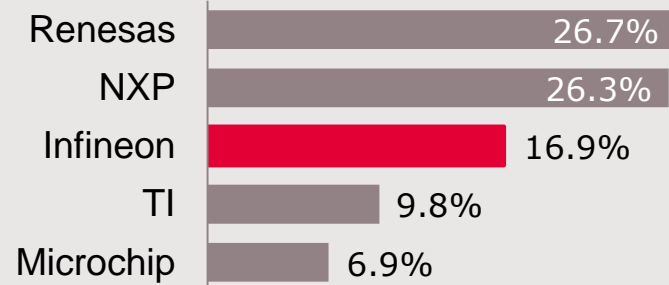


- › Strengthened #1 position; increasing distance to #2
- › #1 in power semiconductors
- › Undisputed #1 in automotive NOR Flash memory ICs
- › #2 position in sensors
- › Solid #3 position in microcontrollers due to strong demand in AURIX™, TRAVEO™ and PSoC™ families

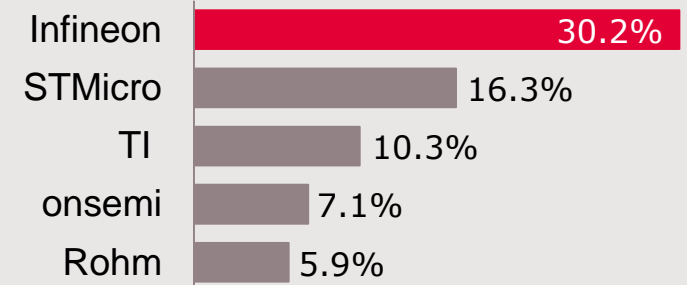
Sensors



Microcontrollers



Power semiconductors

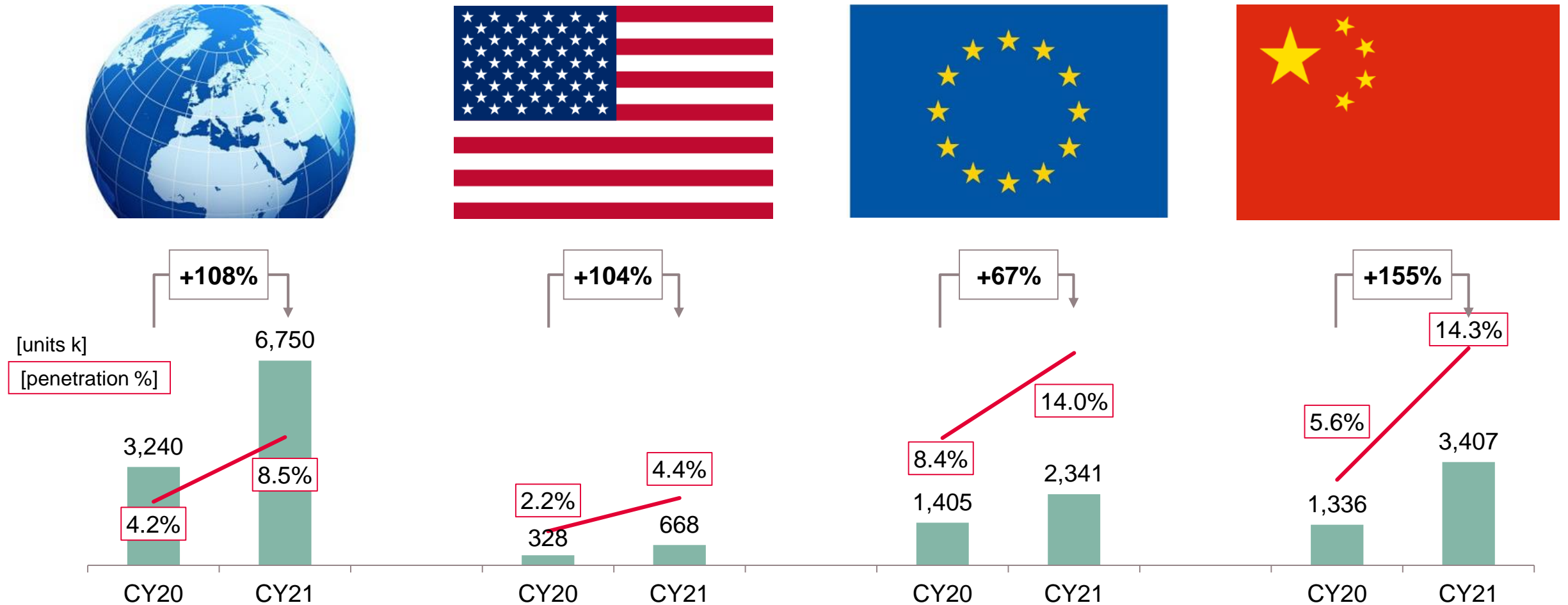




Electromobility



In CY21, xEV (PHEV + BEV) sales more than doubled yoy reaching ~6.7m units globally and more than 8% penetration



Source: Based on or includes content supplied by IHS Markit Automotive: PEV Volumes. November 2021; EV-volumes.com. January 2022.

The road to emission-free cruising: Governments and OEMs indicated when to ban the ICE

/ Government regulations

2035:

- › EU: all new cars zero-emission.
- › China: public transport vehicles to be fully electrified.
- › Canada: no new ICE on sales.
- › California, Massachusetts, New Jersey, Thailand: no ICE on the street.

2030:

- › USA: ~40% of new vehicle sales to be BEVs.
- › Japan: no ICE on the street.
- › UK, Denmark, Sweden, Ireland, Netherlands: no ICE on sale.
- › International Energy Agency: no new ICE car sales recommended. 60% of global car sales to be BEV or H₂.

2025:

- › Norway: no new ICE on sale.
- › Mallorca: no Diesel car on sale.
- › Netherlands, special zones: only electrified trucks and delivery vehicles allowed.

2023: Spain, cities with > 50,000 inhabitants: only zero-emission vehicles allowed.

2050: Spain, cities with > 50,000 inhabitants: no ICE on the street.

2040: Spain, cities with > 50,000 inhabitants: no new ICE on sale.

2040:

- › Honda: "All new vehicles will be BEV."

2039:

- › BMW: "All new vehicles will be BEV."

2035:

- › GM: "All new vehicles will be BEV."
- › VW brand: "To end sales of ICEs in Europe."

2033:

- › Audi: "All new vehicles will be BEV."

2030:

- › VW brand: "> 70% of all new vehicles to be BEV in Europe."
- › Volvo: "All new vehicles will be BEV."
- › Ford: "All new vehicles in Europe will be BEV. 40% of Ford global vehicle volume to be BEV."
- › Jaguar: "No new ICEs."
- › BMW: "50% of all new vehicles to be BEV."

2025:

- › Lamborghini: "All new vehicles will be BEV or PHEV."
- › Mercedes: "The upcoming S class generation will be available as BEV only. All new vehicle architectures are BEV only (no longer PHEV). ~50% of all new vehicle sales to be BEV or PHEV (vs ~25% so far)."

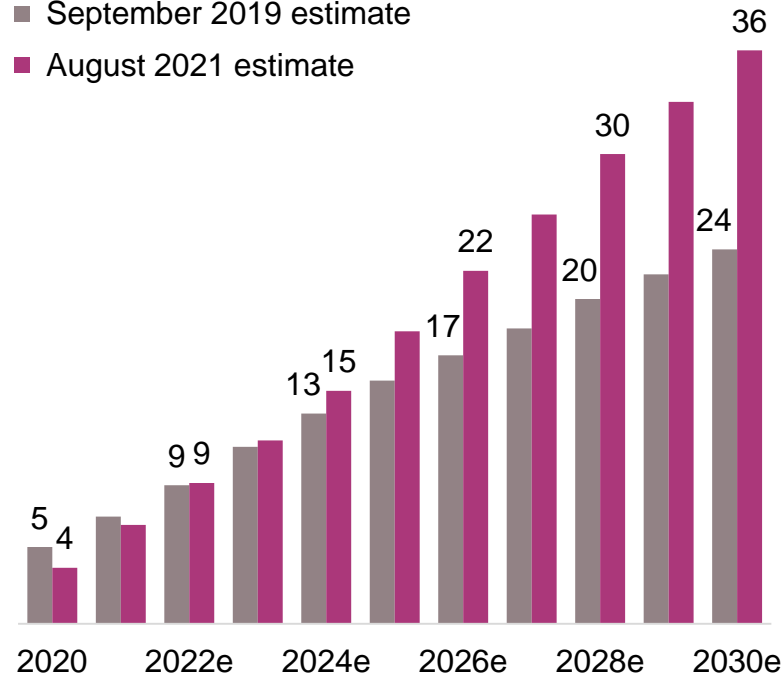
/ OEM statements

The penetration of PHEV + BEV is accelerating; the incremental content of power semis in xEV is a significant opportunity for Infineon

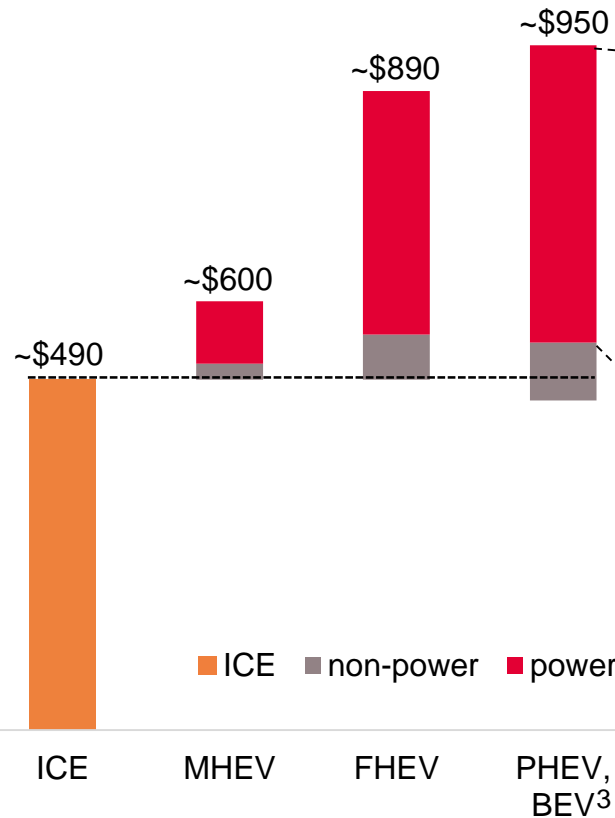
PHEV + BEV annual car production¹

[m units]

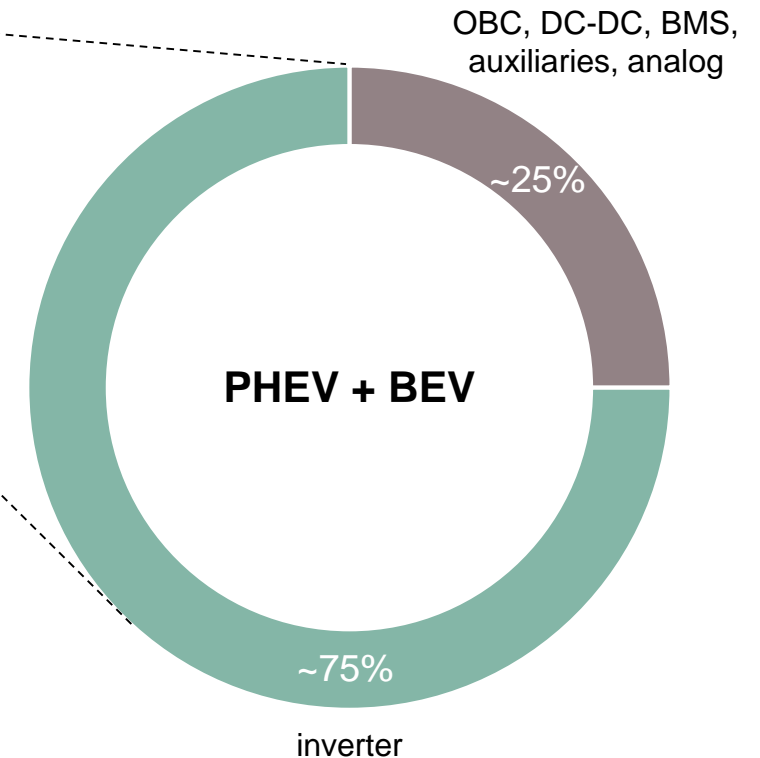
■ September 2019 estimate
■ August 2021 estimate



2021 average xEV semi content²



Incremental power semi by application



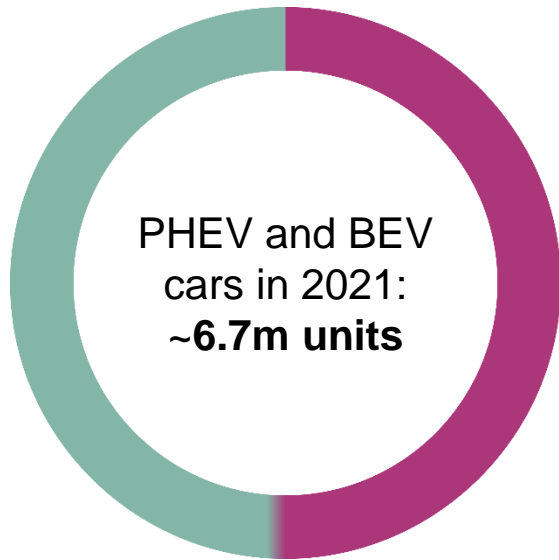
¹ Based on or includes content supplied by IHS Markit Automotive: *Alternative Propulsion Forecast*. September 2019, August 2021.

² Strategy Analytics: *Automotive Semiconductor Demand Forecast 2019 - 2028*. July 2021; Infineon. "power" includes voltage regulators, ADCs and ASICs.

³ Due to missing ICE engine in BEV the weighted incremental semiconductor content for PHEV and BEV starts below the "~\$490" line.

For newly produced cars in CY21, about every second inverter for a PHEV or BEV car is equipped with Infineon power semiconductors

2021 PHEV + BEV inverters¹



Share of inverters equipped with Infineon chips or modules

Ex. of OEMs powered by Infineon



Examples of SiC design-wins



- › Infineon has an excellent position to win upcoming SiC-based xEV platforms:
 - leverage huge IGBT customer base with broadest portfolio and full system solution
 - seamless and cost-effective upgrade path across entire power range

¹ Based on or includes content supplied by IHS Markit Automotive. January 2022; Strategy Analytics: *Automotive Semiconductor Demand Forecast 2019 - 2028*. July 2021; Infineon



Automated Driving



The car of the future is driving digitalization in many aspects and Infineon provides the ingredients



ADAS/AD

- › object recognition
- › advanced spatial sensing
- › MCU (AURIX™, TRAVEO™ 2, PSoC™)
- › radar sensor
- › NOR flash and RAM memory



software-over-the-air

- › remote OS updates
- › secure feature upgrades
- › NOR flash memory
- › security solution



infotainment and HMI

- › seamless digital entertainment
- › always-on, secure connectivity
- › intuitive user interface (UI)
- › MCU (AURIX™, TRAVEO™ 2, PSoC™)
- › Wi-Fi, Bluetooth®, USB Type C
- › touch controller with CapSense™



digital instrument cluster

- › real-time driver information
- › user-specific digital content
- › MCU (AURIX™, TRAVEO™ 2, PSoC™)
- › NOR flash and RAM memory



Car of the future



comfort / premium

- › automatic exterior and interior lighting
- › passenger-specific automatic settings
- › MCU (AURIX™, TRAVEO™ 2, PSoC™)
- › pressure and magnetic sensors
- › LED driver ICs

The Infineon AURIX™ MCU family has become the first-choice automotive architecture for high-growth and safety-critical applications



Infineon AURIX™ revenue development over time

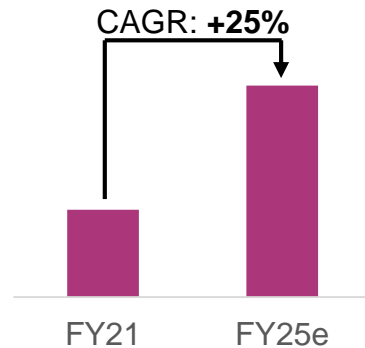
Powertrain

- › ICE engine management
- › ICE transmission
- › xEV motor control



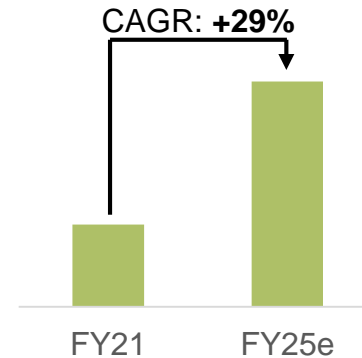
Classical safety

- › power steering
- › braking
- › airbag



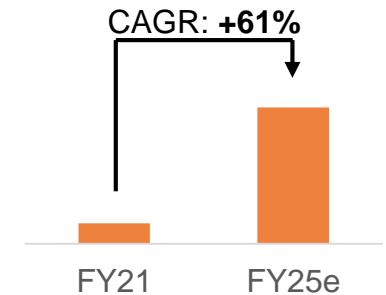
ADAS/AD

- › camera host control
- › sensor fusion host control
- › radar signal pre-processing



Domain and zone control

- › drive domain
- › body & convenience domain
- › zone control



Example of AURIX™ platform design-win



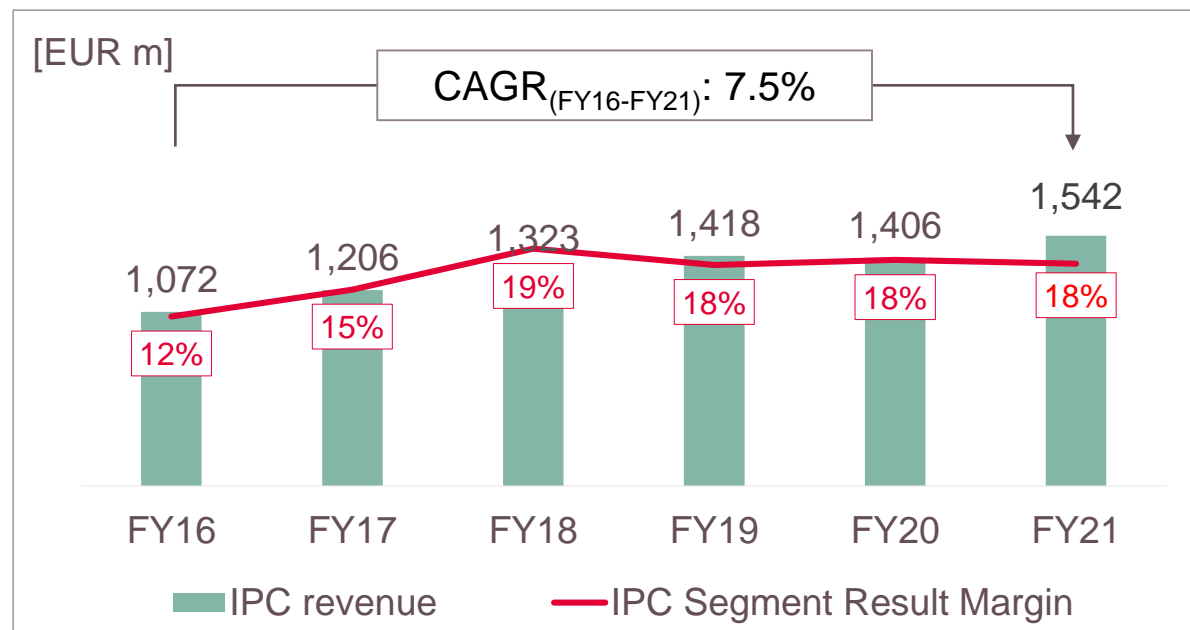


Industrial Power Control

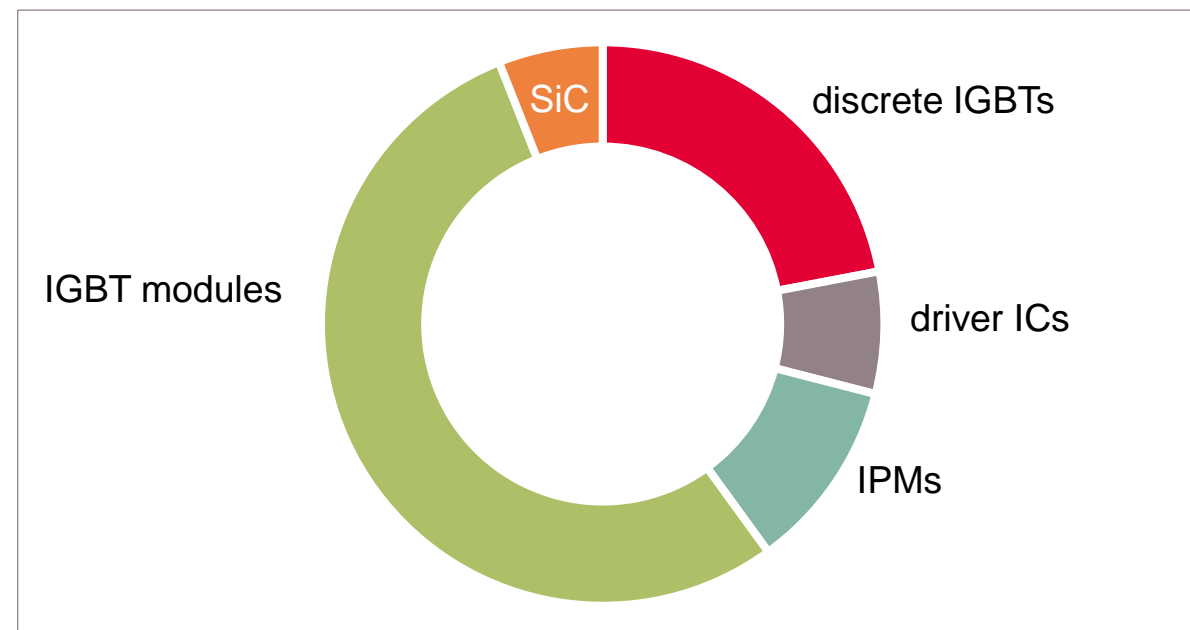


IPC at a glance

IPC revenue and Segment Result Margin











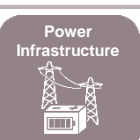



FY21 revenue split by product group (indicative)



Key customers



Market outlook remains positive across most target applications; growth rates returning to normal long term patterns

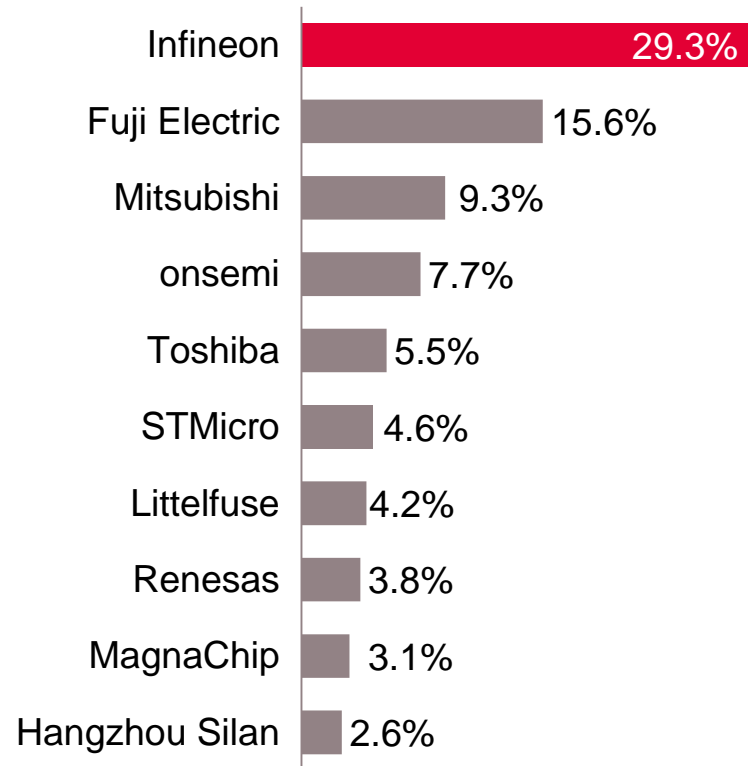
Applications (% of FY21 segment revenue)	Market Outlook for CY22	
 <div>Automation and Drives</div> <div>~33%</div>		> After strong recovery in CY21, growth rates returning to long-term averages
 <div>Renewable Energy Generation</div> <div>~28%</div>		> Wind: installations forecasted at similar level as in CY21 > PV with ongoing double-digit growth in installations
 <div>Home appliance</div> <div>~17%</div>		> Demand still driven by energy efficiency incentives for major appliances; growth after strong surge in CY21 expected to be flattish
 <div>Transportation</div> <div>~7%</div>		> Overall expectations dominated and dampened by still delayed recovery for traction in China; growth expected for delivery vehicles and eTrucks, as well as for traction projects in other regions
 <div>Power Infrastructure</div> <div>~8%</div>		> Strong growth of xEV driving charging infrastructure; continuous installation of renewable energy generation driving energy storage systems
 <div>Others</div> <div>~7%</div>		> Long-term positive outlook driven by general trend of electrification in emerging applications (e.g. eMarine)

Clear leader in discrete IGBTs and IGBT modules; fostering position in IPMs



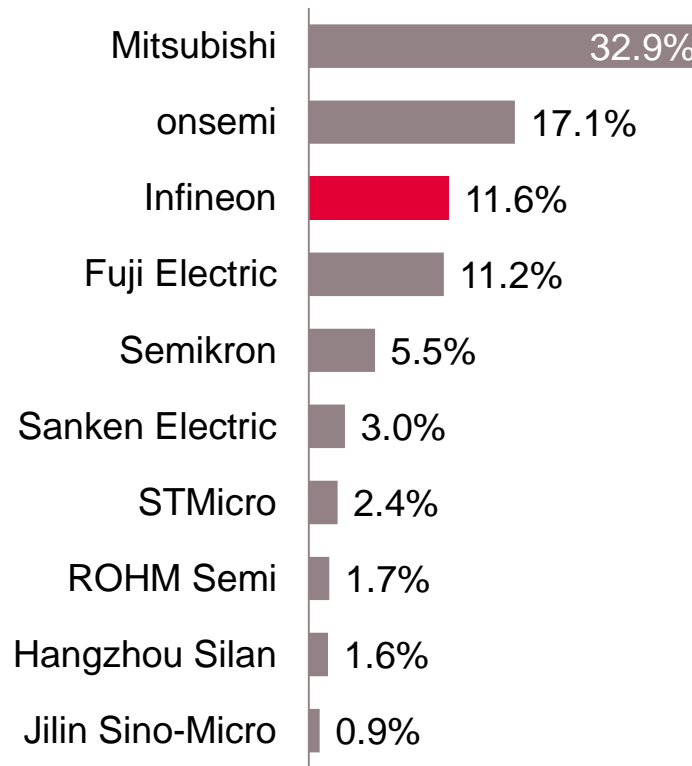
Discrete IGBTs

2020 total market: \$1.59bn



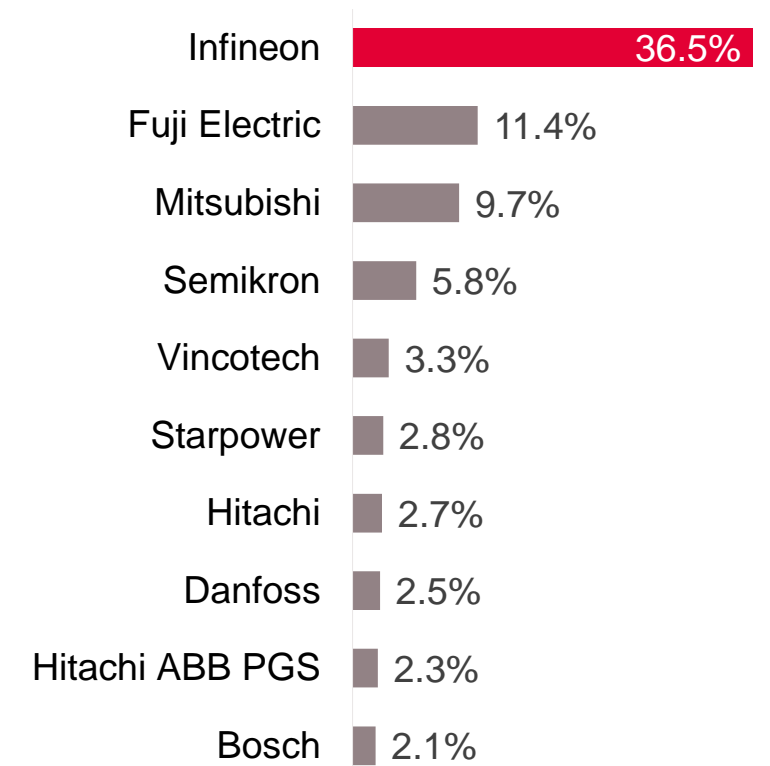
IPMs

2020 total market: \$1.43bn



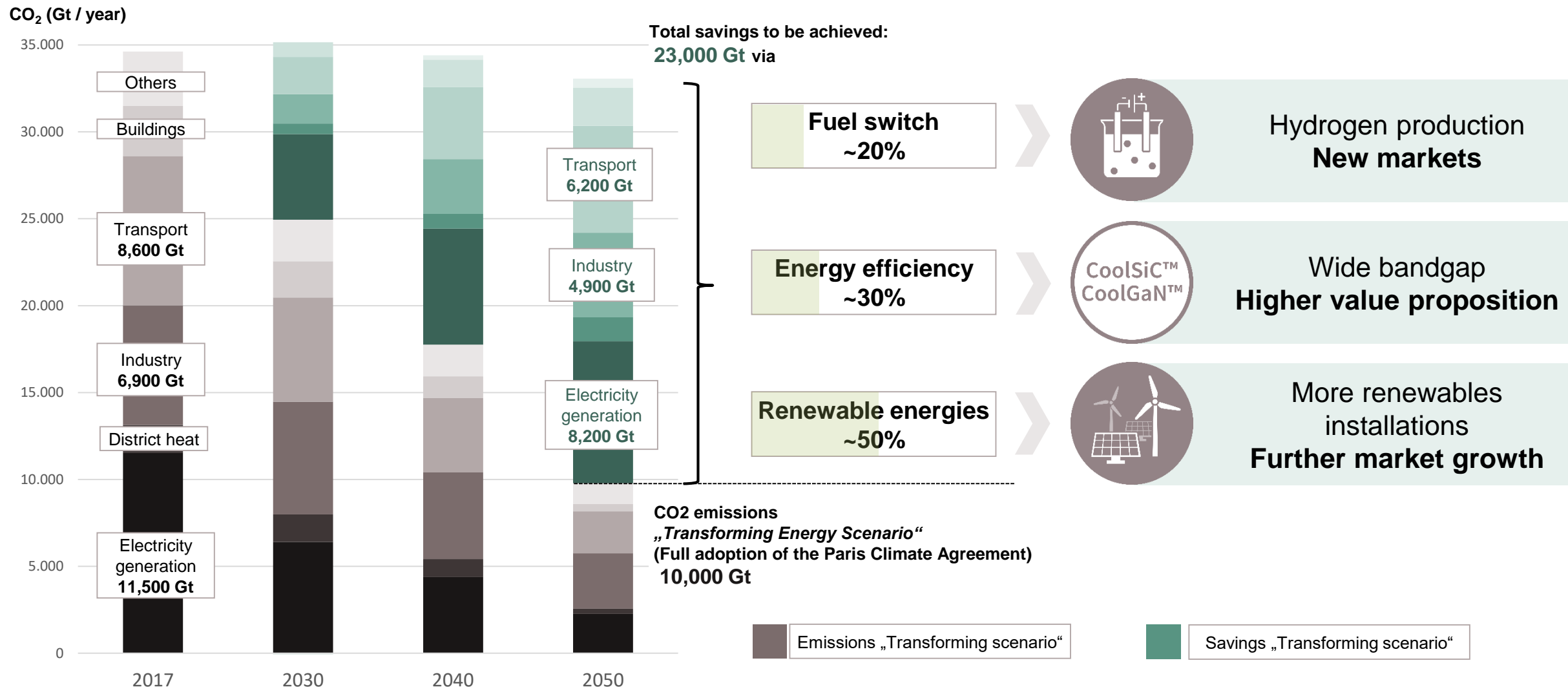
IGBT modules¹

2020 total market: \$3.63bn



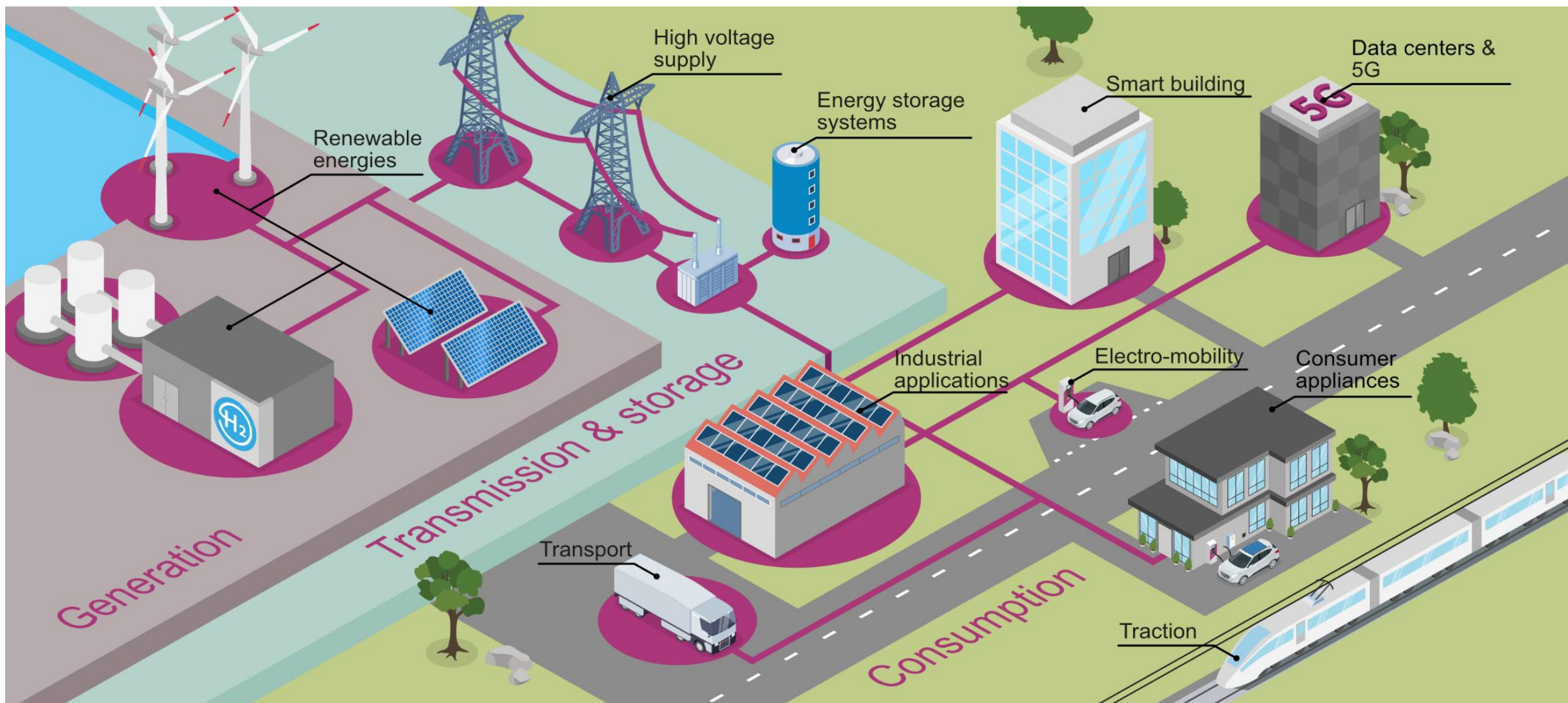
¹ Including standard (non-integrated) IGBT modules and power integrated modules (PIMs) / converter inverter brake (CIB) modules
Based on or includes research from Omdia: *Power Semiconductor Market Share Database 2020*. September 2021

Infineon will benefit from all CO₂ saving measures



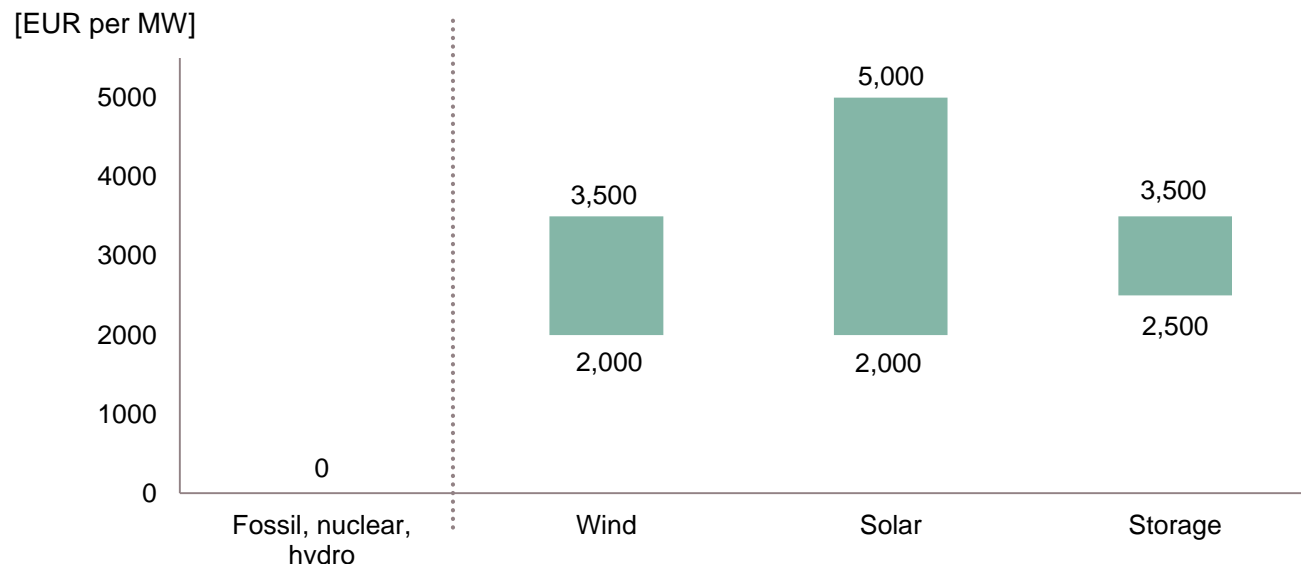
Source: IRENA, „Global Renewables Outlook 2020“

Infineon provides solutions for all links in the energy conversion chain



Green energy generation provides large business opportunities

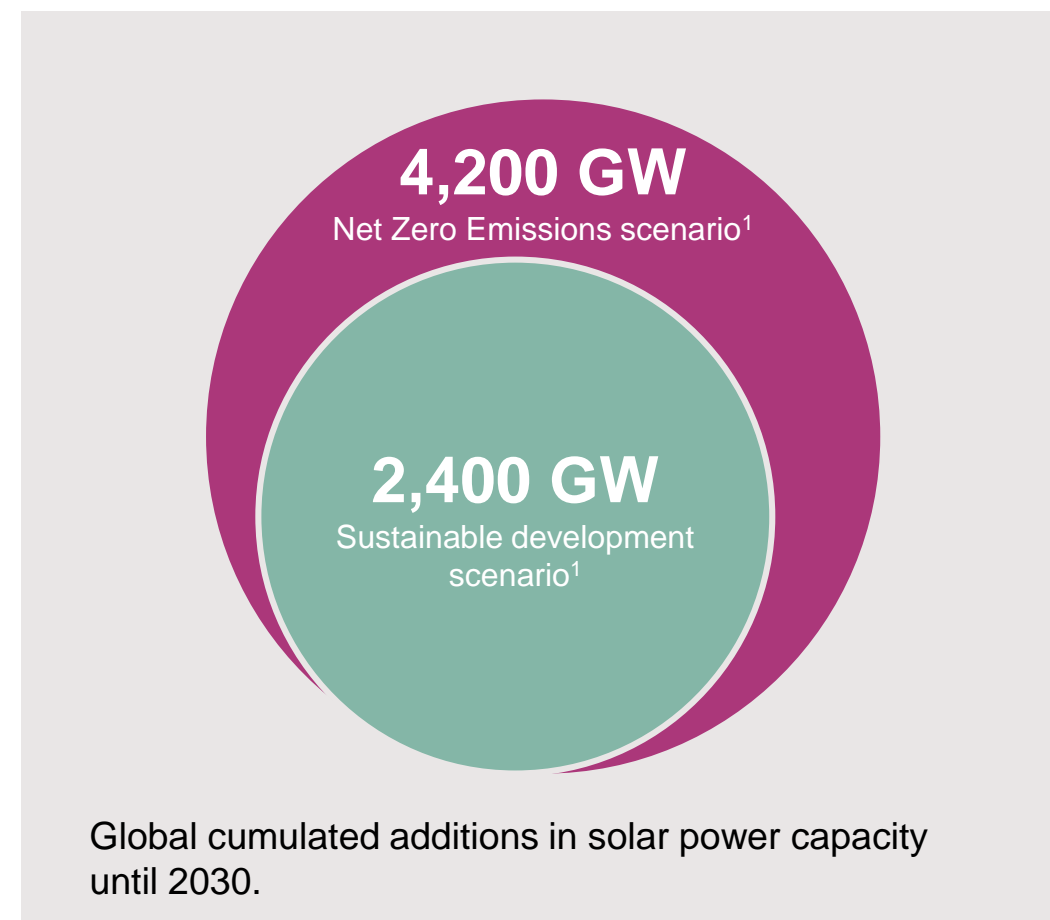
Power semiconductor content by application



Additions in 2020	[GW]	114	134	5 ²
Ø 2021 – 2030 annual additions Sustainable development scenario ¹		110	240	22 ²
Ø 2021 – 2030 annual additions Net Zero Emissions (NZE) scenario ¹		240	420	33 ³

¹ IEA: *Net Zero by 2050 - A Roadmap for the Global Energy Sector*. May 2021 | ² Based on or includes content supplied by IHS Markit Climate and Sustainability Group: *Grid Connected Energy Storage Market Tracker H1 2021*. August 2021
³ Extrapolation; conservative assumption of equal ratio renewable generation to storage capacity

Upside potential: example solar power



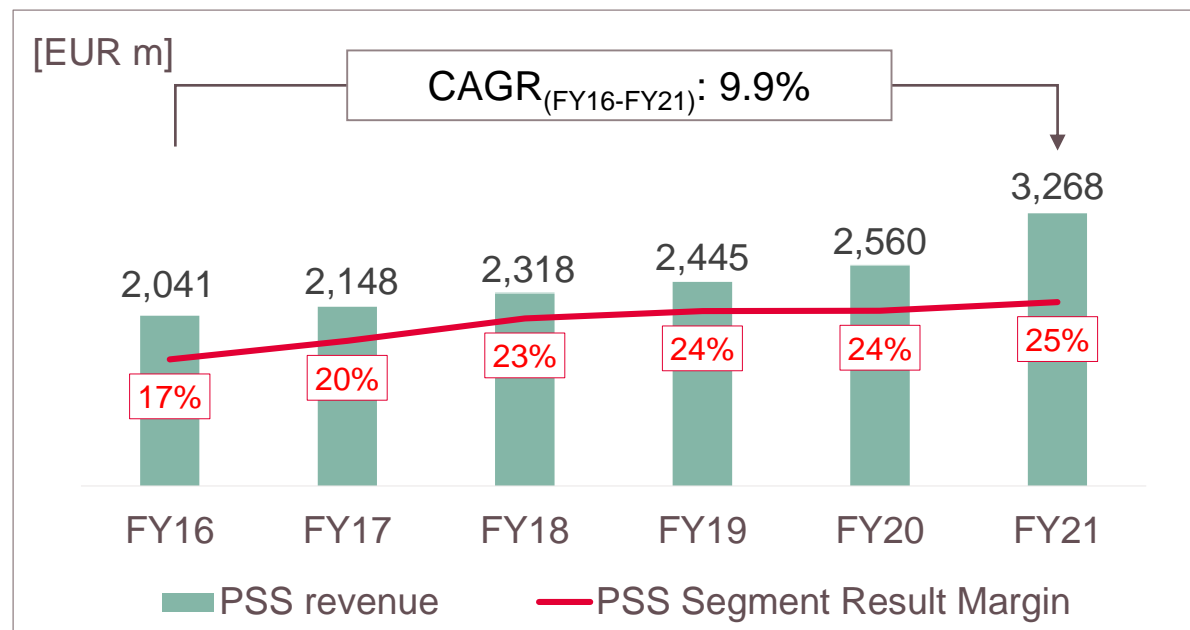


Power & Sensor Systems

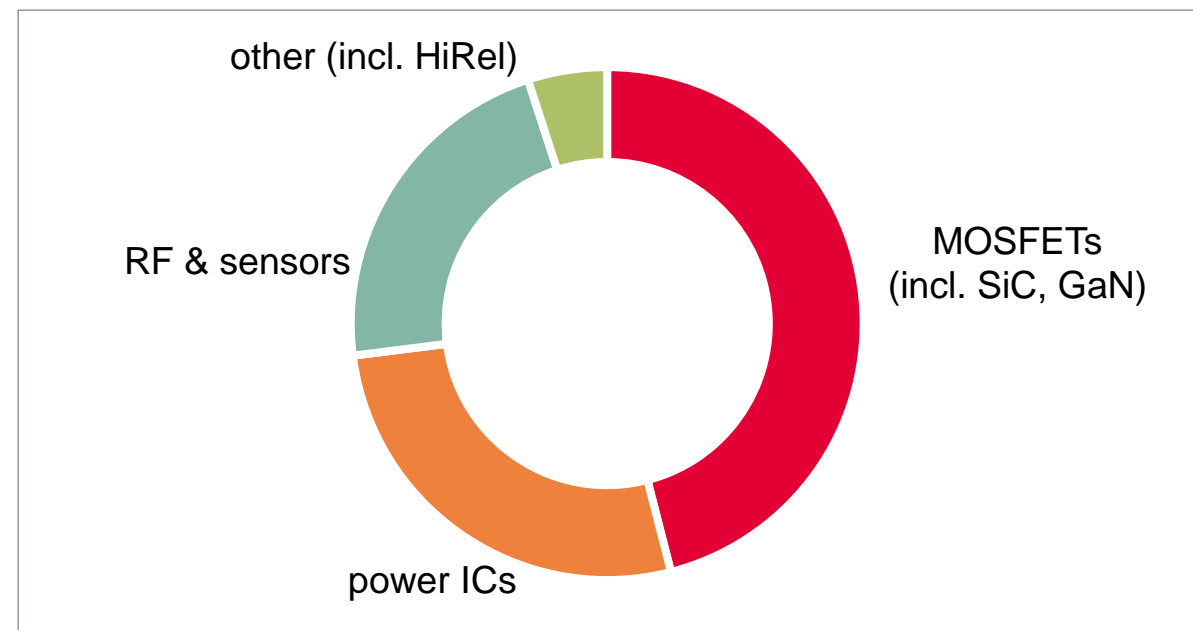


PSS at a glance

PSS revenue and Segment Result Margin













FY21 revenue split by product group



Key customers



Market outlook positive across virtually all target applications

Applications (% of FY21 segment revenue) ¹		Market Outlook for CY22	
<div>Computing</div> <div></div> <div>~20%</div>	<div></div> <div><ul style="list-style-type: none">> Structural growth driven by cloud computing and to a lesser extent by enterprise servers> Notebook PC shipments are expected to grow steadily (remote work), but PCs for education likely to experience saturation</div>		
<div>Communication</div> <div></div> <div>~5%</div>	<div></div> <div><ul style="list-style-type: none">> 5G cycle will continue to drive telecom equipment spending in CY22> Remaining trade tensions generate some uncertainty around speed of roll-outs</div>		
<div>Smartphone</div> <div></div> <div>~17%</div>	<div></div> <div><ul style="list-style-type: none">> Positive unit growth is expected for CY22 despite supply shortages through continued strong demand also driven by 5G replacement cycle</div>		
<div>Consumer</div> <div></div> <div>~24%</div>	<div></div> <div><ul style="list-style-type: none">> Demand expected to decline in some consumer areas, e.g. TVs, in light of re-allocation of consumer spending</div>		
<div>Industrial</div> <div></div> <div>~25%</div>	<div></div> <div><ul style="list-style-type: none">> Demand in renewable energy, EV charging and automotive expected to be healthy; value chain risks to be watched> Tailwinds from US, EU and Asia stimuli packages for infrastructure/ green energy initiatives</div>		

¹ does not sum up to 100% due to other applications not shown here

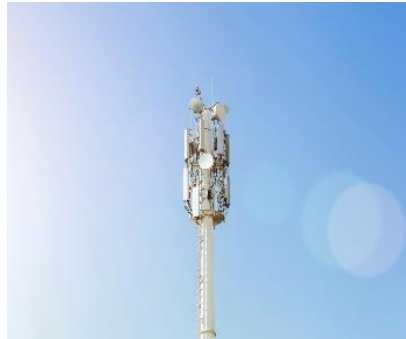
PSS's growth is built on many applications from different sectors in power and non-power

Computing



- › data center
- › enterprise server
- › PC, notebook
- › peripherals
- › chargers and adapters

Communications



- › base stations
- › backhaul cellular infrastructure
- › 5G massive MIMO
- › telecommunication servers

Smartphones



- › smartphones
- › mobile devices
- › wearables
- › USB Type-C, USB Type-C PD

Consumer



- › eBikes, eScooter
- › multicopter
- › LSEV
- › gaming
- › TV sets
- › smart home

Industrial



- › power supplies
- › EV on-board charger
- › charging infrastructure
- › PV inverter
- › power tools
- › lighting
- › Industry 4.0
- › aerospace



PSS – Power

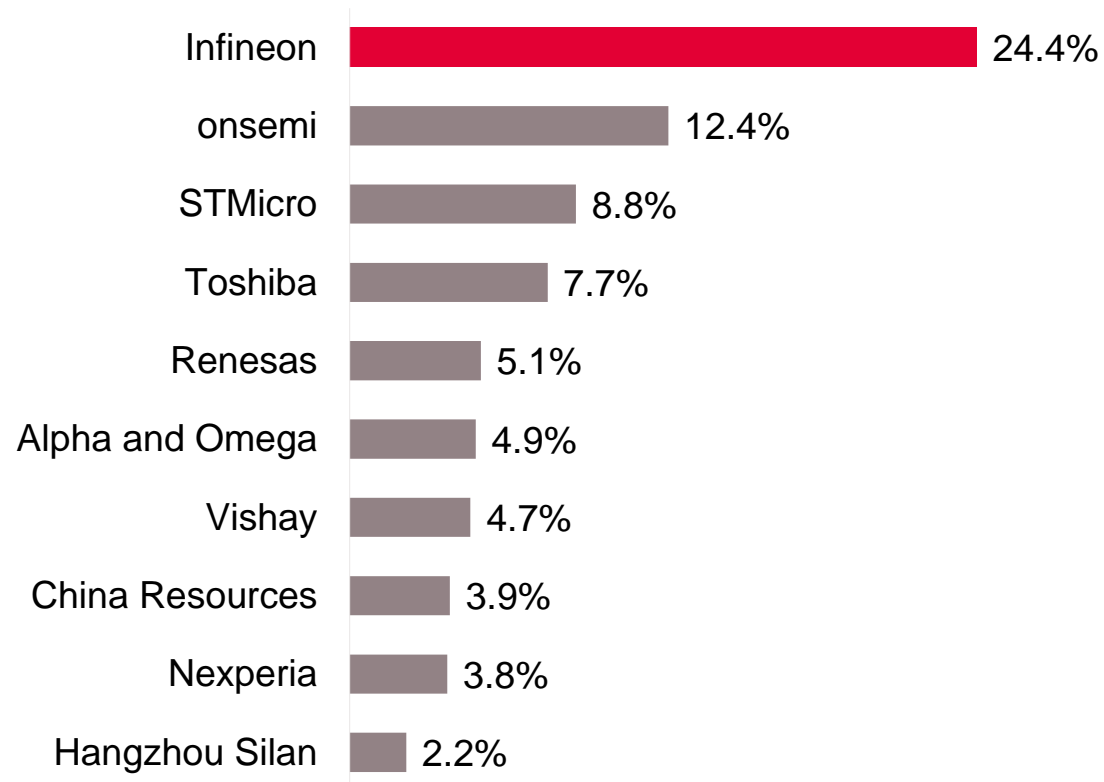


Infineon is the clear leader in MOSFETs; growth potential in power ICs



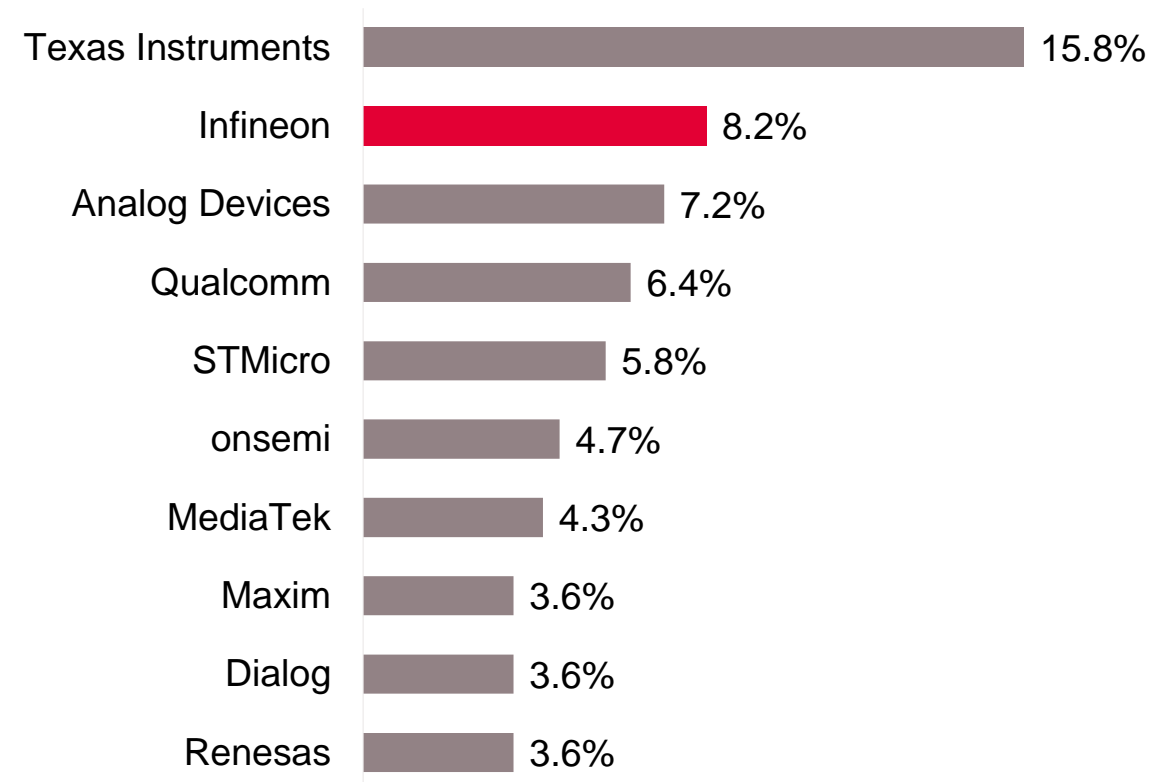
Discrete Power MOSFETs¹

2020 total market: \$8.1bn



Power ICs²

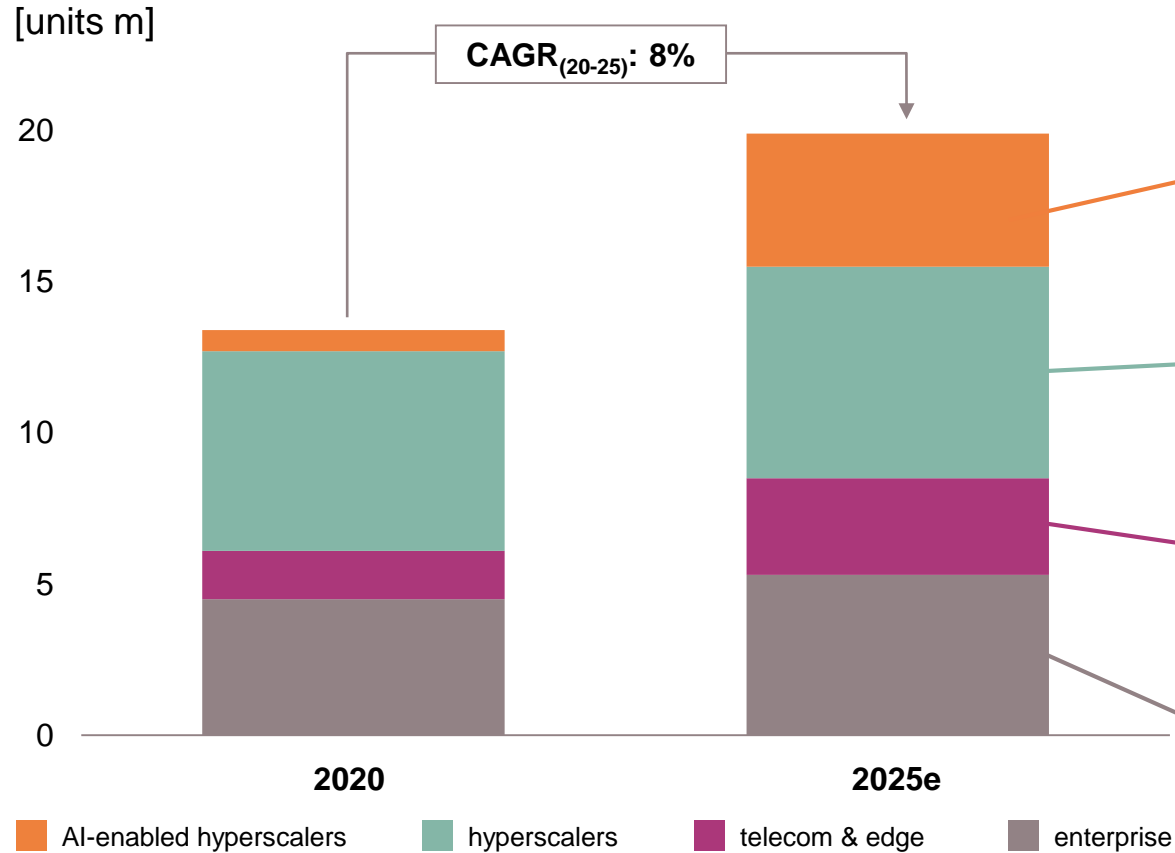
2020 total market: \$24.3bn



¹ Discrete Power MOSFET market includes automotive MOSFETs, protected MOSFETs, SiC MOSFETs and GaN power transistors. | ² Power IC market includes automotive power ICs.
Based on or includes research from Omdia: *Power Semiconductor Market Share Database 2020*. September 2021

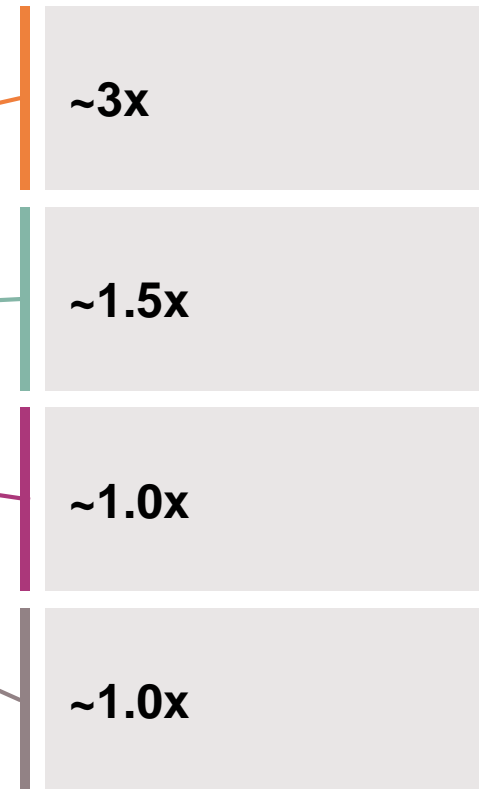
Data center – AI hyperscaler and telecom/edge computing are driving the growth

Server growth



Power requirement per server

Power¹:



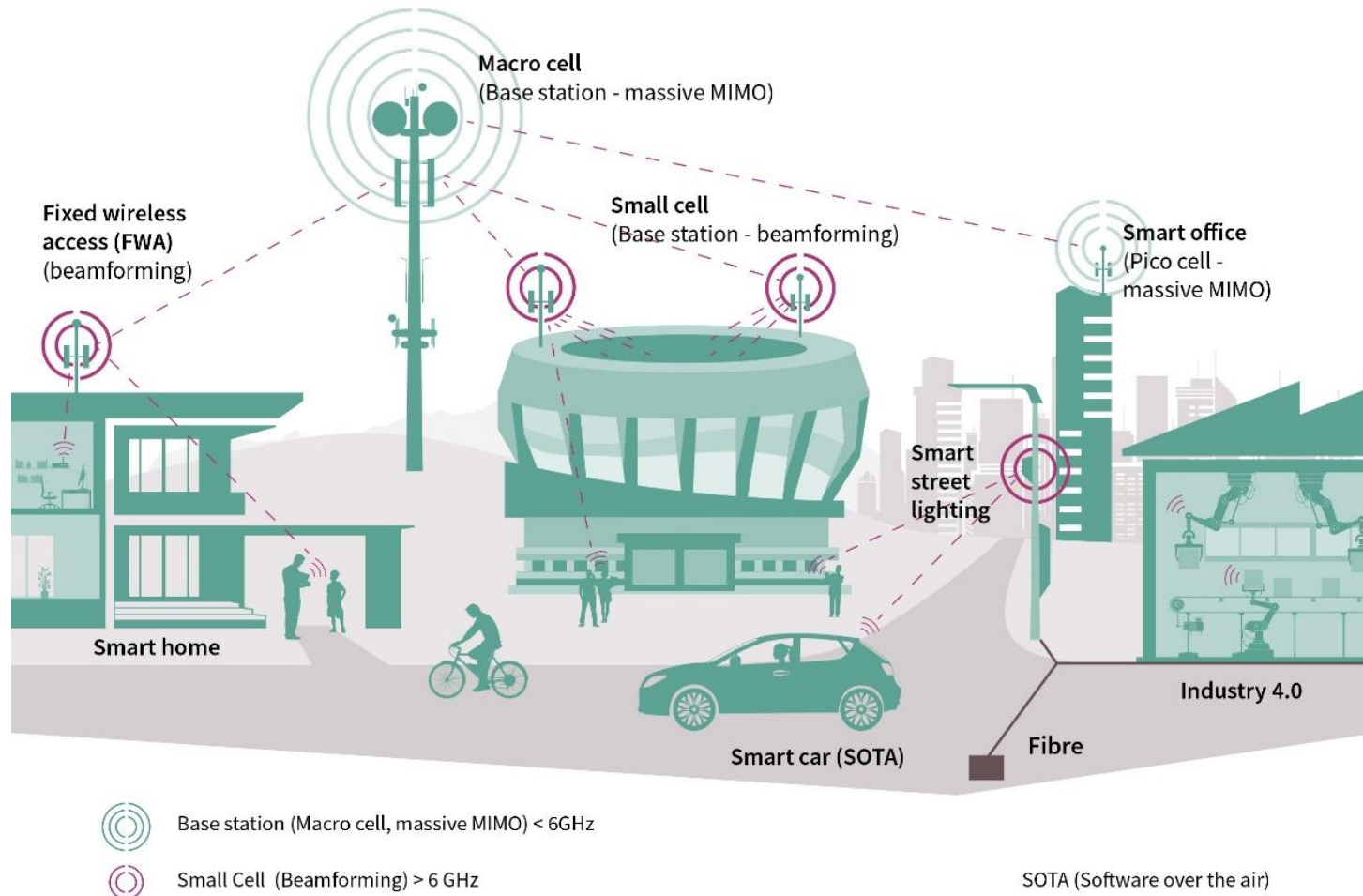
Exponential increase in **AI Training & Networking** (ASIC/SoC/FPGA/CPU/GPU) power level requires cutting-edge innovation in Device & Packaging technologies to solve power efficiency and density challenges

→ The bill of material is outpacing unit growth by a factor of ~1.3x.

¹ Normalized overall power requirement per server board for x-comparison
Based on or includes research from Omdia: *Data Center Server Equipment Market Tracker – 2Q21 Database*. September 2021

Transition from 3G/4G to 5G drives demand in power semis for antennas and power supplies

Smart and connected - the communication of tomorrow with 5G




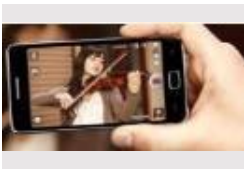

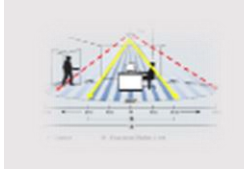
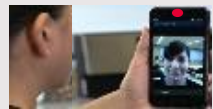

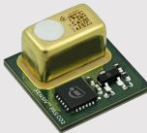

- > **driver #1:** massive growth of data and computing power
- > **driver #2:** higher number of base stations due to dense network
- > **driver #3:** ~4x higher power semi content per radio board: from ~\$25 for MIMO antenna to ~\$100 for massive MIMO antenna array
- > **driver #4:** fog computing data center as a completely new market



PSS – RF and Sensing



Main applications addressed by PSS sensors portfolio

MEMS microphone	3D radar (24/60 GHz)	3D ToF image sensor	Environmental
 <p>Best audio performance</p>  <p>Low power consumption</p>	 <p>Ultra-low power consumption</p>  <p>Presence detection/ Vital Sensing</p>	 <p>Best price / performance</p>  <p>Face ID (biometrics), VR/AR</p>	 <p>High precision and Small form factor</p>  <p>Measure CO₂</p>

Main applications

- › Smartphone
- › True wireless stereo headsets
- › Smart speaker
- › Laptop & Tablet

- › Automotive
- › Smart home
- › TV
- › Security camera
- › Smart building

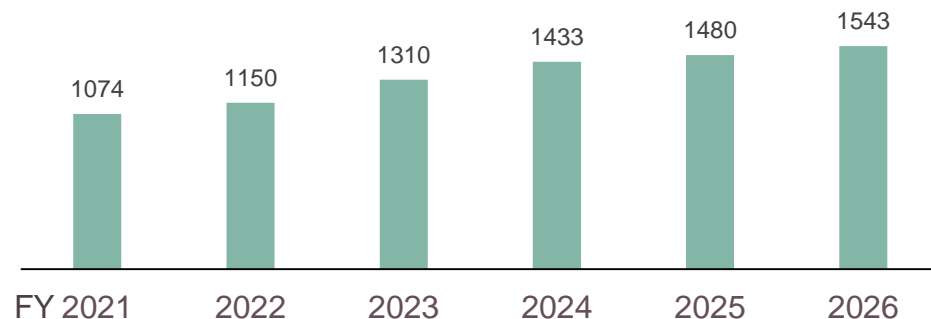
- › Smartphone: world-facing and user-facing
- › Robotics
- › Automotive in-cabin sensing
- › Payment terminals

- › Heating, ventilation, air conditioning (HVAC)
- › Air purifier
- › Smart thermostat
- › CO₂/virus risk reduction

Sensor markets targeted by PSS offer attractive growth potential

MEMS microphone market

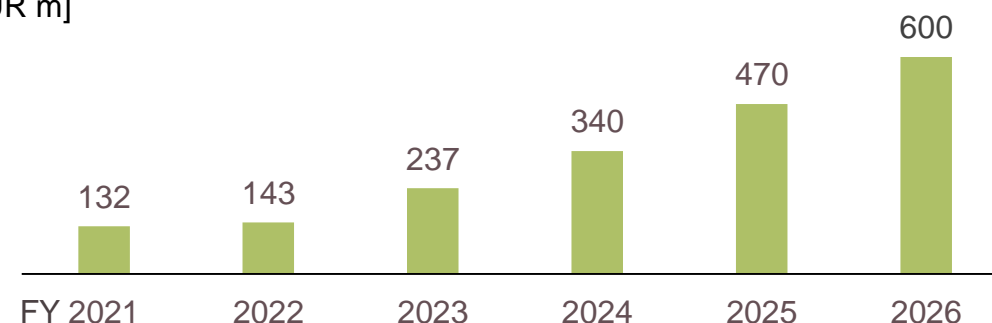
[EUR m]



Source: Infineon estimates

Radar IC market (24 GHz and 60 GHz only)

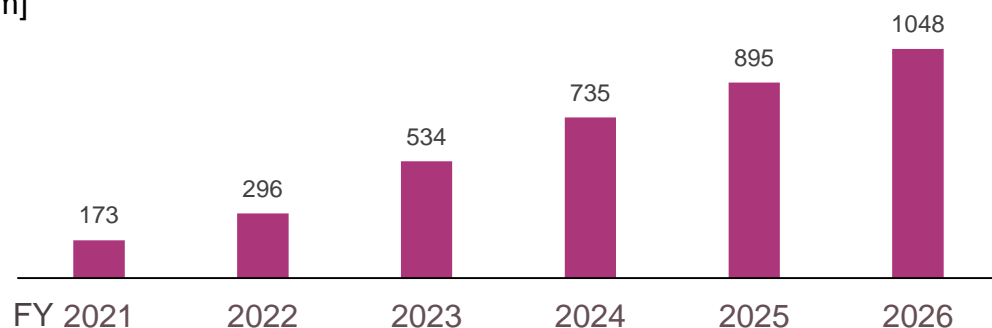
[EUR m]



Source: Infineon estimates

3D ToF image sensor market

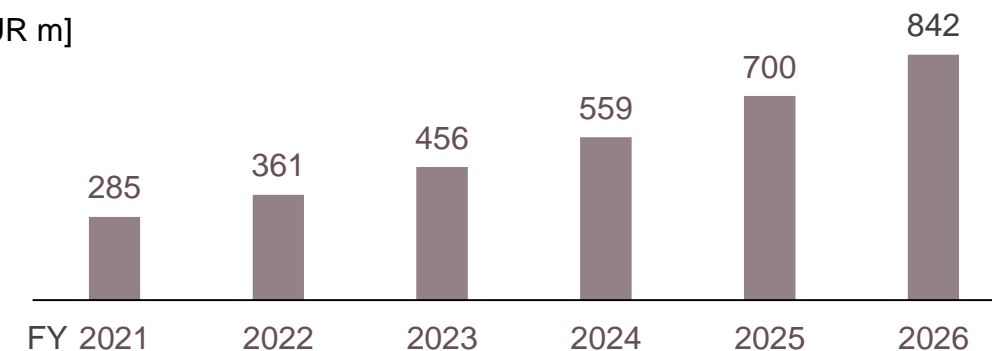
[EUR m]



Source: Infineon estimates

Environmental sensor market*

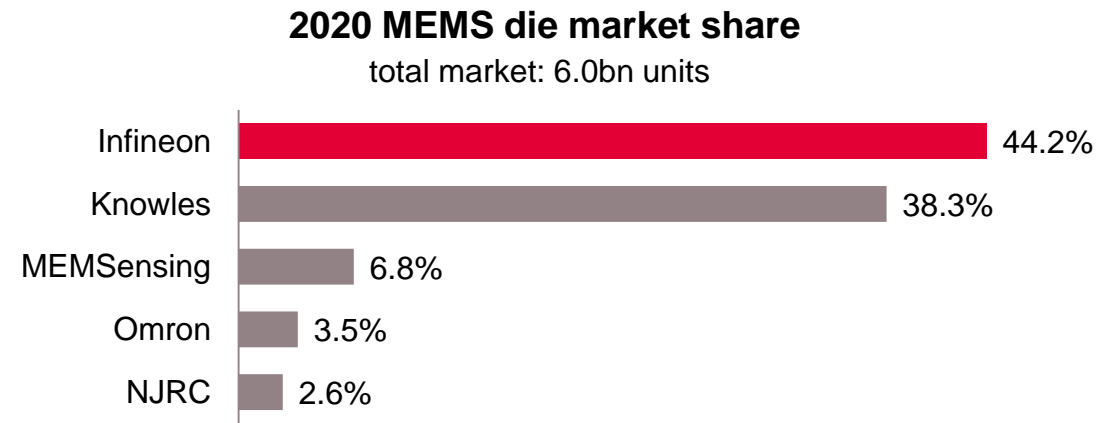
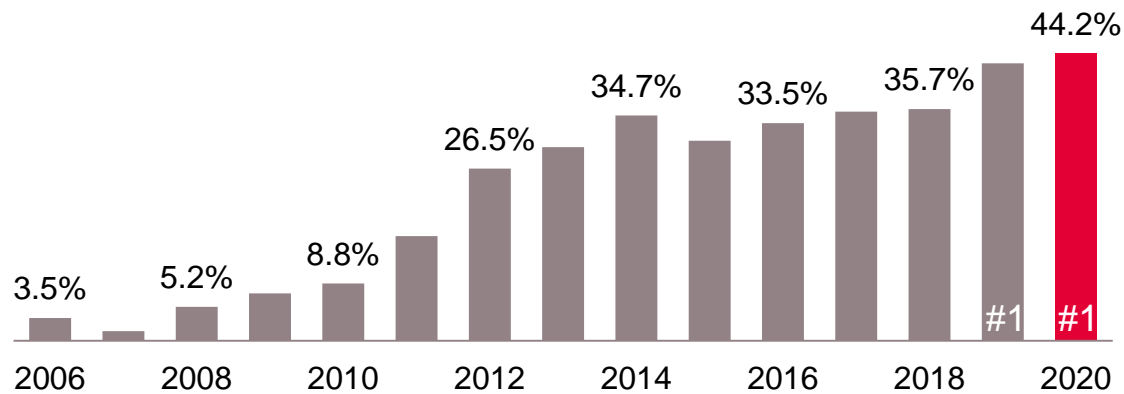
[EUR m]



* Infineon is addressing smart building, smart home, smart appliances, consumer IoT devices and automotive
Source: Infineon estimates

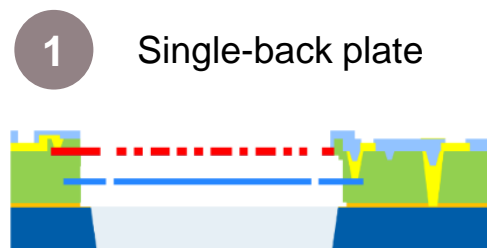
Unparalleled audio characteristics of our XENSIV™ MEMS microphones made Infineon #1 in 2019 with further m/s gain in 2020

Infineon's market share development in MEMS microphones (by units)

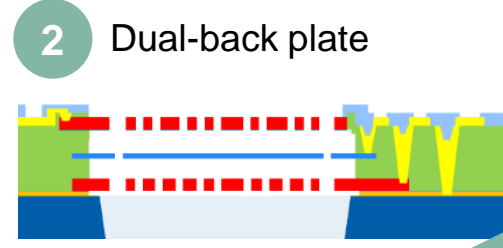


Based on or includes research from Omdia: *MEMS Microphones Dice Market Shares 2021*. July 2021

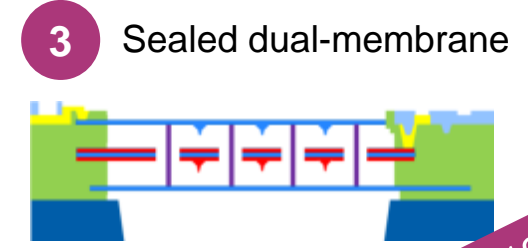
Technological progression of Infineon XENSIV™ MEMS microphones



SNR = 62 – 65 dB(A)



SNR = 65 – 69 dB(A)



SNR = 68 – 75 dB(A)

Radar offers several use cases for presence detection and health monitoring

Presence detection

- › **Room Occupancy Devices**
e.g. human localization and counting
- › **Occupancy based heating and ventilation**
e.g. reduction of CO₂ level to prevent spreading of diseases
- › **Device switch on/off**
e.g. reduction of energy consumption (e.g. lamp, TV, air conditioning...)
- › **Directional audio effects on individuum**
e.g. to improve audio quality (e.g. smart speaker, TV)
- › **Home surveillance**
e.g. detection of intruders

Health monitoring

- › **Sleep monitoring**
Sleep detection, sleep quality, apnea & snoring detection (radar combined with MEMS microphone)
- › **Vital sensing for home Fitness**
Heart rate and breathing rate measurement (person standing still after exercise)

Segmentation with radar enables smart devices to recognize each person in the room



Infinion 3D ToF is a versatile technology for many consumer applications

Mobile Phones – User Facing

Face ID



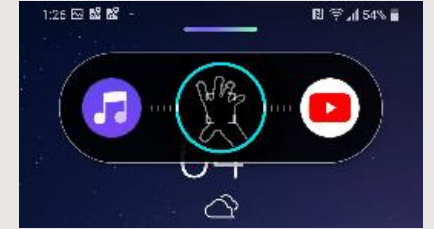
Hand ID



Payment



3D Gestures



Mobile Phones – World Facing

Bokeh



Virtual Retail



AR Gaming



3D Scanning



Consumer Robotics

Robot



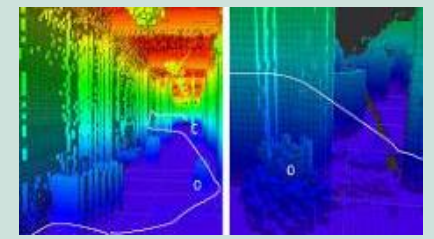
Last Mile



Collision avoidance



Navigation



Augmented- & Virtual Reality

AR



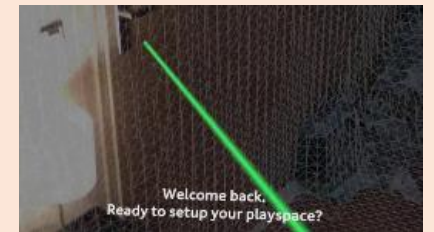
Control



AR Gaming



Mapping



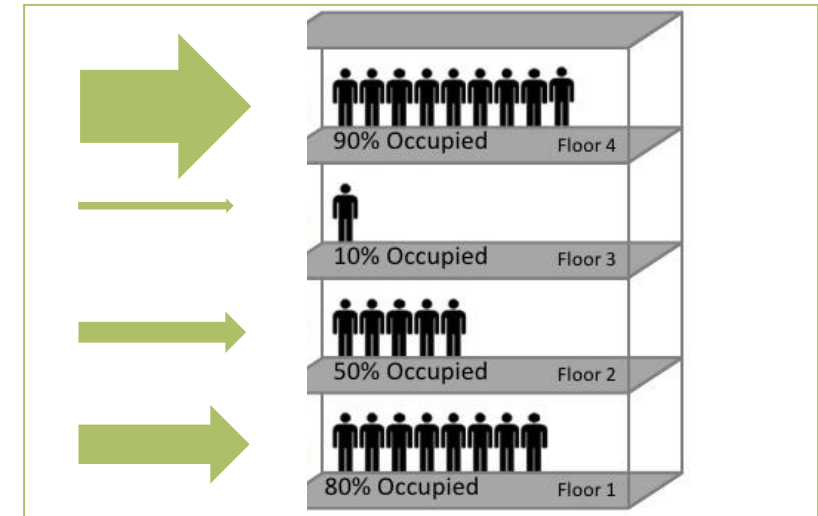
Infineon XENSIV™ PAS CO₂ sensor enables highly-precise CO₂ measuring in an extremely small size

Photoacoustic spectroscopy (PAS) technology based on Infineon's high (SNR) signal-to-noise ratio MEMS microphone

- › Infineon XENSIV™ PAS CO₂ sensor enables highly-precise, cost-effective and space saving CO₂ measuring
- › The technology offers an exceptionally small form factor (14 mm x 13.8 mm x 7.5 mm) that is 4x smaller and 3x lighter (2 grams) than the typical NDIR (non-dispersive infrared) sensor, allowing for more than 75% space savings in customer systems
- › The SMD package ensures compatibility with high-volume manufacturing standards, enabling cost-effective, fast assembly and system integration
- › Advanced compensation and configuration algorithms enable a plug-&-play sensor performance and fast design-to-market

XENSIV™ PAS CO₂ leads to demand-oriented and energy efficient control of air conditioning systems

XENSIV™ PAS CO₂ sensor measures the CO₂ level



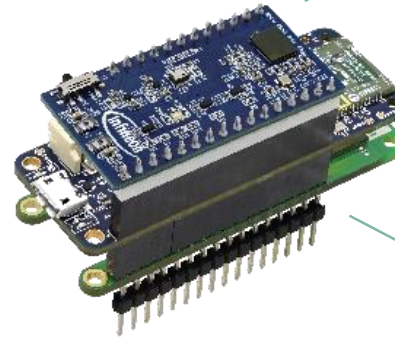
Infiniteon system solution addresses IoT market via combining XENSIV™ sensors, PSoC™ 6 MCU and connectivity

Key facts

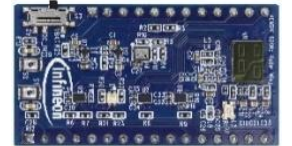
- › Infineon offers system solutions comprising of sensor, MCU, connectivity and software libraries (apps, SDKs)
- › BLE functionality monolithically integrated on MCU
- › IoT target applications for radar: entrance control or presence detection for smart home and smart building
- › Radar solutions are anonymous and therefore respecting privacy
- › First orders for presence detection received from several Asian customers
- › Radar solution can perfectly be combined with Infineon's XENSIV™ PAS CO₂ sensor for air quality monitoring



Example offering: Combination of sensors, microcontrollers and connectivity in development kit



XENSIV™ Radar + Pressure Wing Board



XENSIV™ PAS CO₂ Wing Board



Main board with MCU + Wi-Fi + Bluetooth combo



Advantages of radar over passive infrared

- › super compact design; smaller system sizes
- › determination of person's direction, speed, distance
- › programmable; can flexibly be adapted to the target application
- › higher accuracy; more precise measurements of detected objects

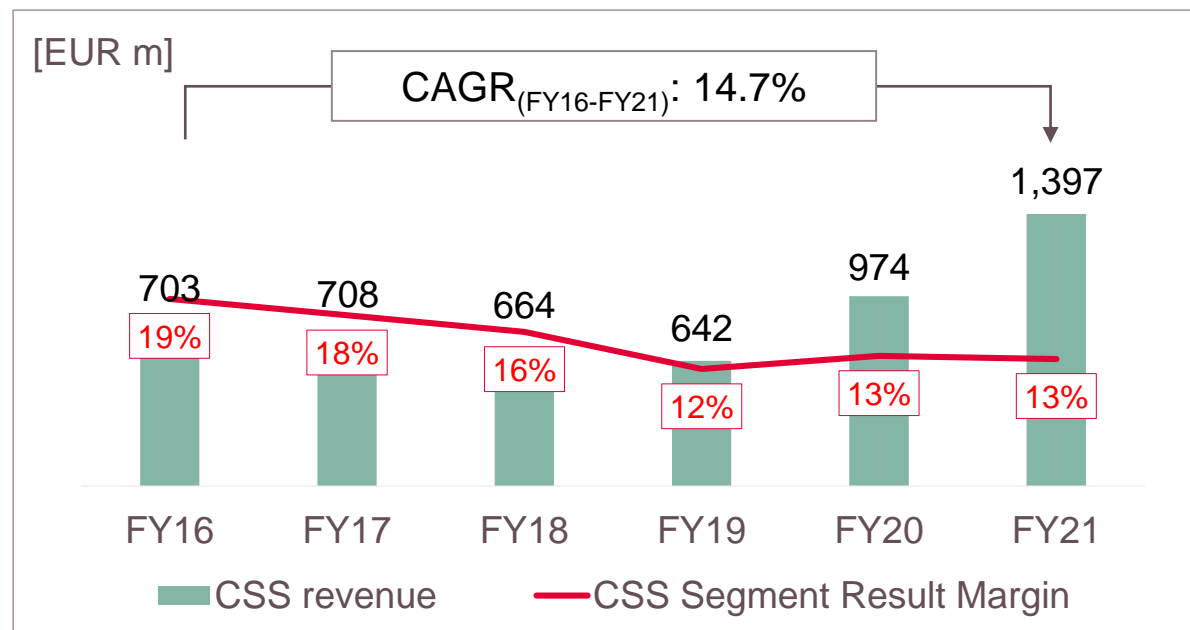


Connected Secure Systems

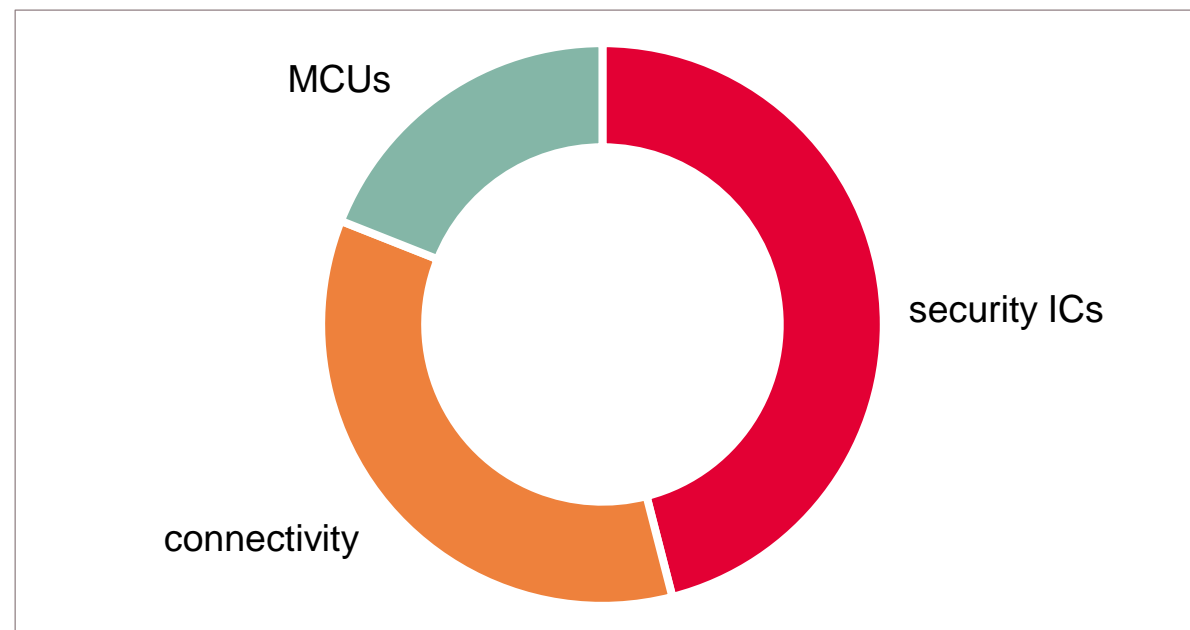


CSS at a glance

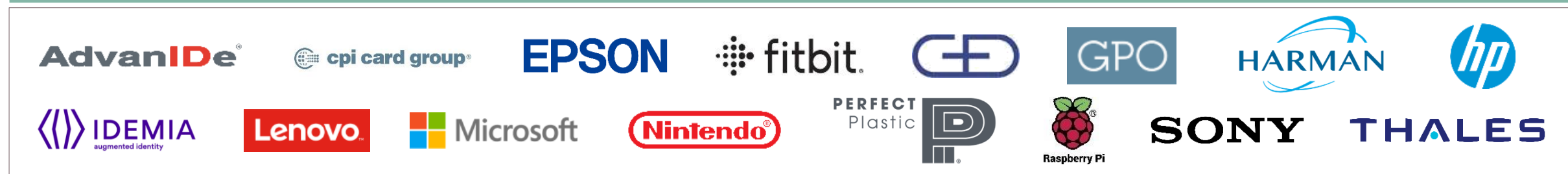
CSS revenue and Segment Result Margin










FY21 revenue split by product group



Key customers

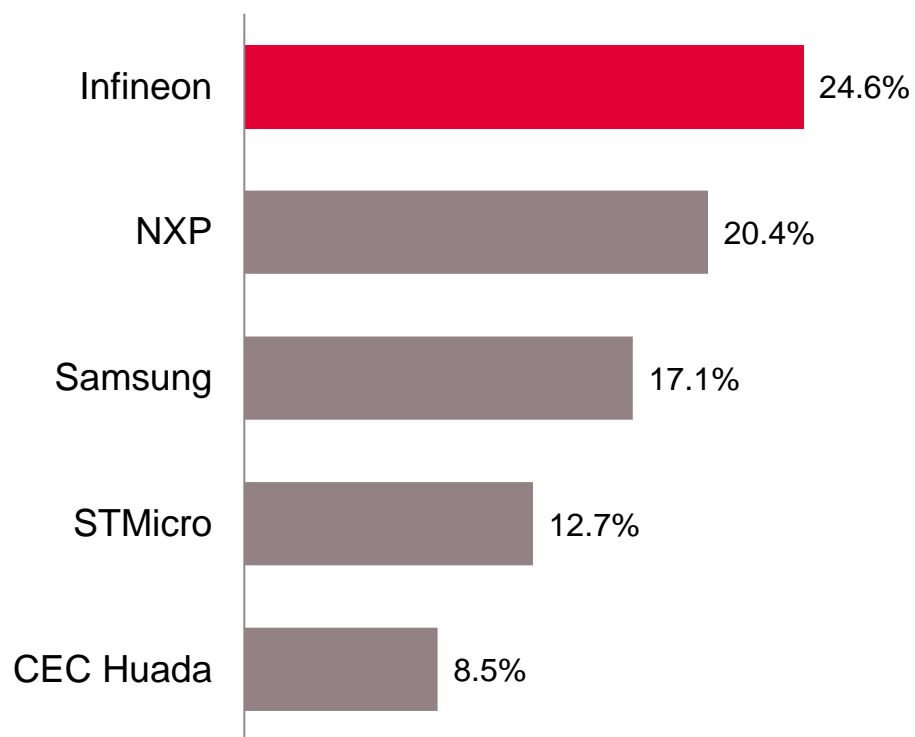


Positive outlook for most markets for CY22, while allocation has varying effects on the segments with the strongest impacts on payment

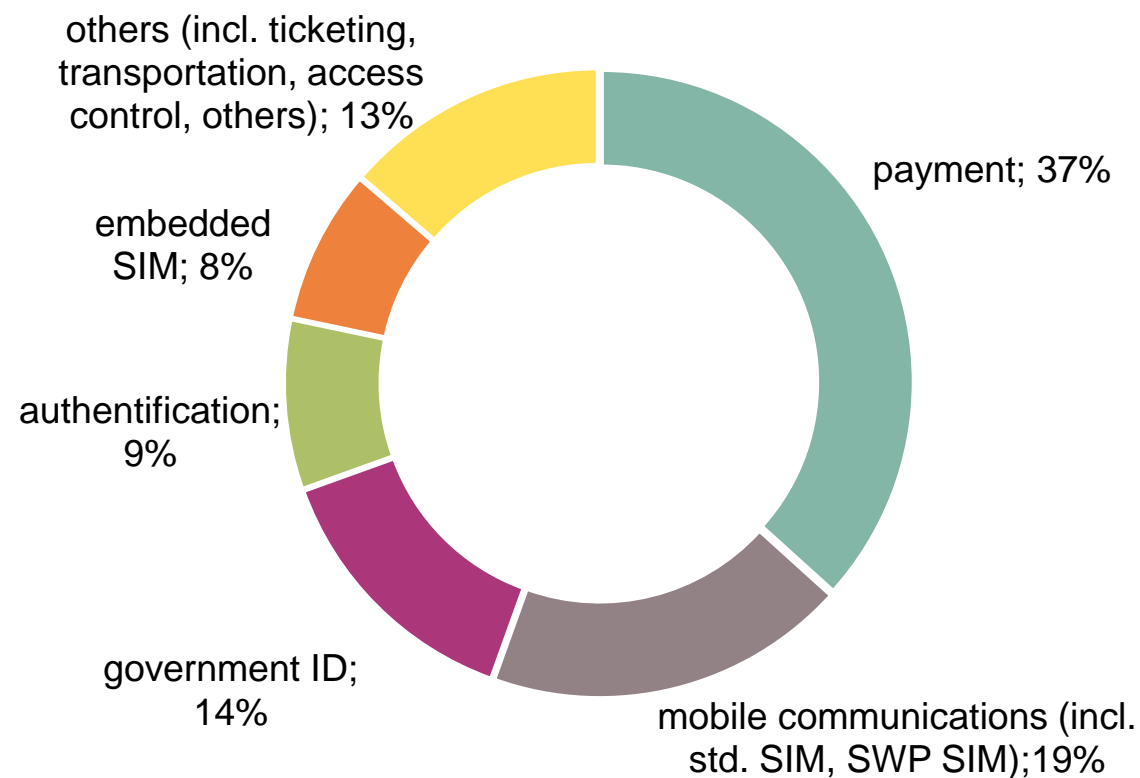
Applications (% of FY21 segment revenue)	Market Outlook for CY22 (not considering supply constraints)
<div>Industrial and Consumer IoT ~67%</div> <div>Industrial IoT</div> <div>Smart Home</div> <div>Wearables</div> <div>Gaming</div> <div>Automotive</div>	<div> > Growth momentum in industrial segments to continue into CY22</div>
	<div> > Further growth momentum across smart home devices and appliances expected due to sustained customer demand</div>
	<div> > Growth in wearables market is assumed to stretch in CY22 driven mainly by smart watches</div>
	<div> > The market is assumed to decline slightly from a high level after 2021 as demand stabilizes</div>
	<div> > Growth is expected to sustain in CY22 driven by increasing penetration rate of eSIM and in-car connectivity, as well as existing backlogs</div>
<div>Payment, ID, Ticketing ~33%</div> <div>Payment</div> <div>Identification</div>	<div> > Supply constraints prevailing, despite strong demand for contactless payment solutions</div>
	<div> > Positive trend expected driven by recovery in passports issuance as well as project roll-out for other eDocuments</div>

Infineon remains top player in security ICs

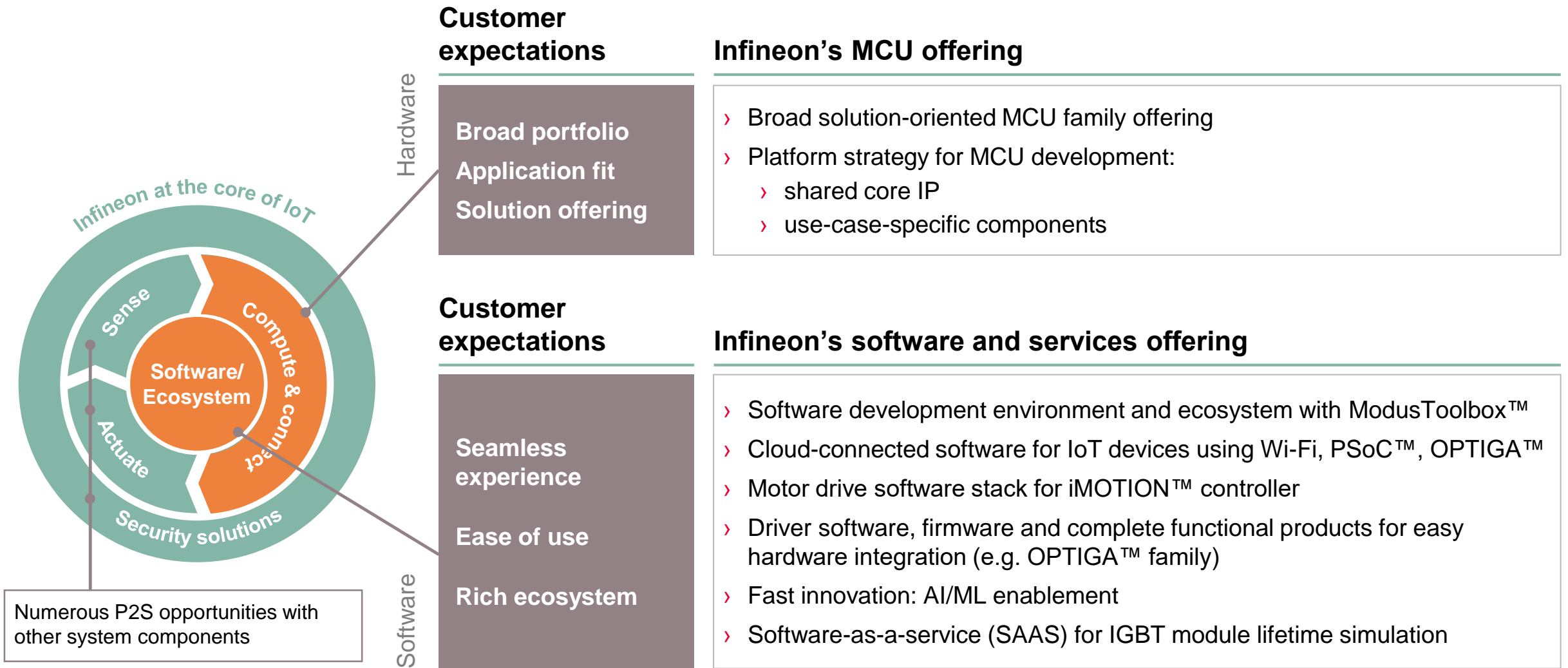
Security ICs (excl. NFC controllers; excl. NFC eSE)
2020 total market: \$2.8bn



Security ICs (excl. NFC controllers; excl. NFC eSE)
2020 by application



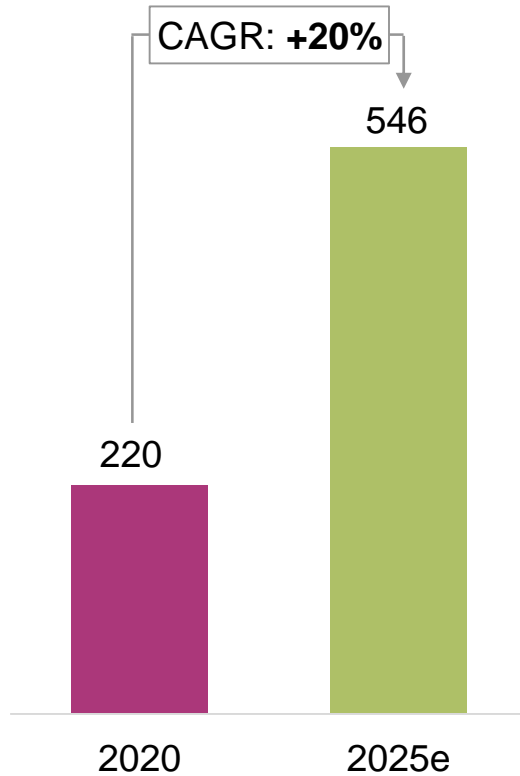
MCU and software are key for the success in IoT as they define the functionality and time-to-market of the device











With a broad set of key enabling technologies, Infineon is well positioned to capture growth opportunities

Market: Home Automation Devices¹

[units m]



Leading competencies to provide full system solutions

-  **Application understanding**
-  **Ease-of-use**
-  **Software**
-  **Sense**
-  **Compute**
-  **Actuate**
-  **Security**
-  **Connectivity**



smart door lock



wireless smart camera

Customer ex. for wireless smart cameras and smart door locks



ASSA ABLOY



Google



Kaadas



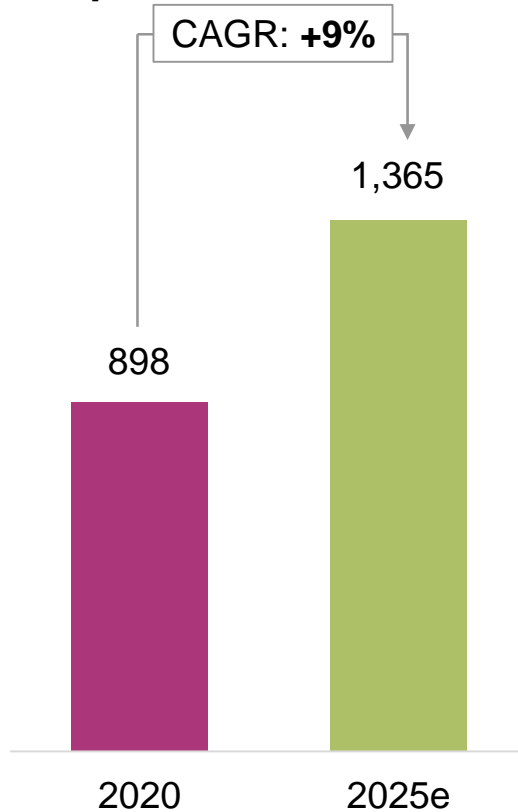
¹ ABI Research: *Wireless Connectivity Technology Segmentation and Addressable Markets*. July 2021; excluding Chromebooks, desktop PCs, feature phones, media tablets, netbooks, smartphones, white box tablets.

Infiniteon acts as one-stop-shop with excellent RF, sensor, connectivity, power, memory and security solutions











Market: Smartwatches, Trackers & Hearables¹

[units m]



Acting as one-stop-shop with comprehensive solutions

-  **Application understanding**
-  **Ease-of-use**
-  **Software**
-  **Sense**
-  **Compute**
-  **Actuate**
-  **Security**
-  **Connectivity**



smartwatch



fitness tracker

Customer examples for smart watches and fitness trackers

GARMIN



huami

POLAR

SAMSUNG

SUUNTO

vivo

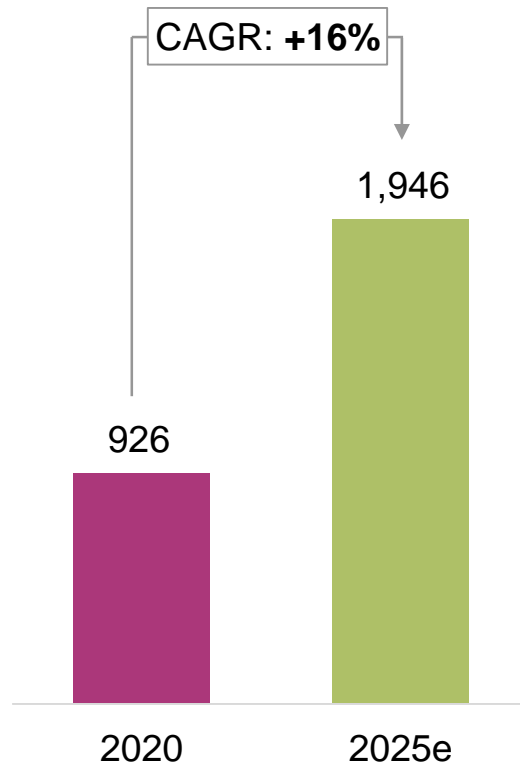
WYZE

¹ ABI Research: *Wireless Connectivity Technology Segmentation and Addressable Markets*. July 2021; excluding Chromebooks, desktop PCs, feature phones, media tablets, netbooks, smartphones, white box tablets.

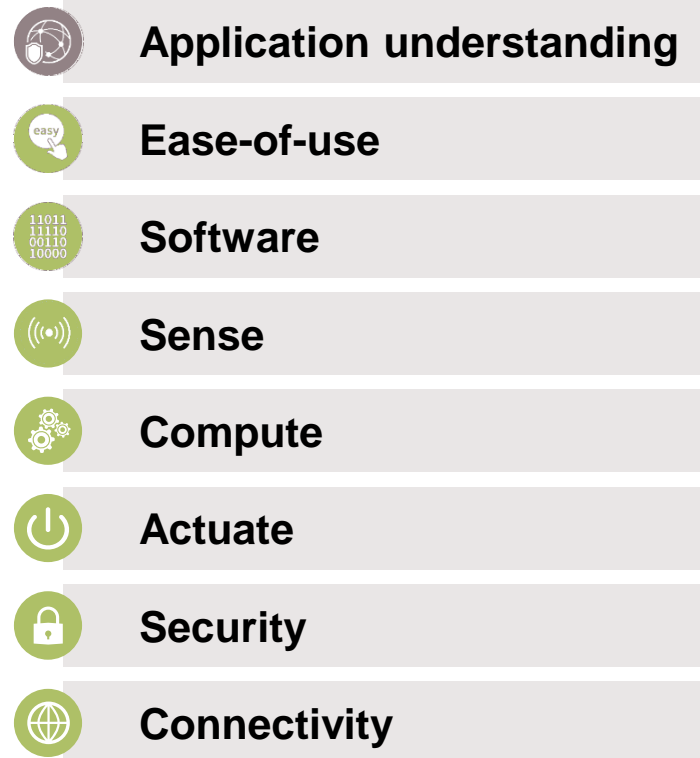
We are driving the smart home opportunity together with market-shaping customers

Market: Smart home^{1,2,3}

[units m]



Combining our portfolio to create new use cases with our customers



Frame TV



smart vacuum cleaner

Customer examples for smart home



¹ ABI Research: *Wireless Connectivity Technology Segmentation and Addressable Markets*. July 2021; excluding Chromebooks, desktop PCs, feature phones, media tablets, netbooks, smartphones, white box tablets.

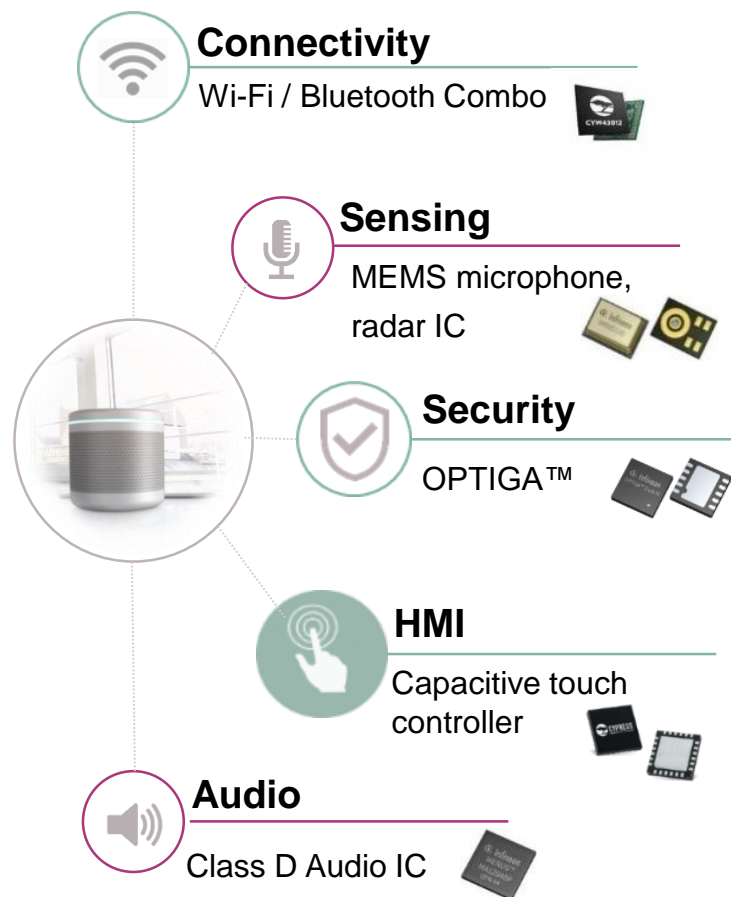
² ABI Research: *Smart Home Hardware Market*. June 2021. | ³ Incl. Smart Appliances, Smart Lighting, Flat Panel TVs, Smart Speakers & Displays, Smoke & Air Quality Sensors, Consumer Robotics, Thermostats and others.

Significant synergy potential of a combined company product portfolio

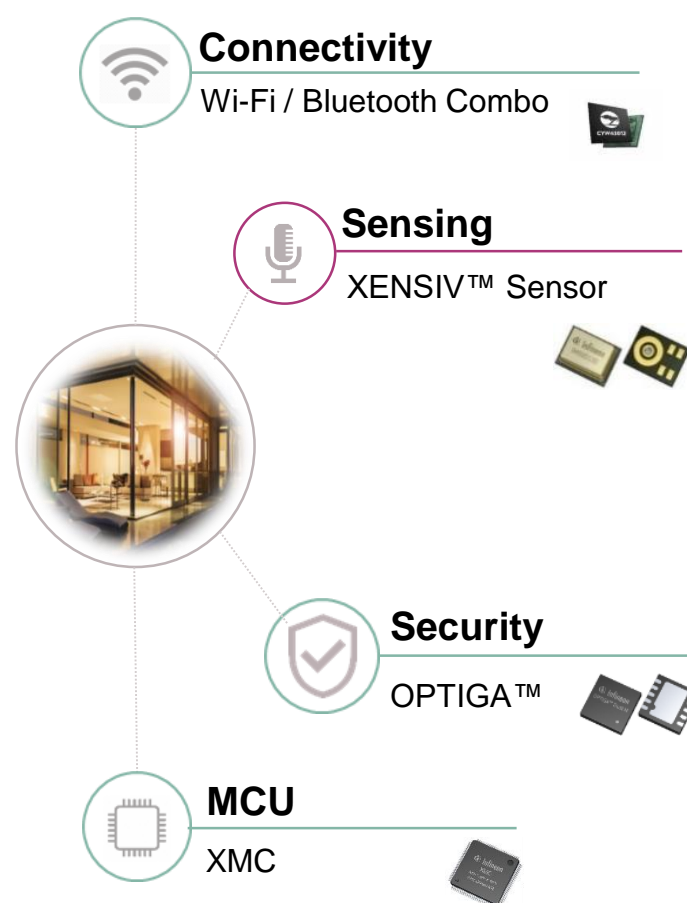
Synergies application examples

 CSS offering
 Other Infineon Divisions offering

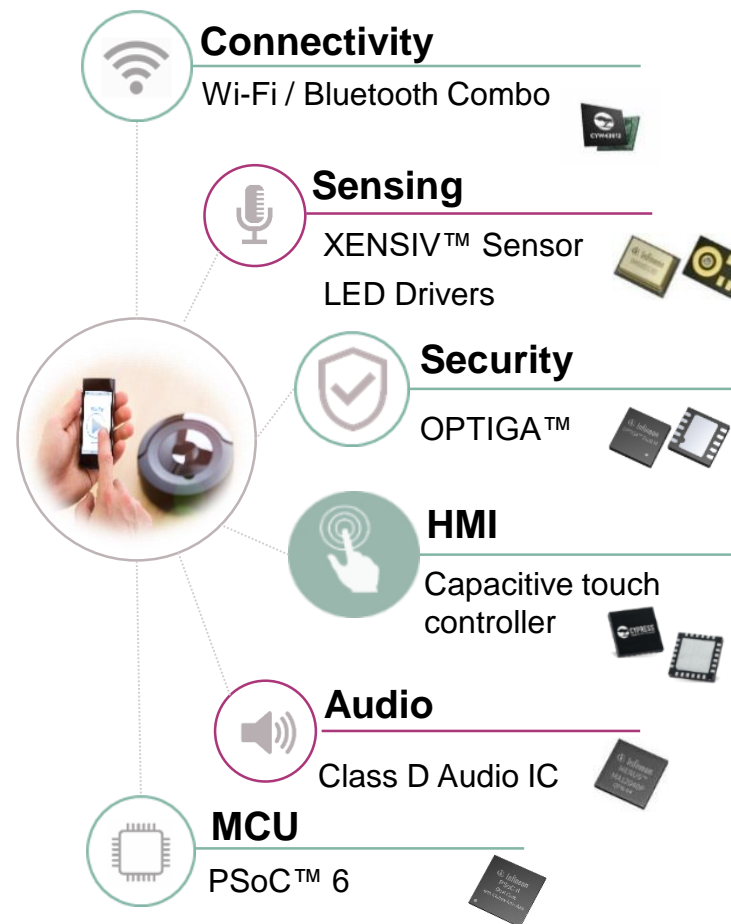
Smart speaker



Smart lighting



Service robots

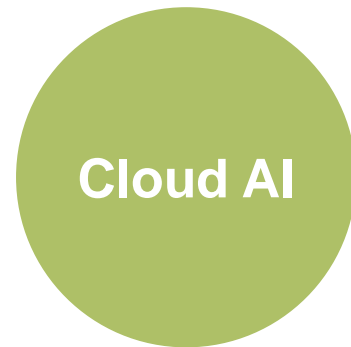


Edge AI is a fast developing market enabled by and calling for many of our core competencies

Edge AI to offer additional growth opportunities as inference workloads move to device level

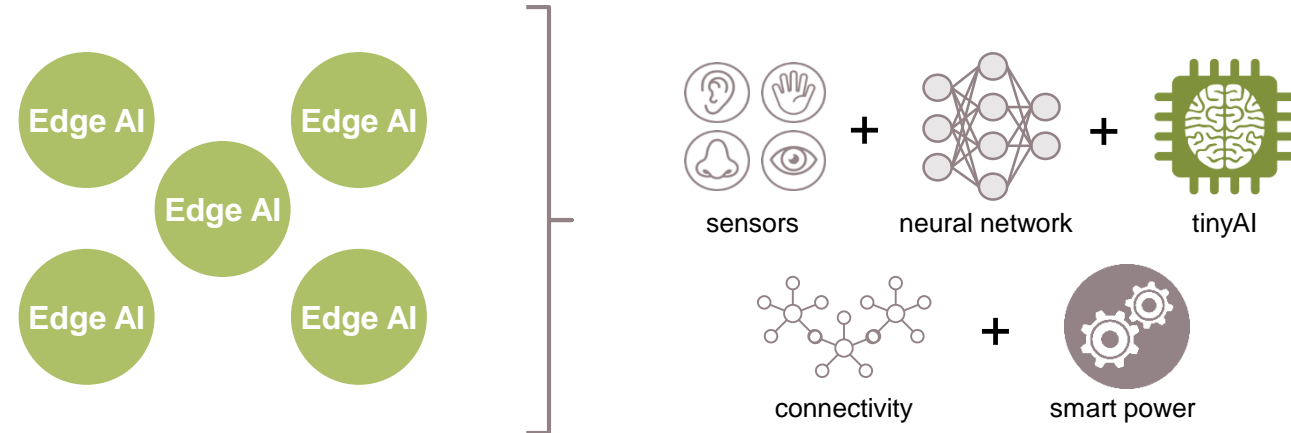
Cloud AI

- › Public and private clouds offer scalability and flexibility
- › Growing performance demand with higher power consumption (ASIC/SoC/FPGA/CPU/GPU)



Edge AI

- › Smart subsystems offer low latency, improved privacy, higher power efficiency
- › Growing solution demand for e.g. image and object recognition, autonomous material handling, predictive maintenance, and human-machine interface



Infineon:

**Power supply (AC-DC)
Power conversion (DC-DC)**

Infineon:

**Smart sensors with AI capabilities
Embedded control including connectivity and edge AI accelerators
Smart power, toolchain/ecosystem, deployment services**

For the Industrial IoT, Edge AI enables predictive maintenance and other use cases – playing right into our core competences

Predictive maintenance is a significant lever for productivity



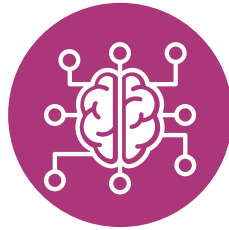
Maintenance prediction for key assets
(avoidance of fixed preventive maintenance cycles)

Advantages






- › Reduced downtime through optimized maintenance
- › Lower maintenance costs
- › Increase transparency on device usage

Edge AI enhances Industrial IoT to enable predictive maintenance, increasing production efficiency and robustness

Edge AI-enabled control and field-level devices



Products and services from Infineon enable safe, secure, power-efficient, dependable implementation

-  **Smart sensors**
Detect and pre-process signals through AI capabilities to recognize potential abnormal operation of equipment
-  **Edge AI processing and control**
Edge AI enabled MCUs to identify at-risk equipment, repair urgency and control adaptation
-  **Smart Actuators**
Receive and implement instructions to reduce potential impacts in production
-  **Security**
Ensure secure communication and protection of critical information
-  **Connectivity**
Enable dependable communication across devices, factory levels, cloud and secure device management

7RE3	37.278	1.14	+0.72▲	634.270	3.984%	369,000
S421	94.107	0.73	-0.51▼	538.014	2.416%	743,000
YT64	21.744	5.63	+3.18▲	692.380	0.657%	405,000
I897	13.361	1.82	-1.23▼	237.981	0.103%	882,000



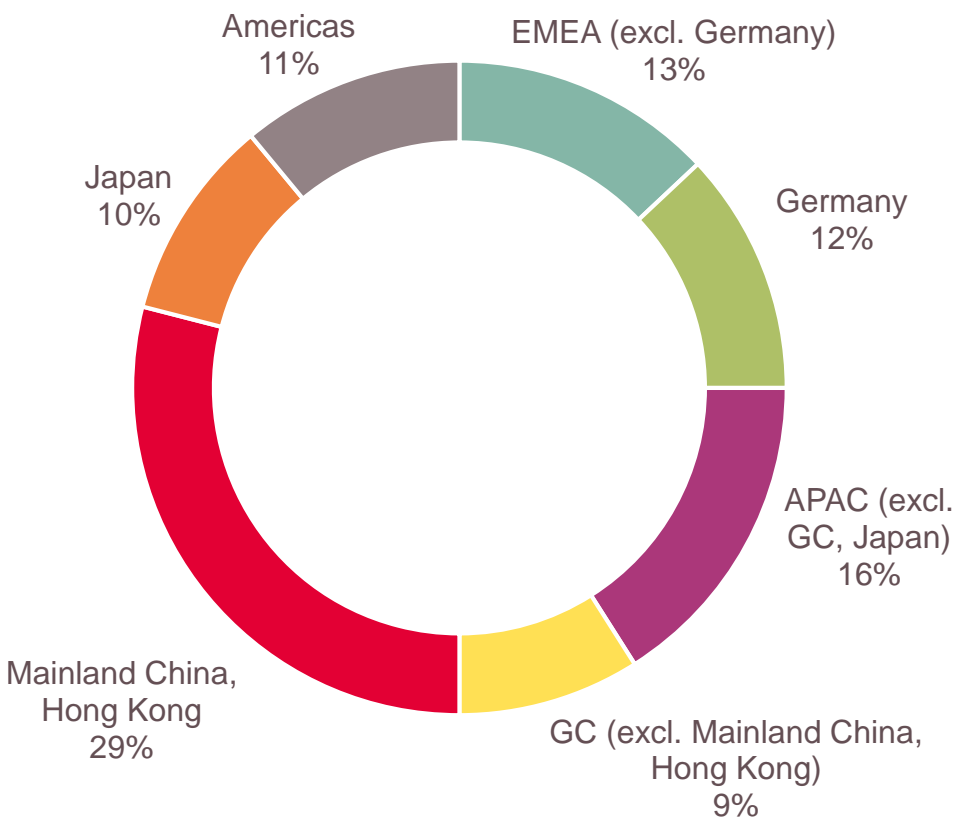
Selected financial figures



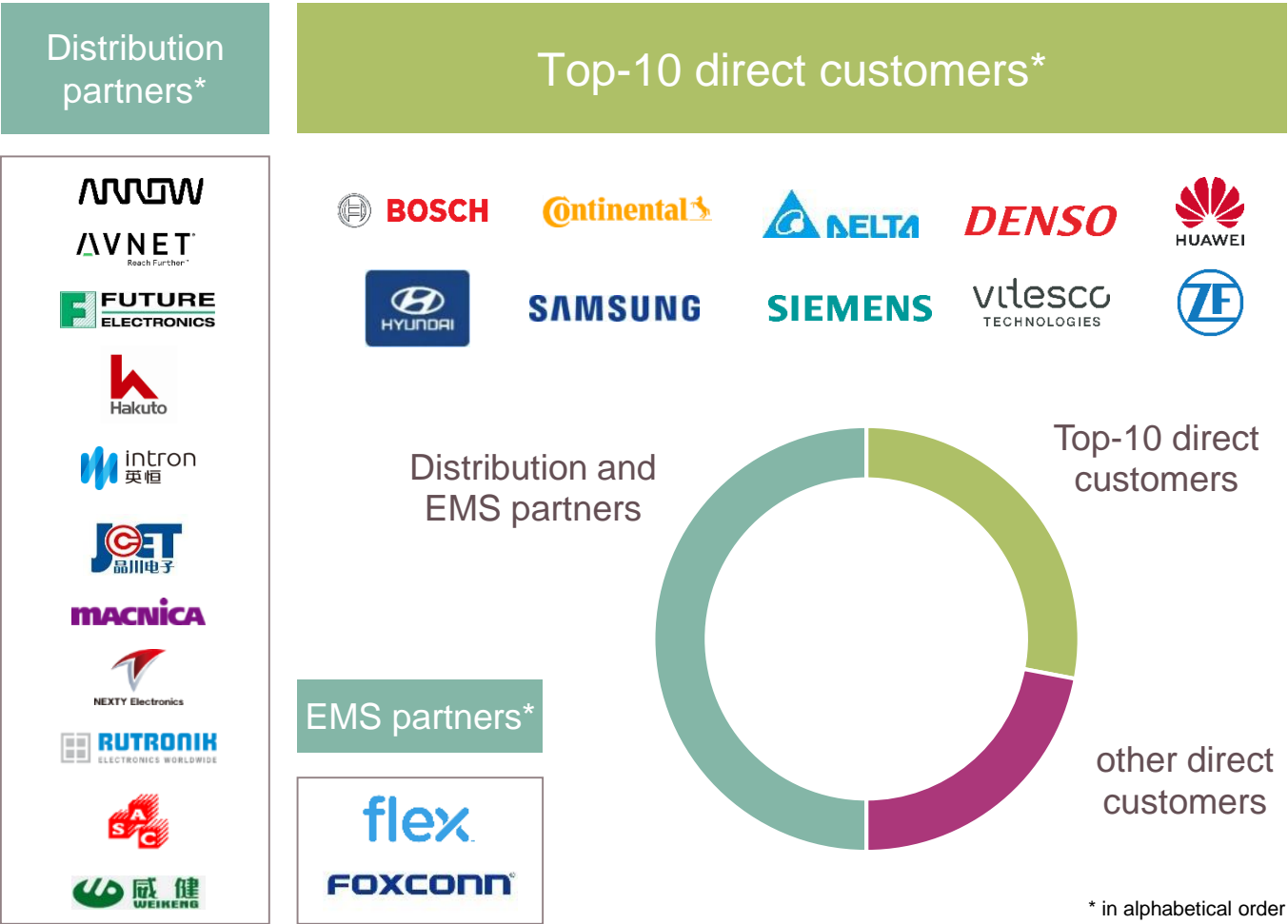
Strong presence in all regions; well-balanced customer portfolio;
no customer represents more than 10% of total sales



FY21 revenue by region



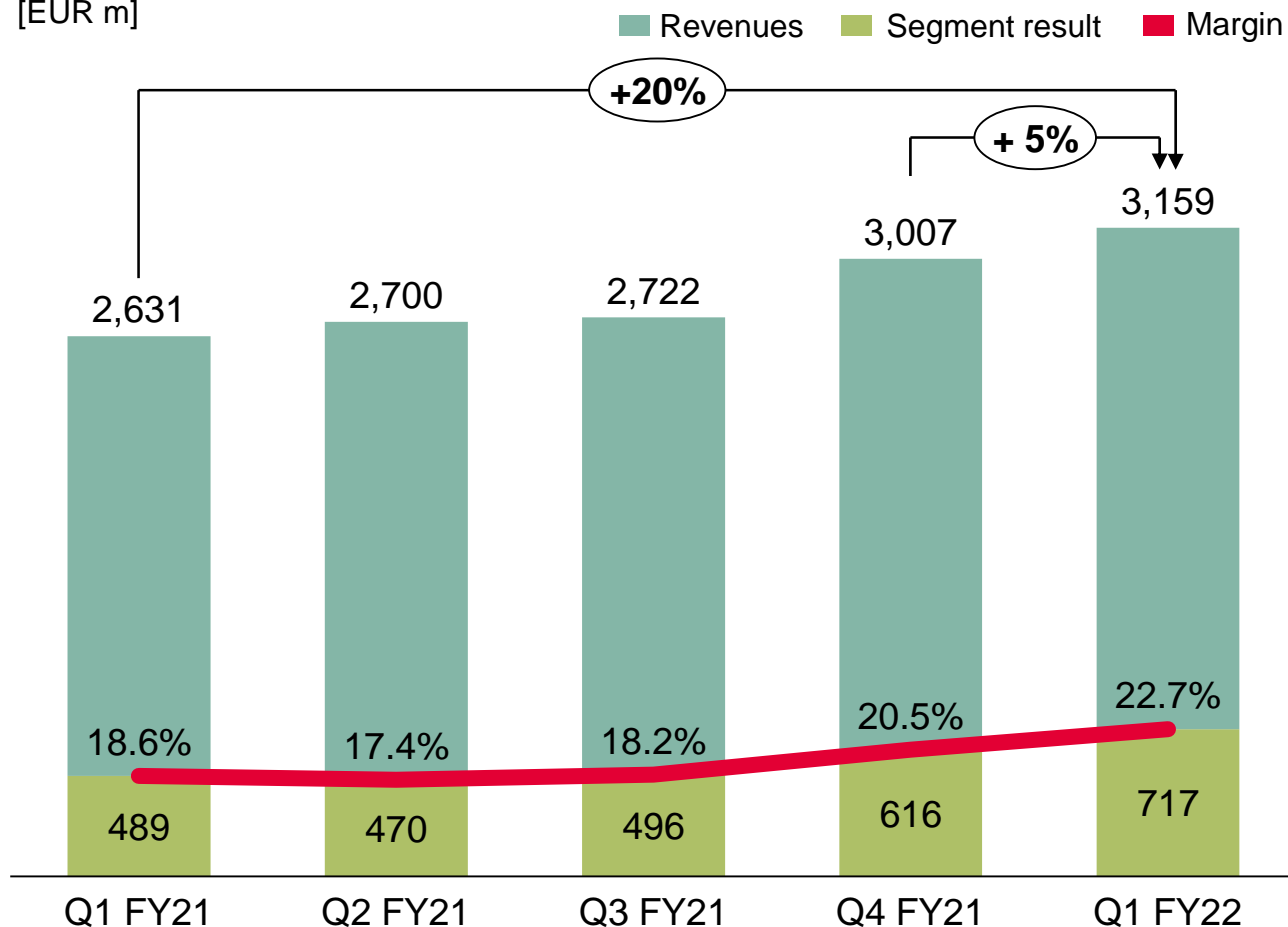
Revenue by sales channel



Group financial performance

Revenues and segment result

[EUR m]



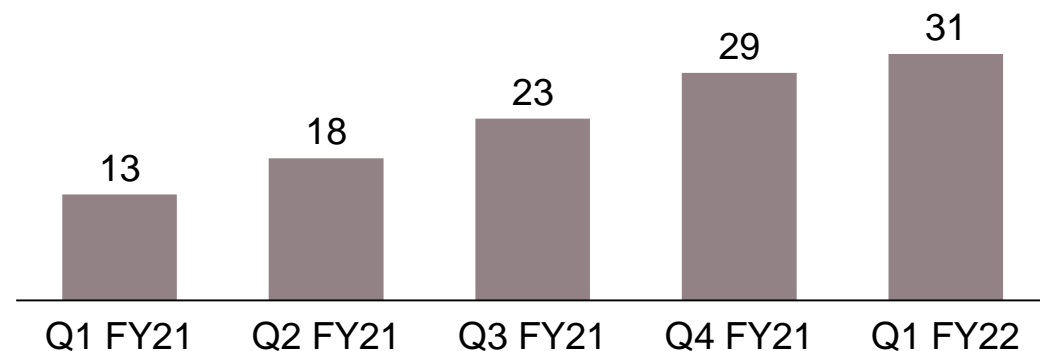
USD exchange rate

Average exchange rate

	Q1 FY21	Q4 FY21	Q1 FY22
Ø USD/EUR	1.19	1.18	1.14

Order backlog¹

[EUR bn]

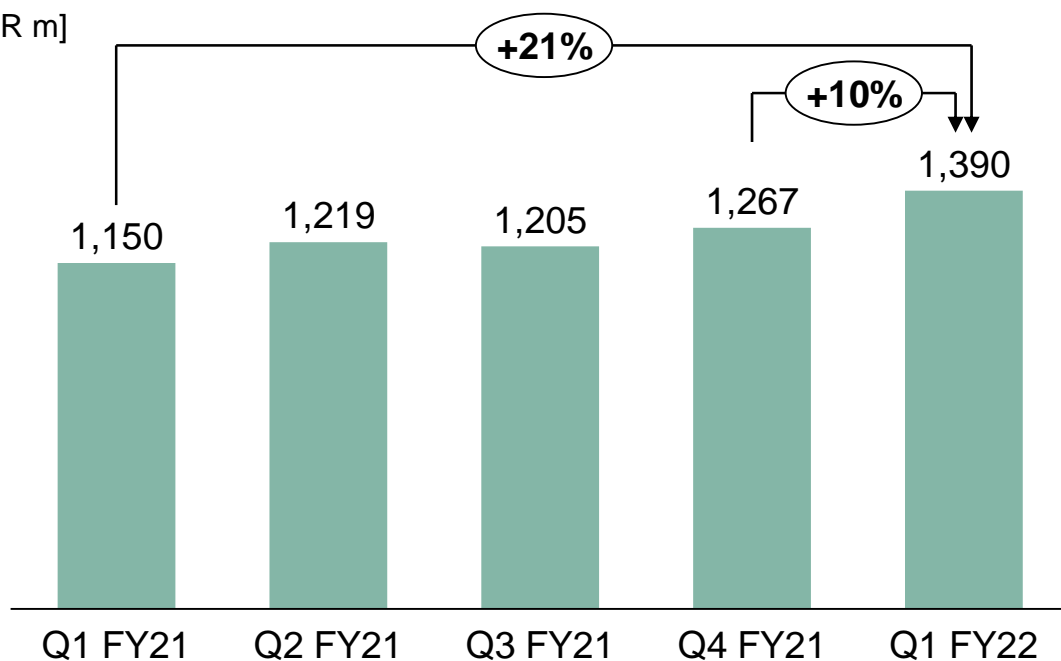


¹ For definition please see page "Notes"

Automotive (ATV)

Revenues

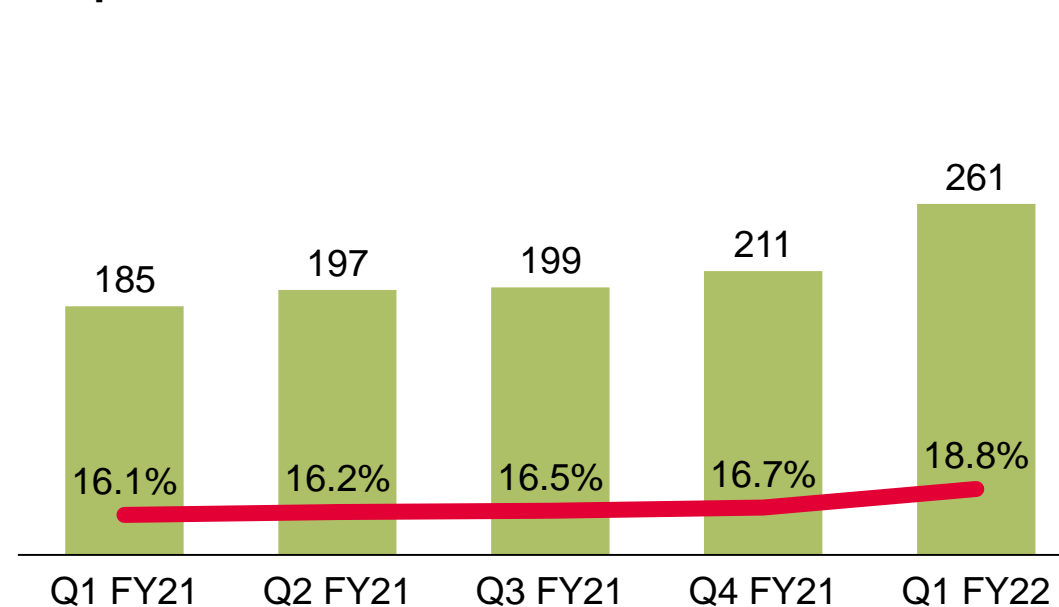
[EUR m]



Segment Result

Margin

[EUR m]

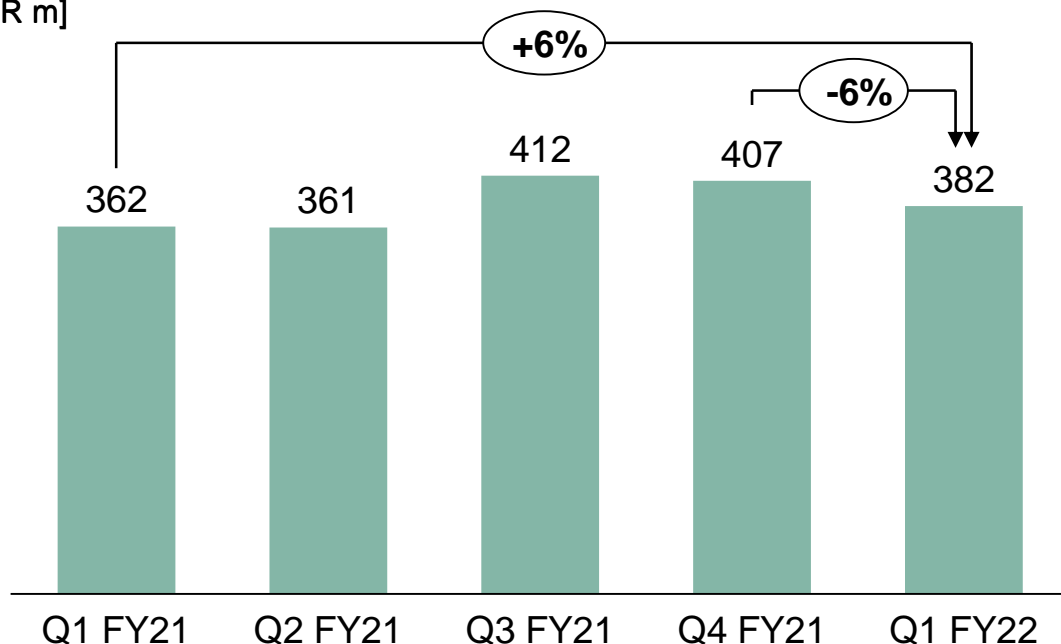


- › On-going strong demand across applications could be better served due to absence of supply disruptions
- › Shortages will gradually ease in CY22 but worldwide auto production remains vulnerable to external shocks
- › 2021 was pivotal for EV adoption – sales of battery electric and plug-in hybrid vehicles doubled within a year

Industrial Power Control (IPC)

Revenues

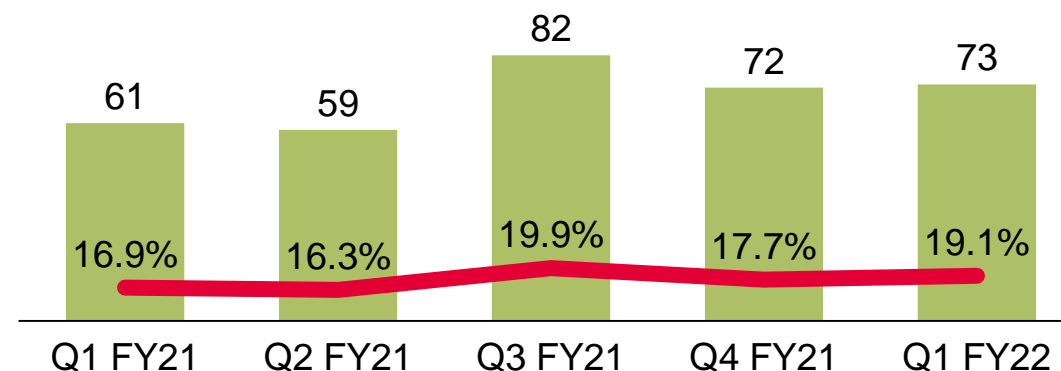
[EUR m]



Segment Result

Margin

[EUR m]

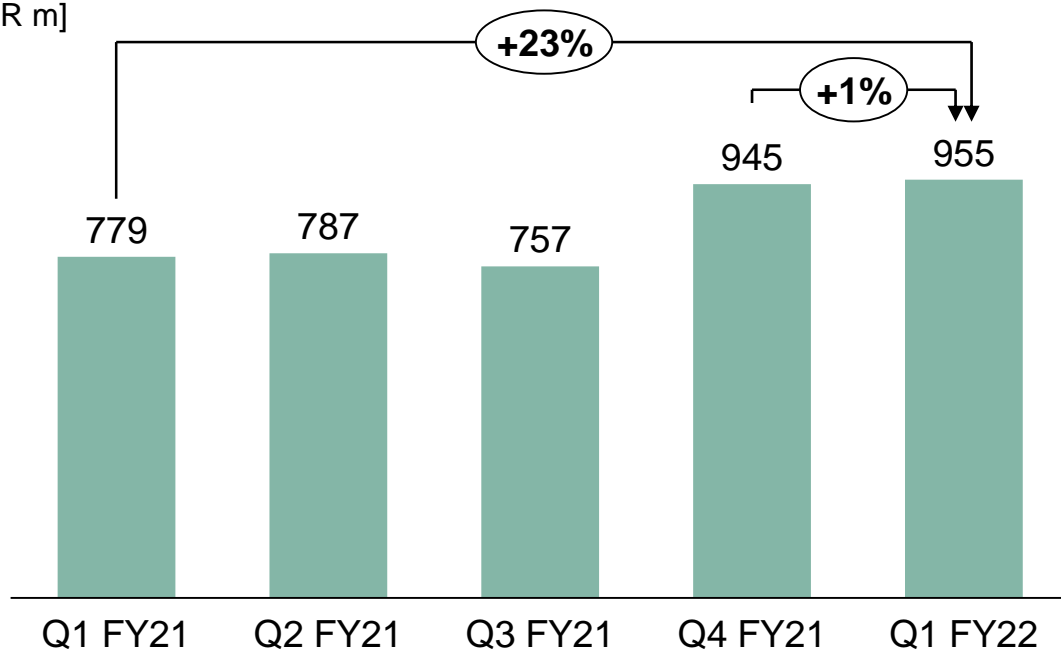


- › Typical pattern of seasonal decline pattern in most applications, notable exception: power infrastructure (energy storage, EV charging, etc.)
- › Impact of lower revenue was offset by the fall-away of costs related to supply disruptions
- › The current business perspective is positive: strong order intake, many product areas continue to be on allocation, channel inventories have downticked again

Power & Sensor Systems (PSS)

Revenues

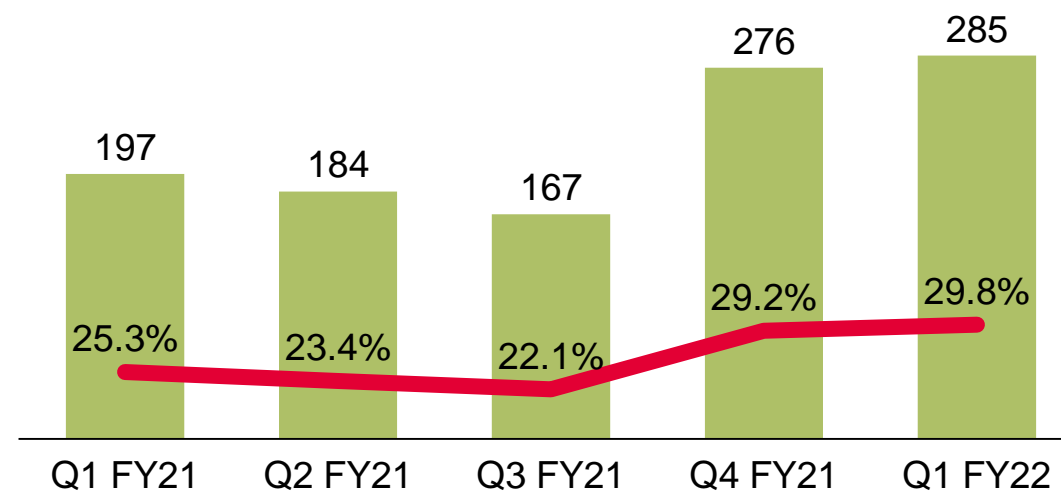
[EUR m]



Segment Result

Margin

[EUR m]

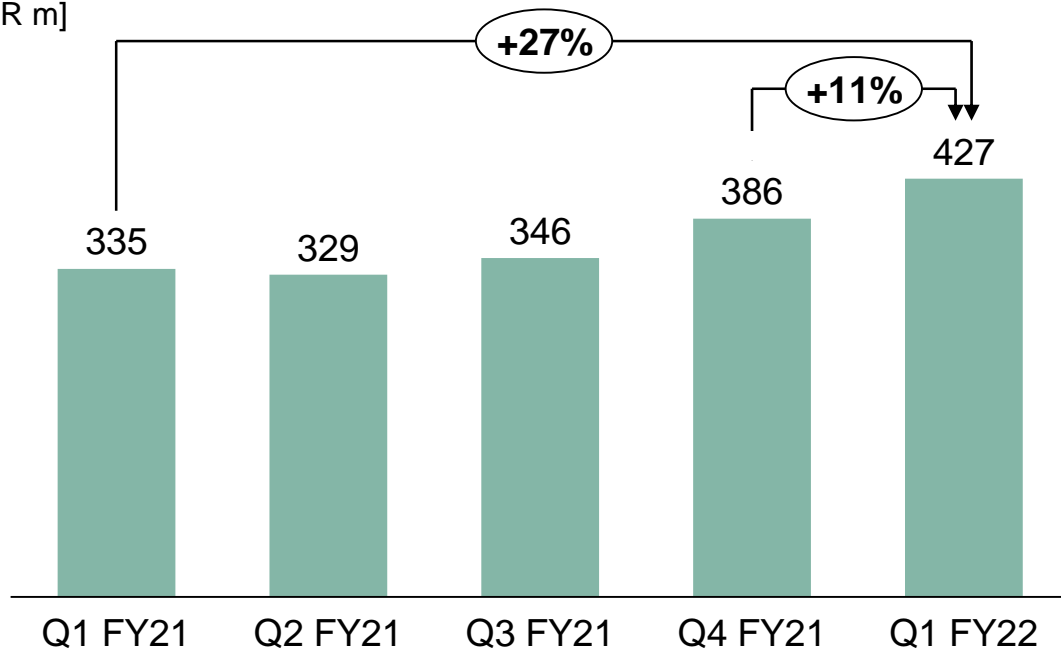


- › Strong demand for all power-related product areas, smartphone components experienced seasonal decline
- › Demand for the large majority of applications remains robust – channel inventories are lean
- › The overall healthy picture should last well into this year – data centers are a case in point, with increasing cloud & enterprise spending

Connected Secure Systems (CSS)

Revenues

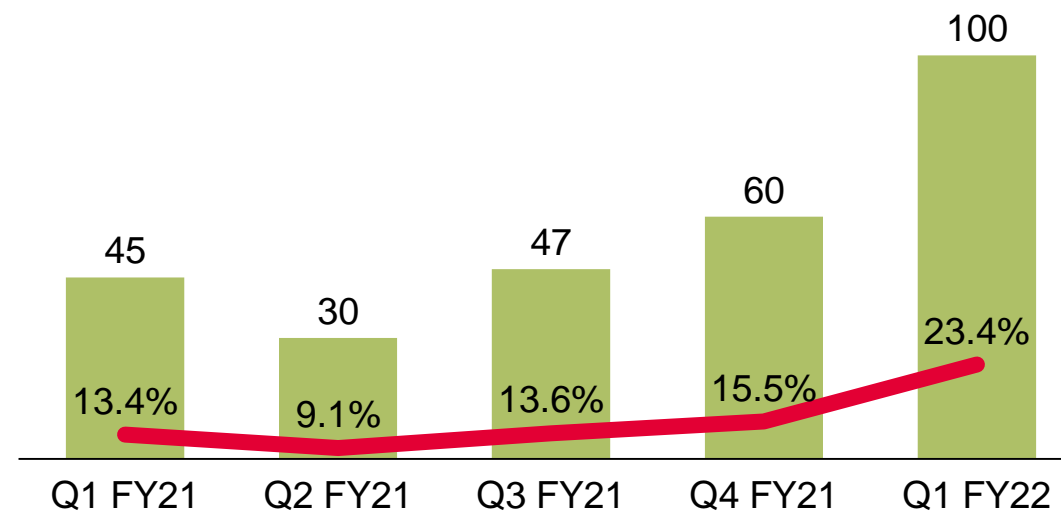
[EUR m]



Segment Result

Margin

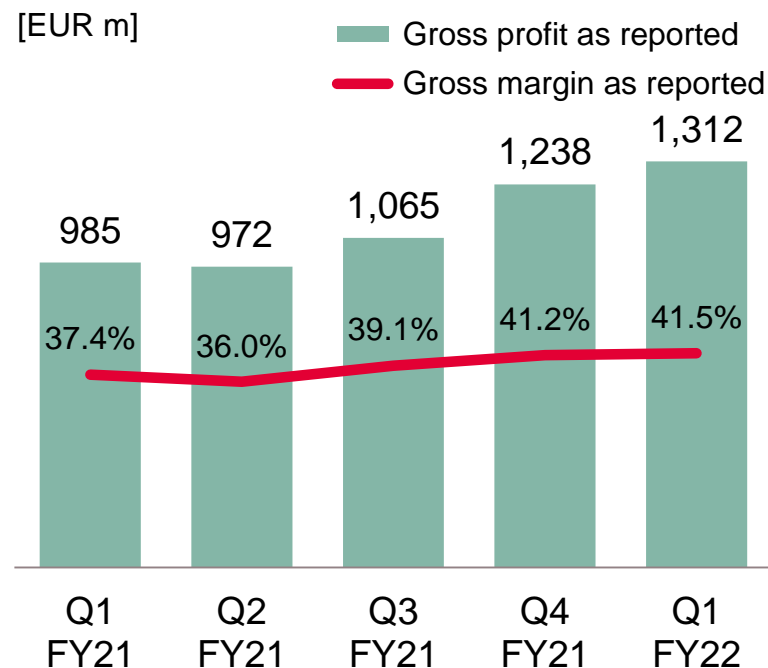
[EUR m]



- › Revenue and segment result improved due to favorable product and customer mix, the strengthening of the US-Dollar and some supply improvement for microcontrollers and Wi-Fi products
- › But: supply constraints continue to cap revenue potential
- › Demand for compute, connectivity, and security components remains strong, IoT innovation pipeline is well-filled

Gross margin and Opex

Gross profit



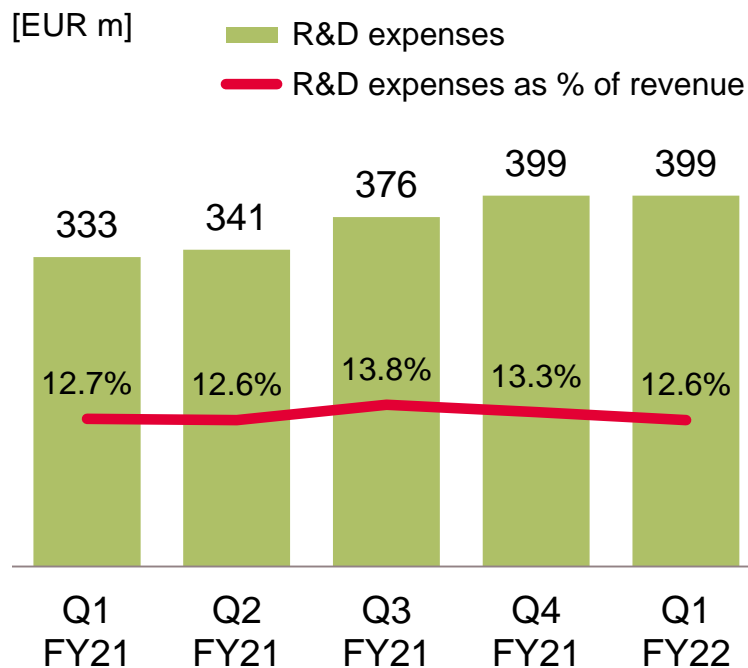
Therein non-segment result charges

[EUR m]				
75	89	74	83	76

Adjusted gross margin

40.3 %	39.3%	41.8%	43.9%	43.9%
--------	-------	-------	-------	-------

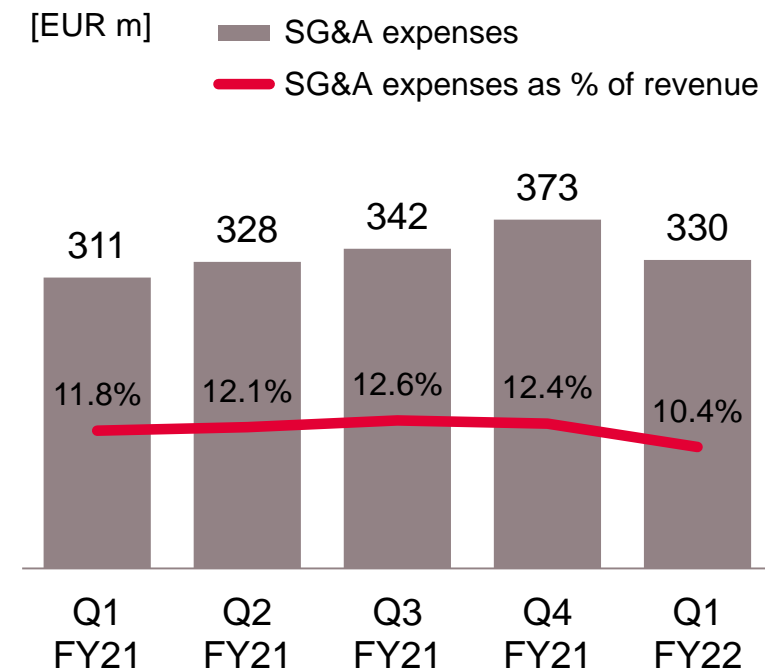
R&D



Therein non-segment result charges

[EUR m]				
8	4	6	6	6

SG&A

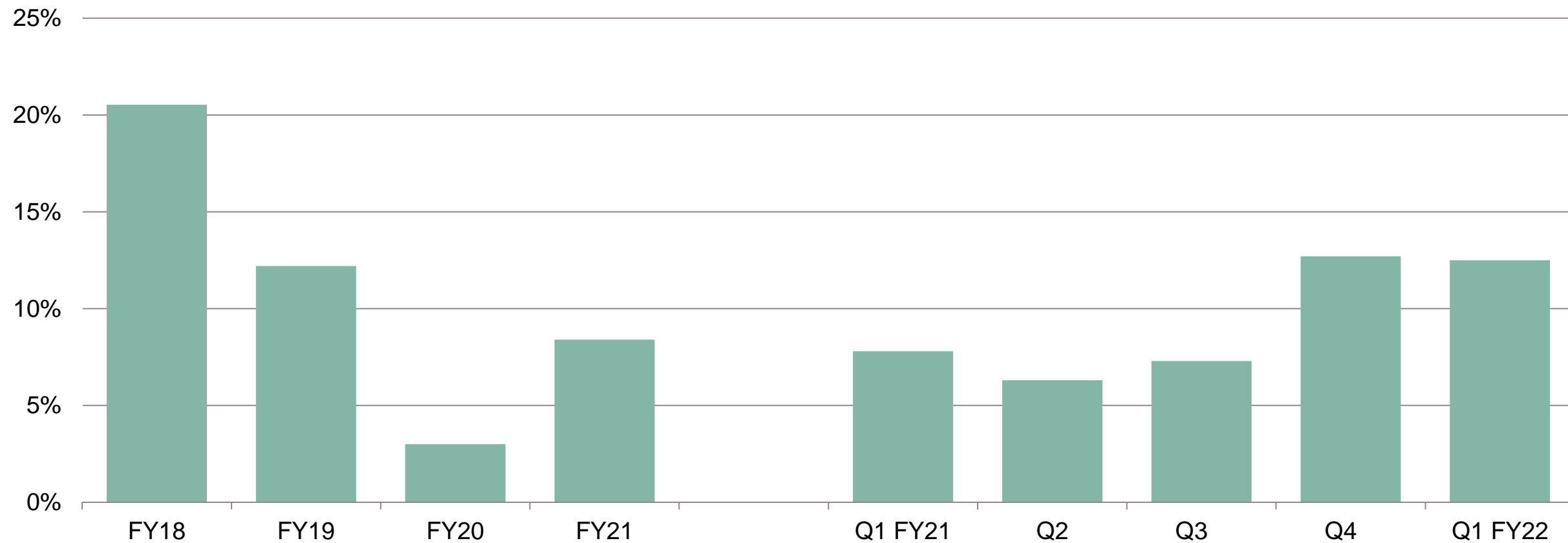


Therein non-segment result charges

[EUR m]				
60	58	60	57	47

Return on capital employed

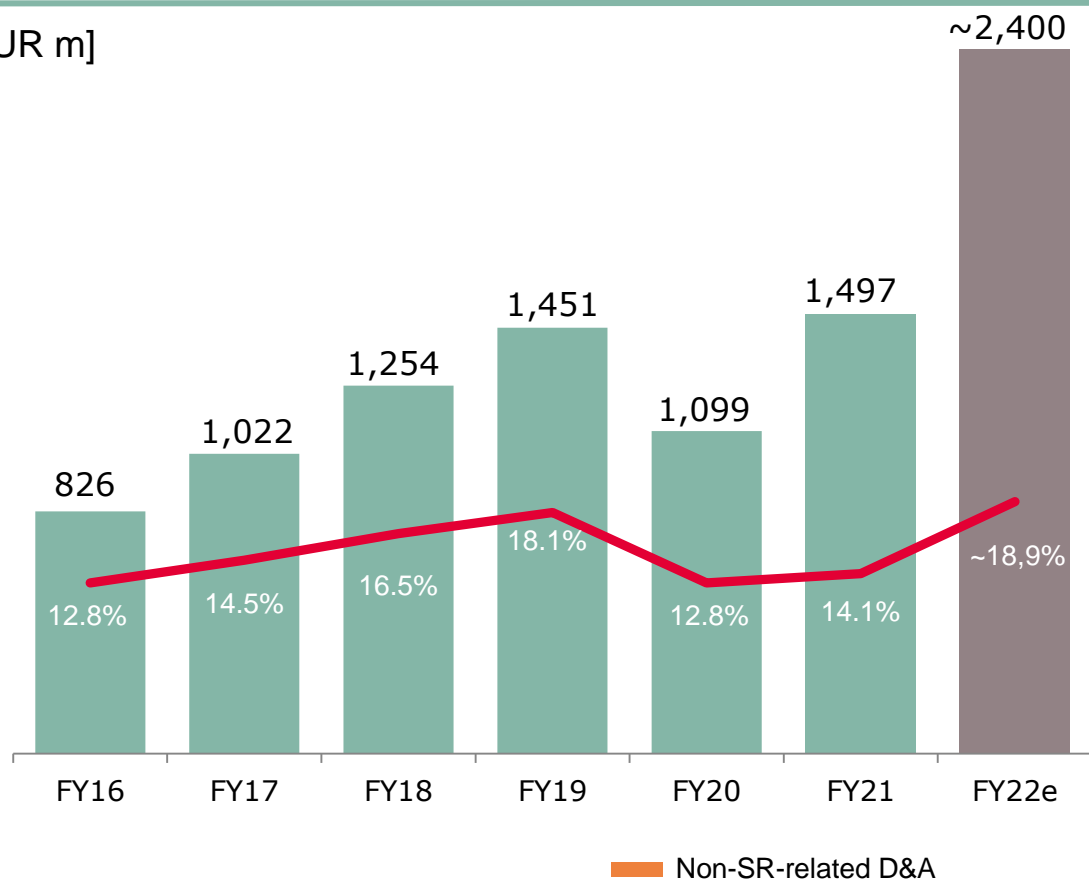
Historical development



D&A mainly impacted by Cypress PPA

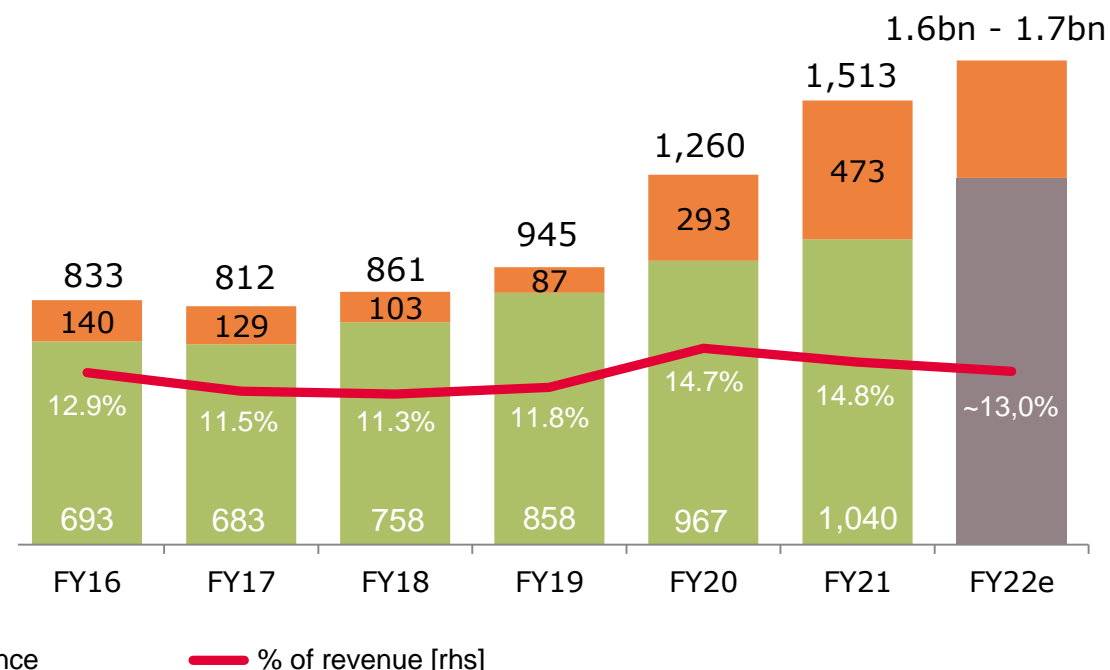
Investments*

[EUR m]



Depreciation & Amortization

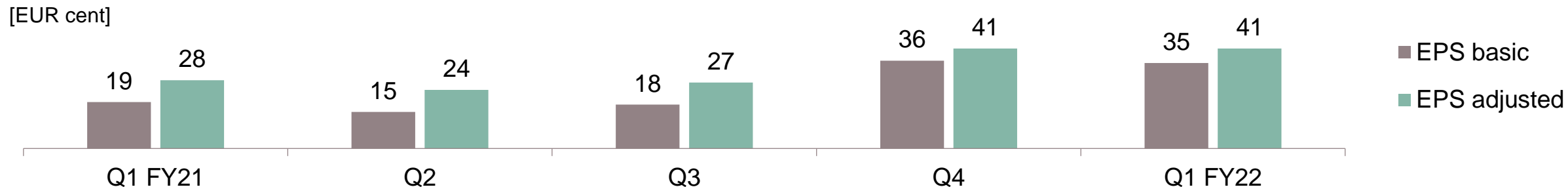
[EUR m]



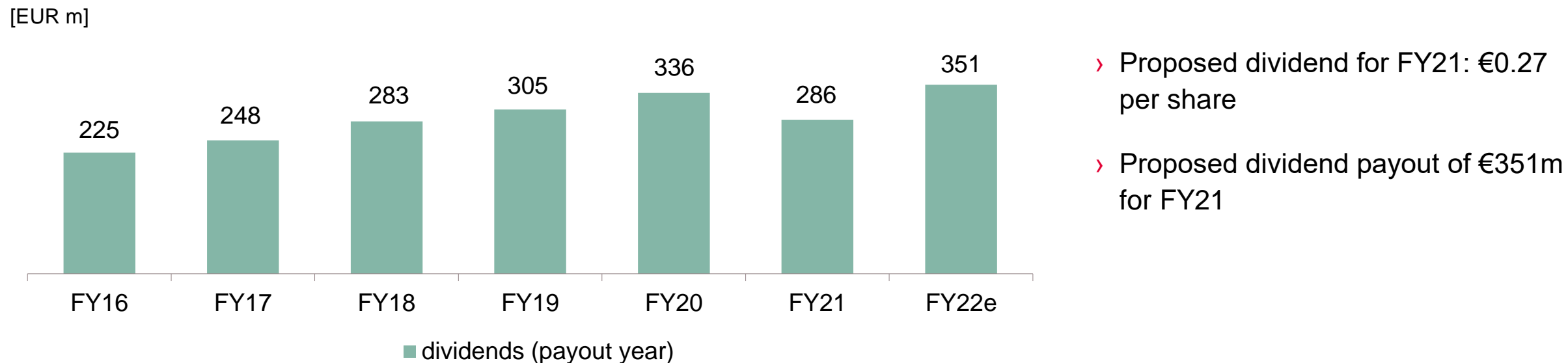
* For definition please see page "Notes".

Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations



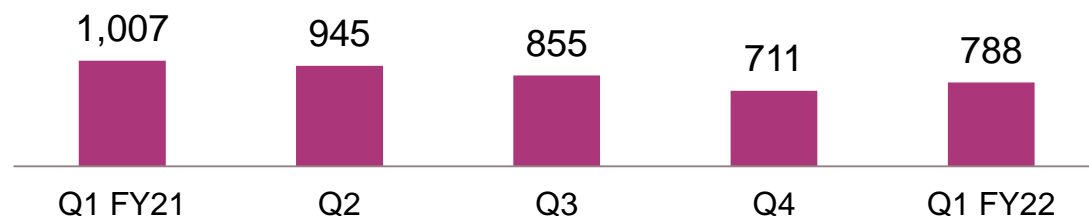
Total cash return to shareholders



Working Capital, in particular trade working capital components

Working capital¹

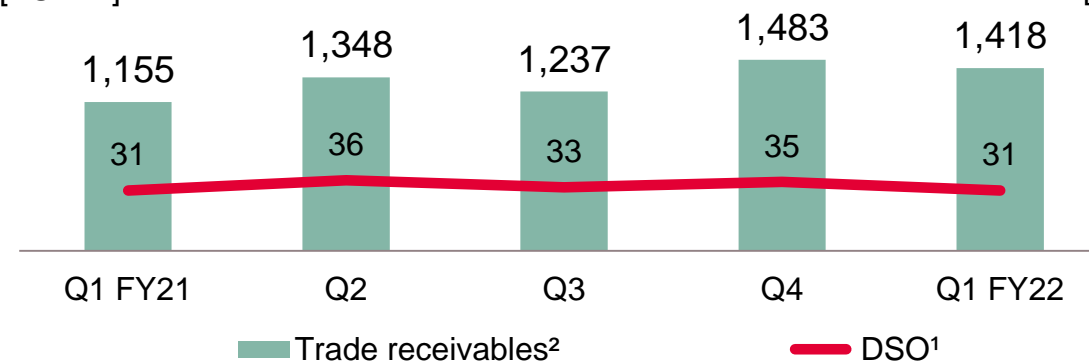
[EUR m]



Trade receivables

[EUR m]

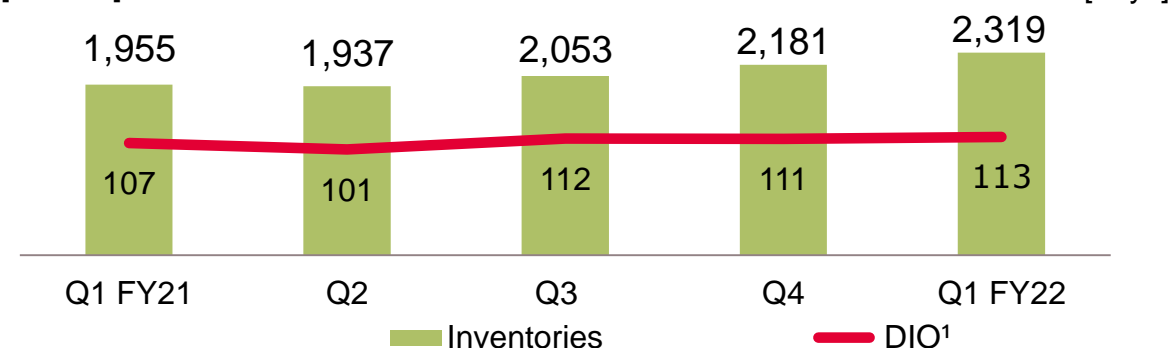
[days]



Inventories

[EUR m]

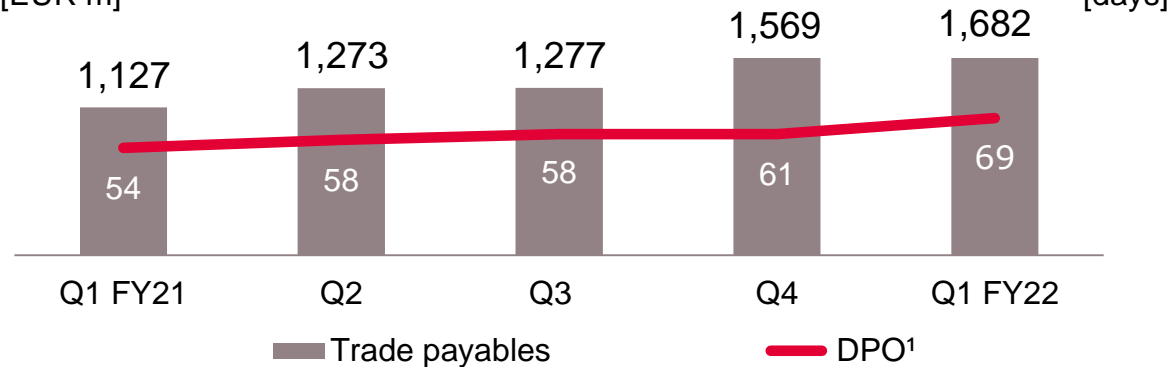
[days]



Trade payables

[EUR m]

[days]



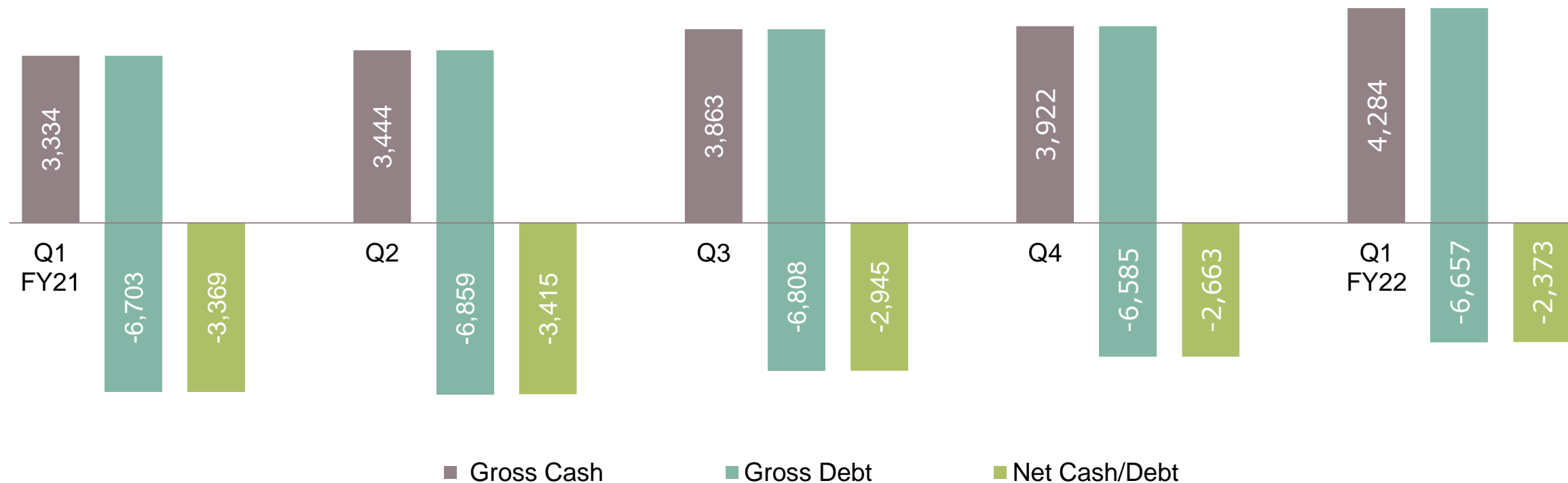
¹ For definition please see page "Notes"

² Along with the integration of Cypress refund liabilities to customers are presented under "other current liabilities" instead of "trade receivables". Prior quarters' figures were adjusted accordingly for better comparability.

Liquidity development

Historical liquidity development

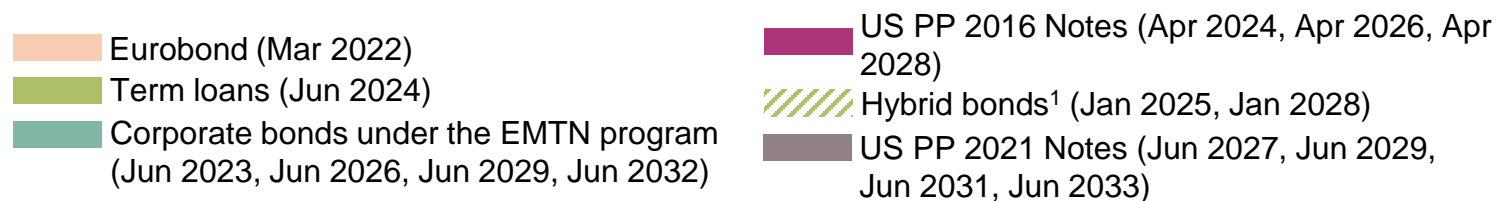
[EUR m]



Maturity profile

Maturity profile from 2022 to 2033

[EUR m; US\$ m; nominal values]



Graph excludes pre-existing Cypress convertibles of ~\$387m repayment value, repaid in January 2022, and additional debt with maturities between 2022 and 2023 totaling €4.5m.

¹ On 1 Oct 2019, Infineon issued a perpetual hybrid bond with two tranches: €600m with first call date in 2025 and €600m with first call date in 2028; both are accounted as equity under IFRS.

Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility

	Financial Policy Targets	Status Quo (LTM 31 December 2021)
Gross Cash ¹	€1bn + at least 10% of revenues → €2.2bn	€1bn + 28% of revenues → €4.3bn
Gross Debt ²	≤ 2.0x EBITDA	2.0x EBITDA
Comfortable liquidity position	<ul style="list-style-type: none">› Flexibility for financing operating activities and investments through the cycle› Cushion for net pension liabilities and contingent liabilities	
Balanced debt position	<ul style="list-style-type: none">› Gross debt target temporarily exceeded for CY acquisition, but still compatible to investment-grade rating› Public commitment to return to target level of ≤ 2.0x – achieved FY22 Q1, one year ahead of schedule, further deleveraging steps envisaged	
Rating	Investment grade	BBB stable outlook (by S&P Global)

¹ Gross cash position is defined as cash and cash equivalents plus financial investments | ² Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization



Part of your life. Part of tomorrow.

Glossary (1 of 2)

ABB	accelerated book building
ABS	anti-blocking system
AC	alternating current
AC-DC	alternating current - direct current
AD	automated driving
ADAS	advanced driver assistance system
AEB	automatic emergency braking
AFS	advanced frontlight system
AI	artificial intelligence
AR	augmented reality
ASP	average selling price
BEV	battery electric vehicle
BGA	ball grid array
BLE	Bluetooth® Low Energy
BMS	battery management system
BoM	bill of material
BT	Bluetooth®
CL	contactless
CPU	central processing unit
CRC	cyclical redundancy check
DC	direct current
DC-DC	direct current - direct current
DIF	dual-interface (contact-based and contactless)
DIY	do it yourself
DPM	digital power management
eCall	emergency call

ECC	error correction code
ECU	electronic control unit
EPS	electric power steering
eSIM	embedded subscriber identity module
ESS	energy storage system
EV	electric vehicle
FHEV	full hybrid electric vehicle
FPGA	field programmable gate array
G2M	go-to-market
GaN	gallium nitride
GPS	global positioning system
GPU	graphics processing unit
HEV	mild and full hybrid electric vehicle
HMI	human machine interaction
HSM	hardware security module
HST	high-speed train
HVAC	heating, ventilation, air conditioning
HW	hardware
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	Internet of Things
IPM	intelligent power module
IVN	in-vehicle networking
iPol	image processing line
IRF	International Rectifier

Glossary (2 of 2)

IVN	in-vehicle networking
LCD	liquid crystal display
LDO	low dropout voltage regulator
LED	light-emitting diode
LSEV	low-speed electric vehicle
LSPS	LS Power Semitech Co. Ltd.
μC	microcontroller
Mb	megabit
MCU	microcontroller unit
MEMS	micro electro-mechanical systems
MHA	major home appliances
MHEV	mild hybrid electric vehicle
MIMO	multiple input, multiple output
micro-hybrid	vehicles using start-stop systems and limited recuperation
mild-hybrid	vehicles using start-stop systems, recuperation, DC-DC conversion, e-motor
MOSFET	metal-oxide silicon field-effect transistor
MPU	microprocessor unit
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PAS	photo-acoustic spectroscopy
PFC	power factor correction
PHEV	plug-in hybrid electric vehicle
PMIC	power management IC
PoL	point-of-load
PSoC	programmable system-on-chip

PTC	positive temperature coefficient
PV	photovoltaic
RF	radio frequency
rhs	right-hand scale
Si	silicon
SiC	silicon carbide
SiGe	silicon germanium
SMD	surface mounted device
SMPS	switch-mode power supply
SNR	signal-to-noise ratio
SoC	system-on-chip
SOTA	software over-the-air
SPI	serial peripheral interface
SRAM	static random access memory
SW	software
TAM	total addressable market
TCO	total cost of ownership
ToF	time-of-flight
TPM	trusted platform module
UPS	uninterruptible power supply
USB	universal serial bus
V2X	vehicle-to-everything communication
VR	virtual reality
VSD	variable speed drive
Wi-Fi	wireless fidelity
WSC	World Semiconductor Council
xEV	all degrees of vehicle electrification (EV, HEV, PHEV)

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Disclaimer

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Financial calendar

Date	Event	Location
17 Feb 2022	Annual General Meeting	virtual
22 Feb 2022	Goldman Sachs Technology & Internet Conference	virtual
1 Mar 2022	dbAccess ESG Conference	virtual
8 Mar 2022	Morgan Stanley Tech Conference	San Francisco
9 Mar 2022	Bernstein Tech Tour 2022	virtual
17 Mar 2022	Kepler Cheuvreux One Stop Shop Conference	Madrid
24 Mar 2022	Citi EMEA TMT Conference	virtual
24 Mar 2022	J.P. Morgan Fireside Chat	virtual
31 Mar 2022	Stifel German Corporate Conference	Copenhagen
9 May 2022 ¹	Q2 FY22 Results	
11 May 2022	IPC Call along with PCIM trade show	
16 May 2022	Equita 17th European Conference	virtual
17 May 2022	J.P. Morgan European Technology, Media and Telecoms Conference	London
23 May 2022	J.P. Morgan Global Technology, Media and Communications Conference	Boston
24 May 2022	Berenberg Conference USA 2022	Tarrytown
21 Jun 2022	BofA TMT Conference	London
3 Aug 2022 ¹	Q3 FY22 Results	
15 Nov 2022 ¹	Q4 FY22 and FY 2022 Results	

¹ preliminary

Notes and ESG footnotes

Investments =	'Purchase of property, plant and equipment' + 'Purchase of intangible assets and other assets' incl. capitalization of R&D expenses
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale' – ('Total Current liabilities' – 'Short-term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')
RoCE =	Operating profit from continuing operations after tax / Capital Employed = ('Operating profit' – 'Financial result excluding interest result' – 'Share of profit (loss) of associates and joint ventures accounted for using the equity method' - 'Income tax') / Capital Employed
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investment' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term debt and current maturities of long-term debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories' / 'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables' / ['Cost of goods sold' + 'Purchase of property, plant and equipment']) x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables' - 'reimbursement obligations')* / 'revenue' x 90 *without debtors with credit balances
Order backlog =	The total amount of orders received regardless of their current status

ESG footnotes:

- 1) This figure takes into account manufacturing, transportation, own vehicles, travel, raw materials and consumables, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. as well as direct and indirect energy-related emissions by manufacturing service providers. It is based on data collected internally and publicly available conversion factors and relates to the 2021 fiscal year.
- 2) This figure is based on internally established criteria, which are described in the explanatory notes. The figure relates to the 2020 calendar year and takes into account the following application areas: automotive, LED, induction cookers, servers, renewable energy (wind, photovoltaic) and cell phone chargers as well as drives. CO2 savings are calculated based on the potential savings generated by technologies in which semiconductors are used. The CO2 savings are allocated based on Infineon's market share, semiconductor share, and the lifetime of the technologies concerned, based on internal and external experts' estimations. Despite the fact that carbon footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.

For further reading

CMD 2021
5 October 2021



<https://www.infineon.com/2021cmd>

IPC Business Update Call
Dr. Peter Wawer
6 May 2021



<https://www.infineon.com/2021ipccall>

ATV Business Update Call
Peter Schiefer
5 October 2020



<https://www.infineon.com/2020atvcall>

CSS Business Update Call
Thomas Rosteck
3 March 2021



<https://www.infineon.com/2021csscall>

PSS Business Update Call
Andreas Urschitz
1 July 2021



<https://www.infineon.com/2021psscall>

Annual Report 2021
<https://www.infineon.com/2021annualreport>



Sustainability Report 2021
<https://www.infineon.com/2021sustainabilityreport>

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